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Low-Power, Stereo Audio Codec with FlexSound Technology

MAX98089

General Description

The MAX98089 is a full-featured audio codec whose high performance and low power consumption make it ideal for portable applications.

Class D speaker amplifiers provide efficient amplification for two speakers. Low radiated emissions enable completely filterless operation. Integrated bypass switches optionally connect an external amplifier to the transducer when the Class D amplifiers are disabled.

The IC features a stereo Class H headphone amplifier that utilizes a dual-mode charge pump to maximize efficiency while outputting a ground referenced signal that does not require output coupling capacitors.

The IC also features a mono differential amplifier that can also be configured as a stereo line output.

Two differential analog microphone inputs are available as well as support for two PDM digital microphones. Integrated switches allow for an additional microphone input as well as microphone signals to be routed out to external devices. Two flexible single-ended or differential line inputs may be connected to an FM radio or other sources.

Integrated FlexSound™ technology improves loudspeaker performance by optimizing the signal level and frequency response while limiting the maximum distortion and power at the output to prevent speaker damage. Automatic gain control (AGC) and a noise gate optimize the signal level of microphone input signals to make best use of the ADC dynamic range.

The device is fully specified over the -40°C to +85°C extended temperature range.

Features

- 5.6mW Power Comsumption (DAC to HP at 97dB DR)
- 101dB DR Stereo DAC (8kHz < f_S < 96kHz)
- 93dB DR Stereo ADC (8kHz < f_S < 96kHz)
- Stereo Low EMI Class D Amplifiers
  - 1.7W/Channel (8Ω, V_{SPK_VDD} = 5.0V)
  - 2.9W/Channel (4Ω, V_{SPK_VDD} = 5.0V)
- Efficient Class H Headphone Amplifier
- Differential Receiver Amplifier/Stereo Line Outputs
- 2 Stereo Single-Ended/Mono Differential Line Inputs
- 3 Differential Microphone Inputs
- FlexSound Technology
  - 5-Band Parametric EQ
  - Automatic Level Control (ALC)
  - Excursion Limiter
  - Speaker Power Limiter
  - Speaker Distortion Limiter
  - Microphone Automatic Gain Control and Noise Gate
- Dual I^{2}S/PCM/TDM Digital Audio Interfaces
- Asynchronous Digital Mixing
- Supports Master Clock Frequencies from 10MHz to 60MHz
- RF Immune Analog Inputs and Outputs
- Extensive Click-and-Pop Reduction Circuitry
- Available in 63-Bump WLP Package (3.80mm x 3.30mm, 0.4mm Pitch) and 56-Pin TQFN Package (7mm x 7mm x 0.75mm)

***Ordering Information* appears at end of data sheet.**

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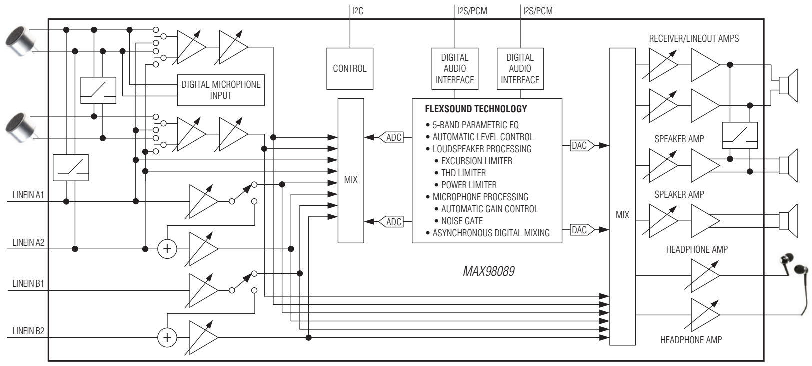
Simplified Block Diagram



19-5865; Rev 5; 5/25

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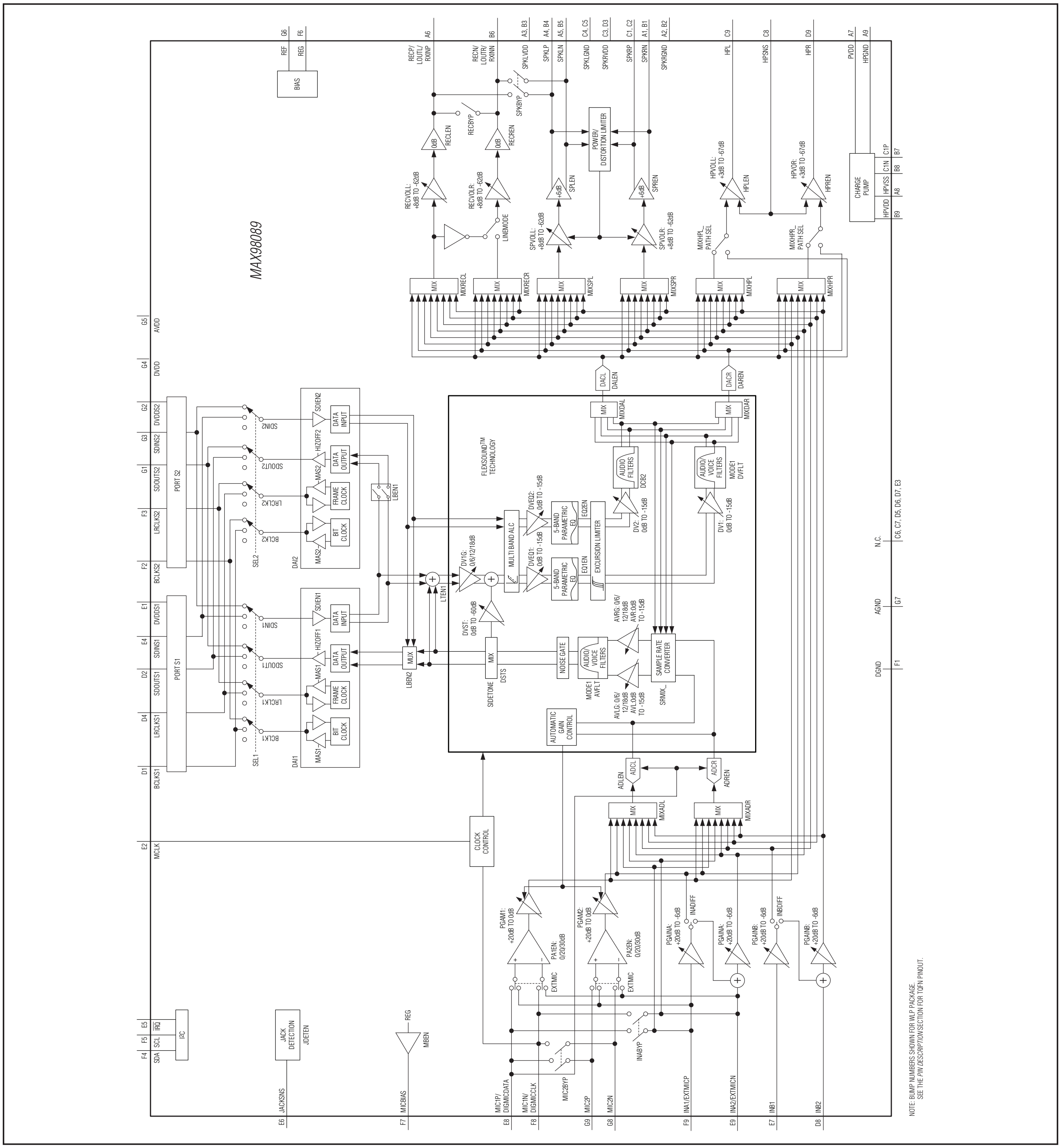
Functional Diagram



NOTE: BUMP NUMBERS SHOWN FOR WLP PACKAGE.
SEE THE *PIN DESCRIPTION* SECTION FOR TQFN PINOUT.

ABSOLUTE MAXIMUM RATINGS

(Voltages with respect to AGND.)
DVDD, AVDD, PVDD, HPVDD ....-0.3V to +2.2V
SPKLVDD, SPKRVDD, DVDDS1, DVDDS2 ....-0.3V to +6.0V
DGND, HPGND, SPKLGND, SPKRGND............-0.1V to +0.1V
HPVSS ....(V_{HPGND} - 2.2V) to (V_{HPGND} + 0.3V)
C1N ....(V_{HPVSS} - 0.3V) to (V_{HPGND} + 0.3V)
C1P................................. (V_{HPGND} - 0.3V) to (V_{HPVDD} + 0.3V)
REF, MICBIAS ....-0.3V to ($V_{SPKLVDD}$ + 0.3V)
MCLK, SDINS1, SDINS2, JACKSNS,
SDA, SCL, $\overline{IRQ}$..-0.3V to +6.0V
LRCLKS1, BCLKS1, SDOUTS1.......-0.3V to (V_{DVDDS1} + 0.3V)
LRCLKS2, BCLKS2, SDOUTS2.......-0.3V to (V_{DVDDS2} + 0.3V)
REG, INA1/EXTMICP, INA2/EXTMICN, INB1, INB2,
MIC1P/DIGMICDATA, MIC1N/DIGMICCLK,
MIC2P, MIC2N ....-0.3V to +2.2V
HPSNS ....(V_{HPGND} - 0.3V) to (V_{HPGND} + 0.3V)
HPL, HPR........................(V_{HPVSS} - 0.3V) to (V_{HPVDD} + 0.3V)
RECP/LOUTL/RXINP, RECP/LOUTR/
RXINN..................($V_{SPKLGND}$ - 0.3V) to ($V_{SPKLVDD}$ + 0.3V)
SPKLP, SPKLN ....($V_{SPKLGND}$ - 0.3V) to ($V_{SPKLVDD}$ + 0.3V)
SPKRP, SPKRN ......($V_{SPKRGND}$ - 0.3V) to ($V_{SPKRVDD}$ + 0.3V)
Continuous Power Dissipation (T_A = +70°C)
63-Bump WLP (derate 25.6mW/°C above +70°C)........2.05W
56-Pin TQFN (derate 40mW/°C above +70°C)...............3.2W
Operating Temperature Range.......................... -40°C to +85°C
Storage Temperature Range........................... -65°C to +150°C
Lead Temperature (TQFN only, soldering, 10s).............+300°C
Soldering Temperature (reflow).....................................+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
POWER SUPPLY							
Supply Voltage Range		Guaranteed by PSRR	$V_{SPKLVDD}$, $V_{SPKRVDD}$	2.8		5.5	V
			V_{DVDD}, V_{AVDD}, V_{PVDD}	1.65	1.8	2	
			V_{DVDDS1}, V_{DVDDS2}	1.65		3.6	
Total Supply Current (Notes 2 and 3)	I_{VDD}	Full-duplex 8kHz mono, receiver output, MAS = 1	Analog		4.5	8	mA
			Speaker		1.6	2.3	
			Digital		1.3	2	
		DAC playback 48kHz stereo, headphone outputs, MAS = 1	Analog		1.9	3	
			Speaker		0.001	0.0058	
			Digital		2.47	3.5	
		DAC playback 48kHz stereo, speaker outputs, MAS = 1	Analog		3.6	6.5	
			Speaker		6.41	8.5	
			Digital		2.49	3.5	
Shutdown Supply Current (Note 2)		T_A = +25°C	Analog		0.2	2	µA
			Speaker		0.01	1	
			Digital		1	5	
REF Voltage					2.5		V
REG Voltage					0.79		V
Shutdown to Full Operation		$\overline{VSEN}$ = 0			30		ms
		$\overline{VSEN}$ = 1			17		

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
MICROPHONE TO ADC PATH							
Dynamic Range	DR	f_S = 8kHz, MODE = 0 (IIR voice), $AV_{MICPRE\_}$ = 0dB (Note 4)			88		dB
Total Harmonic Distortion + Noise	THD+N	V_{IN} = 0.1V_{P-P}, f_S = 8kHz, f = 1kHz			-78		dB
		$AV_{MICPRE\_}$ = 0dB, V_{IN} = 1V_{P-P}, f = 1kHz			-85		
		$AV_{MICPRE\_}$ = +30dB, V_{IN} = 32mV_{P-P}, f = 1kHz			-71		
Common-Mode Rejection Ratio	CMRR	V_{IN} = 100mV_{P-P}, f = 217Hz			74		dB
Power-Supply Rejection Ratio	PSRR	V_{AVDD} = 1.65V to 1.95V, input referred, MIC inputs unconnected		50	62		dB
		f = 217Hz, V_{RIPPLE} = 200mV_{P-P}, input referred			62		
		f = 1kHz, V_{RIPPLE} = 200mV_{P-P}, input referred			62		
		f = 10kHz, V_{RIPPLE} = 200mV_{P-P}, input referred			55		
Path Phase Delay		1kHz, 0dB input, highpass filter disabled measured from analog input to digital output	MODE = 0 (IIR voice) 8kHz		2.2		ms
			MODE = 0 (IIR voice) 16kHz		1.1		
			MODE = 1 (FIR audio) 8kHz		4.5		
			MODE = 1 (FIR audio) 48kHz		0.76		
MICROPHONE PREAMP							
Full-Scale Input		$AV_{MICPRE\_}$ = 0dB			1.05		V_{P-P}
Preamplifier Gain	$AV_{MICPRE\_}$	(Note 5)	PA1EN/PA2EN = 01		0		dB
			PA1EN/PA2EN = 10	19.5	20	20.5	
			PA1EN/PA2EN = 11	29.5	30	30.5	
PGA Gain	$AV_{MICPGA\_}$	(Note 5)	PGAM1/PGAM2 = 0x00	19	20	21	dB
			PGAM1/PGAM2 = 0x14		0		
MIC Input Resistance	R_{IN_MIC}	All gain settings, measured at MIC1P/MIC1N/MIC2P/MIC2N			50		kΩ

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MICROPHONE BIAS						
MICBIAS Output Voltage	$V_{MICBIAS}$	I_{LOAD} = 1mA	2.15	2.2	2.25	V
Load Regulation		I_{LOAD} = 1mA to 2mA		0.5	4.5	mV
Line Regulation		$V_{SPKLVDD}$ = 2.8V to 5.5V		110		µV
Ripple Rejection		f = 217Hz, $V_{RIPPLE\ (SPKLVDD)}$ = 100m$V_{P\text{-}P}$		92		dB
		f = 10kHz, $V_{RIPPLE\ (SPKLVDD)}$ = 100m$V_{P\text{-}P}$		83		
Noise Voltage		A-weighted, f = 20Hz to 20kHz		3.9		µV_{RMS}
		P-weighted, f = 20Hz to 4kHz		2.1		
		f = 1kHz		50		nV/√Hz
MICROPHONE BYPASS SWITCH						
On-Resistance	R_{ON}	$I_{MIC1\_}$ = 100mA, INABYP = MIC2BYP = 1, $V_{MIC2\_}$ = $V_{INA\_}$ = 0V, AVDD, T_A = +25°C		5	30	Ω
Total Harmonic Distortion + Noise	THD+N	V_{IN} = 2$V_{P\text{-}P}$, V_{CM} = 0.9V, R_L = 10kΩ, f = 1kHz, INABYP = MIC2BYP = 1		-80		dB
Off-Isolation		V_{IN} = 2$V_{P\text{-}P}$, V_{CM} = 0.9V, R_L = 10kΩ, f = 1kHz		60		dB
Off-Leakage Current		$V_{MIC1\_}$ = [0V, AVDD], $V_{MIC2\_}$/$V_{INA\_}$ = [AVDD, 0V]	-1		+1	µA
LINE INPUT TO ADC PATH						
Dynamic Range (Note 4)	DR	INA pin direct, f_S = 48kHz, MODE = 1 (FIR audio)		93		dB
Total Harmonic Distortion + Noise	THD+N	V_{IN} = 1$V_{P\text{-}P}$, f = 1kHz		-82	-74	dB
Gain Error		DC accuracy		1		%
Power-Supply Rejection Ratio	PSRR	V_{AVDD} = 1.65V to 1.95V, input referred, line inputs unconnected, T_A = +25°C	57	68		dB
		f = 217Hz, V_{RIPPLE} = 200m$V_{P\text{-}P}$, AV_{ADC} = 0dB, input referred		63		
		f = 1kHz, V_{RIPPLE} = 200m$V_{P\text{-}P}$, AV_{ADC} = 0dB, input referred		63		
		f = 10kHz, V_{RIPPLE} = 200m$V_{P\text{-}P}$, AV_{ADC} = 0dB, input referred		57		

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2μF, $C_{MICBIAS}$ = C_{REG} = 1μF, $C_{C1N-C1P}$ = 1μF, C_{HPVDD} = C_{HPVSS} = 1μF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
LINE INPUT PREAMP							
Full-Scale Input	V_{IN}	$AV_{PGAIN\_}$ = 0dB			1		V_{P-P}
		$AV_{PGAIN\_}$ = -6dB			1.4		
Level Adjust Gain	$AV_{PGAIN\_}$	T_A = +25°C (Note 5)	PGAINA/PGAINB = 0x0	19	20	21	dB
			PGAINA/PGAINB = 0x1	13	14	15	
			PGAINA/PGAINB = 0x2	2	3	4	
			PGAINA/PGAINB = 0x3		0		
			PGAINA/PGAINB = 0x4	-4	-3	-2	
			PGAINA/PGAINB = 0x5, 0x6, 0x7	-7	-6	-5	
Input Resistance	R_{IN}	$AV_{PGAIN\_}$ = +20dB		14.5	21	28	kΩ
		$AV_{PGAIN\_}$ = +14dB			20		
		$AV_{PGAIN\_}$ = +3dB			20		
		$AV_{PGAIN\_}$ = 0dB		7.5	10	14	
		$AV_{PGAIN\_}$ = -3dB			20		
		$AV_{PGAIN\_}$ = -6dB			20		
Feedback Resistance	R_{IN_FB}	INAEXT/INBEXT = 1	T_A = +25°C	18	20	22	kΩ
			T_A = T_{MIN} to T_{MAX}	16		24	
ADC LEVEL CONTROL							
ADC Level Adjust Range	AV_{ADCLVL}	AVL/AVR = 0xF to 0x0 (Note 5)		-12		+3	dB
ADC Level Step Size					1		dB
ADC Gain Adjust Range	$AV_{ADCGAIN}$	AVLG/AVRG = 00 to 11 (Note 5)		0		18	dB
ADC Gain Adjust Step Size					6		dB
ADC DIGITAL FILTERS							
VOICE MODE IIR LOWPASS FILTER (MODE1 = 0)							
Passband Cutoff	f_{PLP}	Ripple limit cutoff		0.441 x fs			Hz
		-3dB cutoff		0.449 x fs			
Passband Ripple		f < f_{PLP}		-0.1		+0.1	dB
Stopband Cutoff	f_{SLP}					0.47 x f_S	Hz
Stopband Attenuation (Note 6)		f > f_{SLP}		74			dB

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
VOICE MODE IIR HIGHPASS FILTER (MODE1 = 0)						
Passband Cutoff (-3dB from Peak)	f_{AHPPB}	AVFLT = 0x1 (Elliptical tuned for f_S = 16kHz + 217Hz notch)			0.0161 x f_S	Hz
		AVFLT = 0x2 (500Hz Butterworth tuned for f_S = 16kHz)			0.0319 x f_S	
		AVFLT = 0x3 (Elliptical tuned for f_S = 8kHz + 217Hz notch)			0.0321 x f_S	
		AVFLT = 0x4 (500Hz Butterworth tuned for f_S = 8kHz)			0.0632 x f_S	
		AVFLT = 0x5 (f_S/240 Butterworth)			0.0043 x f_S	
Stopband Cutoff (-30dB from Peak)	f_{AHPSB}	AVFLT = 0x1 (Elliptical tuned for f_S = 16kHz + 217Hz notch)	0.0139 x f_S			Hz
		AVFLT = 0x2 (500Hz Butterworth tuned for f_S = 16kHz)	0.0156 x f_S			
		AVFLT = 0x3 (Elliptical tuned for f_S = 8kHz + 217Hz notch)	0.0279 x f_S			
		AVFLT = 0x4 (500Hz Butterworth tuned for f_S = 8kHz)	0.0312 x f_S			
		AVFLT = 0x5 (f_S/240 Butterworth)	0.0018 x f_S			
DC Attenuation	DC_{ATTEN}	AVFLT ≠ 000		90		dB
STEREO AUDIO MODE FIR LOWPASS FILTER (MODE1 = 1, DHF1 = 0, LRCLK < 50kHz)						
Passband Cutoff	f_{PLP}	Ripple limit cutoff	0.43 x f_S			Hz
		-3dB cutoff	0.48 x f_S			
		-6.02dB cutoff	0.5 x f_S			
Passband Ripple		f < f_{PLP}	-0.1		+0.1	dB
Stopband Cutoff	f_{SLP}				0.58 x f_S	Hz
Stopband Attenuation (Note 6)		f < f_{SLP}	60			dB
ADC STEREO AUDIO MODE FIR LOWPASS FILTER (MODE1 = 1, DHF1 = 1, LRCLK > 50kHz)						
Passband Cutoff	f_{PLP}	Ripple limit cutoff	0.208 x f_S			Hz
		-3dB cutoff	0.28 x f_S			
Passband Ripple		f < f_{PLP}	-0.1		+0.1	dB
Stopband Cutoff	f_{SLP}				0.417 x f_S	Hz
Stopband Attenuation		f < f_{SLP}	60			dB

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2μF, $C_{MICBIAS}$ = C_{REG} = 1μF, $C_{C1N-C1P}$ = 1μF, C_{HPVDD} = C_{HPVSS} = 1μF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
STEREO AUDIO MODE DC BLOCKING HIGHPASS FILTER (MODE1 = 1)						
Passband Cutoff (-3dB from Peak)	f_{AHPPB}	AVFLT ≠ 000			0.000125 x f_S	Hz
DC Attenuation	DC_{Atten}	AVFLT ≠ 000		90		dB
MICROPHONE AUTOMATIC GAIN CONTROL						
AGC Hold Duration		AGCHLD = 01		50		ms
		AGCHLD = 11		400		
AGC Attack Time		AGCATK = 00		2		ms
		AGCATK = 11		123		
AGC Release Time		AGCRLS = 000		0.078		s
		AGCRLS = 111		10		
AGC Threshold Level		AGCTH = 0x0 to 0xF	-3		+18	dB
AGC Threshold Step Size				1		dB
AGC Gain		(Note 5)	0		20	dB
ADC NOISE GATE						
NG Threshold Level		ANTH = 0x3 to 0xF, referred to 0dBFS	-64		-16	dB
NG Attenuation		(Note 5)	0		12	dB
ADC-TO-DAC DIGITAL SIDETONE (MODE = 0)						
Sidetone Gain Adjust Range	AV_{STGA}	DVST = 0x01		-0.5		dB
		DVST = 0x1F		-60.5		
Sidetone Gain Adjust Step Size				2		dB
Sidetone Path Phase Delay		1kHz, 0dB input, highpass filter disabled 8kHz		2.2		ms
		16kHz		1.1		
ADC-TO-DAC DIGITAL LOOP-THROUGH PATH						
Dynamic Range (Note 4)	DR	f_S = 48kHz, MCLK = 12.288MHz, MODE = 1 (FIR audio), MIC to HP output, T_A = +25°C	83	93		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, f_S = 48kHz, MCLK = 12.288MHz, MODE = 1 (FIR audio), MIC to HP output		81		dB
DAC LEVEL CONTROL						
DAC Attenuation Range	$AV_{DACATTN}$	DV_ = 0xF to 0x0 (Note 5)	-15		0	dB
DAC Attenuation Step Size				1		dB
DAC Gain Adjust Range	$AV_{DACGAIN}$	DV1G = 00 to 11 (Note 5)	0		18	dB
DAC Gain Adjust Step Size				6		dB

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DAC DIGITAL FILTERS						
VOICE MODE IIR LOWPASS FILTER (MODE1 = 0)						
Passband Cutoff	f_{PLP}	Ripple limit cutoff	0.448 x f_S			Hz
		-3dB cutoff	0.451 x f_S			
Passband Ripple		f < f_{PLP}	-0.1		+0.1	dB
Stopband Cutoff	f_{SLP}				0.476 x f_S	Hz
Stopband Attenuation (Note 6)		f > f_{SLP}	75			dB
VOICE MODE IIR HIGHPASS FILTER (MODE1 = 0)						
Passband Cutoff (-3dB from Peak)	f_{DHPPB}	DVFLT = 0x1 (Elliptical tuned for f_S = 16kHz + 217Hz notch)			0.0161 x f_S	Hz
		DVFLT = 0x2 (500Hz Butterworth tuned for f_S = 16kHz)			0.0312 x f_S	
		DVFLT = 0x3 (Elliptical tuned for f_S = 8kHz + 217Hz notch)			0.0321 x f_S	
		DVFLT = 0x4 (500Hz Butterworth tuned for f_S = 8kHz)			0.0625 x f_S	
		DVFLT = 0x5 (fs/240 Butterworth)			0.0042 x f_S	
Stopband Cutoff (-30dB from Peak)	f_{DHPSB}	DVFLT = 0x1 (Elliptical tuned for f_S = 16kHz + 217Hz notch)	0.0139 x f_S			Hz
		DVFLT = 0x2 (500Hz Butterworth tuned for f_S = 16kHz)	0.0156 x f_S			
		DVFLT = 0x3 (Elliptical tuned for f_S = 8kHz + 217Hz notch)	0.0279 x f_S			
		DVFLT = 0x4 (500Hz Butterworth tuned for f_S = 8kHz)	0.0312 x f_S			
		DVFLT = 0x5 (f_S/240 Butterworth)	0.0021 x f_S			
DC Attenuation	DC_{ATTEN}	DVFLT ≠ 000		85		dB
STEREO AUDIO MODE FIR LOWPASS FILTER (MODE1 = 1, DHF1/DHF2 = 0, LRCLK < 50kHz)						
Passband Cutoff	f_{PLP}	Ripple limit cutoff	0.43 x f_S			Hz
		-3dB cutoff	0.47 x f_S			
		-6.02dB cutoff	0.5 x f_S			
Passband Ripple		f < f_{PLP}	-0.1		+0.1	dB
Stopband Cutoff	f_{SLP}				0.58 x f_S	Hz
Stopband Attenuation (Note 6)		f > f_{SLP}	60			dB

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
STEREO AUDIO MODE FIR LOWPASS FILTER (MODE1 = 1, DHF1/DHF2 = 1 for LRCLK > 50kHz)						
Passband Cutoff	f_{PLP}	Ripple limit cutoff	0.24 x f_S			Hz
		-3dB cutoff	0.31 x f_S			
Passband Ripple		f < f_{PLP}	-0.1		+0.1	dB
Stopband Cutoff	f_{SLP}				0.477 x f_S	Hz
Stopband Attenuation (Note 6)		f < f_{SLP}	60			dB
STEREO AUDIO MODE DC BLOCKING HIGHPASS FILTER						
Passband Cutoff (-3dB from Peak)	f_{DHPPB}	DVFLT ≠ 000 (DAI1), DCB2 = 1 (DAI2)			0.000104 x f_S	Hz
DC Attenuation	DC_{ATTEN}	DVFLT ≠ 000 (DAI1), DCB2 = 1 (DAI2)		90		dB
AUTOMATIC LEVEL CONTROL						
Dual Band Lowpass Corner Frequency		ALCMB = 1		5		kHz
Dual Band Highpass Corner Frequency		ALCMB = 1		5		kHz
Gain Range			0		12	dB
Low-Signal Threshold		ALCTH = 111 to 001	-48		-12	dBFS
Release Time		ALCRLS = 101		0.25		s
		ALCRLS = 000		8		
PARAMETRIC EQUALIZER						
Number of Bands				5		Bands
Per Band Gain Range			-12		+12	dB
Preattenuator Gain Range		(Note 5)	-15		0	dB
Preattenuator Step Size				1		dB
DAC TO RECEIVER AMPLIFIER PATH						
Dynamic Range	DR	f_S = 48kHz, f = 1kHz (Note 4)		96		dB
Output Offset Voltage	V_{OS}	$AV_{REC\_}$ = -62dB, T_A = +25°C, WLP package only		±0.5	±4	mV
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, P_{OUT} = 15mW, R_{REC} = 32Ω		-70	-63	dB
Power-Supply Rejection Ratio	PSRR	$V_{SPKLVDD}$ = 2.8V to 5.5V, T_A = +25°C	64	75		dB
		f = 217Hz, V_{RIPPLE} = 200m$V_{P\text{-}P}$		80		
		f = 1kHz, V_{RIPPLE} = 200m$V_{P\text{-}P}$		80		
		f = 10kHz, V_{RIPPLE} = 200m$V_{P\text{-}P}$		77		

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Click-and-Pop Level	K_{CP}	Peak voltage, A-weighted, 32 samples per second, AV_{REC} = 0dB	Into shutdown		-68		dBV
			Out of shutdown		-72		
LINE INPUT TO RECEIVER AMPLIFIER PATH							
Dynamic Range (Note 4)	DR	Referenced to full-scale output level			94		dB
Total Harmonic Distortion + Noise	THD+N				-64		dB
Click-and-Pop Level	K_{CP}	Peak voltage, A-weighted, 32 samples per second, AV_{REC} = 0dB	Into shutdown		-51		dBV
			Out of shutdown		-49		
RECEIVER AMPLIFIER							
Output Power	P_{OUT}	R_{REC} = 32Ω, f = 1kHz, THD = 1%			92		mW
Full-Scale Output		(Note 7)			1		V_{RMS}
Volume Control (Note 5)	AV_{REC}	RECVOL = 0x00			-62		dB
		RECVOL = 0x1F			8		
Volume Control Step Size		+8dB to +6dB			0.5		dB
		+6dB to +0dB			1		
		0dB to -14dB			2		
		-14dB to -38dB			3		
		-38dB to -62dB			4		
Mute Attenuation		f = 1kHz			88		dB
Capacitive Drive Capability		No sustained oscillations	R_{REC} = 32Ω		500		pF
			R_{REC} = ∞		100		
DAC TO LINE OUT AMPLIFIER PATH							
Dynamic Range (Note 4)	DR	f_S = 48kHz, f = 1kHz		83	96		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, R_L = 1kΩ			-78	-72	dB
LINE INPUT TO LINE OUT AMPLIFIER PATH							
Dynamic Range (Note 4)	DR	Referenced to full-scale output level			92		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, R_L = 10kΩ			76		dB
Full-Scale Output		(Note 7)			2		$V_{P\text{-}P}$
Mute Attenuation		f = 1kHz			85		dB
Output Offset Voltage	V_{OS}	AV_{REC} = -62dB, TQFN package only			±0.5	±4	mV
Capacitive Drive Capability		No sustained oscillations, R_L = 1kΩ			500		pF

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DAC TO SPEAKER AMPLIFIER PATH							
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, P_{OUT} = 200mW, Z_{SPK} = 8Ω + 68µH			-68		dB
Crosstalk		SPKL to SPKR and SPKR to SPKL, P_{OUT} = 640mW, f = 1kHz			-88		dB
Output Noise					53		$µV_{RMS}$
Click-and-Pop Level	K_{CP}	Peak voltage, A-weighted, 32 samples per second, $AV_{SPK\_}$ = 0dB	Into shutdown		65		dBV
			Out of shutdown		66		
MIC INPUT TO SPEAKER AMPLIFIER PATH							
Dynamic Range (Note 4)	DR	Referenced to full-scale output level, $AV_{SPK\_}$ = 0dB			82		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, P_{OUT} = 200mW, R_L = 8Ω + 68µH			71		dB
Click-and-Pop Level	K_{CP}	Peak voltage, A-weighted, 32 samples per second, $AV_{SPK\_}$ = 0dB	Into shutdown		55		dBV
			Out of shutdown		52		
SPEAKER AMPLIFIER							
Output Power	P_{OUT}	f = 1kHz, THD = 10%, Z_{SPK} = 4Ω + 33µH	$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 5.0V		2950		mW
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 4.2V		2060		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V		1570		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.0V		1000		
		f = 1kHz, THD = 1%, Z_{SPK} = 4Ω + 33µH	$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 5.0V		2320		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 4.2V		1620		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V		1240		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.0V		785		
		f = 1kHz, THD = 10%, Z_{SPK} = 8Ω + 68µH	$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 5.0V		1730		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 4.2V		1210		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V		930		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.0V		600		
		f = 1kHz, THD = 1%, Z_{SPK} = 8Ω + 68µH	$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 5.0V		1365		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 4.2V		955		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V		735		
			$V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.0V		475		
Full-Scale Output		(Note 7)			2		V_{RMS}
Volume Control	$AV_{SPK\_}$	(Note 5)	SPVOLL/SPVOLR = 0x00		-62		dB
			SPVOLL/SPVOLR = 0x1F		+8		

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Volume Control Step Size		+8dB to +6dB			0.5		dB
		+6dB to +0dB			1		
		0dB to -14dB			2		
		-14dB to -38dB			3		
		-38dB to -64dB			4		
Mute Attenuation		f = 1kHz			86		dB
Output Offset Voltage	V_{OS}	AV_{SPK} = -61dB, T_A = +25°C			±0.5	±3	mV
EXCURSION LIMITER							
Upper Corner Frequency Range		DHPUCF = 001 to 100		400		1000	Hz
Lower Corner Frequency		DHPLCF = 01 to 10			400		Hz
Biquad Minimum Corner Frequency		DHPUCF = 000 (fixed mode)			100		Hz
		DHPUCF = 001			200		
		DHPUCF = 010			300		
		DHPUCF = 011			400		
		DHPUCF = 100			500		
Threshold Voltage		Z_{SPK} = 8Ω + 68µH, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 5.5V, $AV_{SPK\_}$ = 8dB	DHPTH = 000		0.34		V_P
			DHPTH = 111		0.95		
Release Time		ALCRLS = 101			0.25		s
		ALCRLS = 000			4		
POWER LIMITER							
Attenuation					-64		dB
Threshold		Z_{SPK} = 8Ω + 68µH, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 5.5V, $AV_{SPK\_}$ = 8dB	PWRTH = 0x1		0.08		W
			PWRTH = 0xF		1.23		
Time Constant 1	t_{PWR1}	PWRT1 = 0x1			0.5		s
		PWRT1 = 0xF			8.7		
Time Constant 2	t_{PWR2}	PWRT2 = 0x1 to 0xF			0.5		min
		PWRT2 = 0xF			8.7		
Weighting Factor	k_{PWR}	PWRK = 000 to 111		12.5		100	%
DISTORTION LIMITER							
Distortion Limit		THDCLP = 0x1			< 1		%
		THDCLP = 0xF			24		
Release Time Constant		THDT1 = 000			0.76		s
		THDT1 = 111			6.2		

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DAC TO HEADPHONE AMPLIFIER PATH							
Dynamic Range (Note 4)	DR	f_S = 48kHz	Master or slave mode		101		dB
			Slave mode	97			
			Low power mode, T_A = +25°C	95	97		
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, P_{OUT} = 20mW	R_{HP} = 16Ω		-84	-64	dB
			R_{HP} = 32Ω		-85		
Crosstalk		HPL to HPR and HPR to HPL, P_{OUT} = 5mW, f = 1kHz, R_{HP} = 32Ω			-92		dB
Power-Supply Rejection Ratio	PSRR	V_{AVDD} = V_{PVDD} = 1.65V to 2.0V		46	54		dB
		f = 217Hz, V_{RIPPLE} = 200mV_{P-P}, $AV_{HP\_}$ = 0dB			72		
		f = 1kHz, V_{RIPPLE} = 200mV_{P-P}, $AV_{HP\_}$ = 0dB			63		
		f = 10kHz, V_{RIPPLE} = 200mV_{P-P}, $AV_{HP\_}$ = 0dB			43		
DAC Path Phase Delay		1kHz, 0dB input, highpass filter disabled measured from digital input to analog output	MODE = 0 (voice) 8kHz		2.2		ms
			MODE = 0 (voice) 16kHz		1.1		
			MODE = 1 (music) 8kHz		4.5		
			MODE = 1 (music) 48kHz		0.76		
Gain Error					1	5	%
Channel Gain Mismatch					1		%
Click-and-Pop Level	K_{CP}	Peak voltage, A-weighted, 32 samples per second, $AV_{HP\_}$ = 0dB	Into shutdown		-62		dBV
			Out of shutdown		-63		
LINE INPUT TO HEADPHONE AMPLIFIER PATH							
Total Harmonic Distortion + Noise	THD+N	V_{IN} = 1V_{P-P}, f =1kHz, R_{HP} = 32Ω			81		dB
Dynamic Range (Note 4)					92.5		dB
Click-and-Pop Level	K_{CP}	Peak voltage, A-weighted, 32 samples per second, $AV_{HP\_}$ = 0dB	Into shutdown		-62		dBV
			Out of shutdown		-63		

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
HEADPHONE AMPLIFIER							
Output Power	P_{OUT}	f = 1kHz, THD = 1%	R_{HP} = 32Ω		30		mW
			R_{HP} = 16Ω		38		
Positive Charge-Pump Output Voltage	HPVDD	$V_{OUT} \le V_{PVDD}$ x 0.2V, R_{HP} = ∞			PVDD/2		V
		$V_{OUT} > V_{PVDD}$ x 0.2V, R_{HP} = ∞			PVDD		
Negative Charge-Pump Output Voltage	HPVSS	$V_{OUT} \le V_{PVDD}$ x 0.2V, R_{HP} = ∞			-PVDD/2		V
		$V_{OUT} > V_{PVDD}$ x 0.2V, R_{HP} = ∞			-PVDD		
Output Voltage Threshold (Output Voltage at which the Charge Pump Switches Modes; VOUT Rising; Transition from Split to Invert Mode)	V_{TH}	RL = ∞			±PVDD x 0.2		V
Full-Scale Output		(Note 7)			1		V_{RMS}
Volume Control	$AV_{HP\_}$	(Note 5)	HPVOL_ = 0x00		-67		dB
			HPVOL_ = 0x1F		+3		
Volume Control Step Size		+3dB to +1dB			0.5		dB
		+1dB to -5dB			1		
		-5dB to -19dB			2		
		-19dB to -43dB			3		
		-43dB to -67dB			4		
Mute Attenuation		f = 1kHz			100		dB
Output Offset Voltage	V_{OS}	$AV_{HP\_}$ = -67dB	T_A = +25°C		±0.1	±1	mV
			T_A = T_{MIN} to T_{MAX}			±3	
Capacitive Drive Capability		No sustained oscillations	R_{HP} = 32Ω		500		pF
			R_{HP} = ∞		100		
SPEAKER BYPASS SWITCH							
On-Resistance	R_{ON}	$I_{SPKL\_}$ = 100mA, SPKBYP = 1, $V_{RXIN\_}$ = [0V, $V_{SPKLVDD}$]			2.8		Ω
Total Harmonic Distortion + Noise	THD+N	V_{IN} = $2V_{P\text{-}P}$, V_{CM} = $V_{SPKLVDD}$/2, Z_{SPK} = 8Ω + 68µH, f = 1kHz, SPKBYP = 1	R_S = 10Ω		60		dB
			R_S = 0Ω		60		
Off-Isolation		V_{IN} = $2V_{P\text{-}P}$, V_{CM} = $V_{SPKLVDD}$/2, Z_{SPK} = 8Ω + 68µH, f = 1kHz			96		dB
Off-Leakage Current		$V_{RXIN\_}$ = [0V, $V_{SPKLVDD}$], $V_{SPKL\_}$ = [$V_{SPKLVDD}$, 0V]		-20		+20	µA

ELECTRICAL CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND. R_{LOAD} = R_{HP} = ∞, R_{REC} = ∞, Z_{SPK} = ∞, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 0. T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
RECEIVER BYPASS SWITCH						
On-Resistance	R_{ON}	I_{RECP} = 100mA, RECBYP = 1, V_{RECN} = [0V, $V_{SPKLVDD}$]		2		Ω
Total Harmonic Distortion + Noise	THD+N	V_{IN} = $2V_{P\text{-}P}$, V_{CM} = $V_{SPKLVDD}$/2, Z_{SPK} = 8Ω + 68µH, f = 1kHz, RECBYP = 1, R_S = 0Ω		60		%
Off-Isolation		V_{IN} = $2V_{P\text{-}P}$, V_{CM} = $V_{SPKLVDD}$/2, Z_{SPK} = 8Ω + 68µH, f = 1kHz		84		dB
Off-Leakage Current		V_{RECP} = [0V, $V_{SPKLVDD}$], V_{RECN} = [$V_{SPKLVDD}$, 0V]	-15		+15	µA
JACK DETECTION						
JACKSNS High Threshold	V_{TH1}	MICBIAS enabled	0.92 x $V_{MICBIAS}$	0.95 x $V_{MICBIAS}$	0.98 x $V_{MICBIAS}$	V
		MICBIAS disabled	0.92 x $V_{SPKLVDD}$	0.95 x $V_{SPKLVDD}$	0.98 x $V_{SPKLVDD}$	
JACKSNS Low Threshold	V_{TH2}	MICBIAS enabled	0.06 x $V_{MICBIAS}$	0.10 x $V_{MICBIAS}$	0.17 x $V_{MICBIAS}$	V
		MICBIAS disabled	0.06 x $V_{SPKLVDD}$	0.10 x $V_{SPKLVDD}$	0.17 x $V_{SPKLVDD}$	
JACKSNS Sense Voltage		MICBIAS disabled, JDWK = 1	3.65	3.7		
JACKSNS Sense Resistance	R_{SENSE}	MICBIAS disabled, JDWK = 0	1.6	2.4	2.9	kΩ
JACKSNS Weak Pullup Current	I_{WPU}	MICBIAS disabled, JDWK = 1	2	5	9.5	µA
JACKSNS Deglitch Period	t_{GLITCH}	JDEB = 00		25		ms
		JDEB = 11		200		
BATTERY ADC						
Input Voltage Range			2.6		5.6	V
LSB Size				0.1		V

DIGITAL INPUT/OUTPUT CHARACTERISTICS

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MCLK						
Input High Voltage	V_{IH}		1.2			V
Input Low Voltage	V_{IL}				0.6	V
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDD} = 2.0V, V_{IN} = 0V, 5.5V; T_A = +25°C	-1		+1	µA
Input Capacitance				10		pF

DIGITAL INPUT/OUTPUT CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SDINS1, BCLKS1, LRCLKS1—INPUT						
Input High Voltage	V_{IH}		0.7 x DVDDS1			V
Input Low Voltage	V_{IL}				0.29 x DVDDS1	V
Input Hysteresis				200		mV
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDDS1} = 3.6V, V_{IN} = 0V, 3.6V; T_A = +25°C	-1		+1	µA
Input Capacitance				10		pF
BCLKS1, LRCLKS1, SDOUTS1—OUTPUT						
Output Low Voltage	V_{OL}	V_{DVDDS1} = 1.65V, I_{OL} = 3mA			0.4	V
Output High Voltage	V_{OH}	V_{DVDDS1} = 1.65V, I_{OH} = 3mA	DVDDS1 - 0.4			V
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDD} = 2.0V, V_{IN} = 0V, 5.5V; T_A = +25°C, high-impedance state	-1		+1	µA
SDINS2, BCLKS2, LRCLKS2—INPUT						
Input High Voltage	V_{IH}		0.7 x DVDDS2			V
Input Low Voltage	V_{IL}				0.29 x DVDDS2	V
Input Hysteresis				200		mV
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDDS2} = 3.6V, V_{IN} = 0V, 3.6V; T_A = +25°C	-1		+1	µA
Input Capacitance				10		pF
BCLKS2, LRCLKS2, SDOUTS2—OUTPUT						
Output Low Voltage	V_{OL}	V_{DVDDS2} = 1.65V, I_{OL} = 3mA			0.4	V
Output High Voltage	V_{OH}	V_{DVDDS2} = 1.65V, I_{OH} = 3mA	DVDDS2 - 0.4			V
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDD} = 2.0V, V_{IN} = 0V, 5.5V; T_A = +25°C, high-impedance state	-1		+1	µA
SDA, SCL—INPUT						
Input High Voltage	V_{IH}		0.7 x DVDD			V
Input Low Voltage	V_{IL}				0.3 x DVDD	V
Input Hysteresis				210		mV
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDD} = 2.0V, V_{IN} = 0V, 5.5V; T_A = +25°C	-1		+1	µA
Input Capacitance				10		pF
SDA, $\overline{IRQ}$—OUTPUT						
Output High Current	I_{OH}	V_{OUT} = 5.5V, T_A = +25°C			1	mA
Output Low Voltage	V_{OL}	V_{DVDD} = 1.65V, I_{OL} = 3mA			0.2 x DVDD	V

DIGITAL INPUT/OUTPUT CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIGMICDATA—INPUT						
Input High Voltage	V_{IH}		0.65 x DVDD			V
Input Low Voltage	V_{IL}				0.35 x DVDD	V
Input Hysteresis				125		mV
Input Leakage Current	I_{IH}, I_{IL}	V_{DVDD} = 2.0V, V_{IN} = 0V, 2.0V; T_A = +25°C	-25		+25	µA
Input Capacitance				10		pF
DIGMICCLK—OUTPUT						
Output Low Voltage	V_{OL}	V_{DVDD} = 1.65V, I_{OL} = 1mA			0.4	V
Output High Voltage	V_{OH}	V_{DVDD} = 1.65V, I_{OH} = 1mA	DVDD - 0.4			V

INPUT CLOCK CHARACTERISTICS

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MCLK Input Frequency	f_{MCLK}		10		60	MHz
MCLK Input Duty Cycle		PSCLK = 01	40	50	60	%
		PSCLK = 10 or 11	30		70	
Maximum MCLK Input Jitter				100		ps_{RMS}
LRCLK Sample Rate (Note 8)		DHF_ = 0	8		48	kHz
		DHF_ = 1	48		96	
DAI1 LRCLK Average Frequency Error (Note 9)		FREQ1 = 0x8 to 0xF	0		0	%
		FREQ1 = 0x0	-0.025		+0.025	
DAI2 LRCLK Average Frequency Error (Note 9)			-0.025		+0.025	%
PLL Lock Time		Rapid lock mode		2	7	ms
		Nonrapid lock mode		12	25	
Maximum LRCLK Jitter to Maintain PLL Lock					100	ns
Soft-Start/Stop Time				10		ms

AUDIO INTERFACE TIMING CHARACTERISTICS

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
BCLK Cycle Time	t_{BCLK}	Slave mode		90			ns
BCLK High Time	t_{BCLKH}	Slave mode		20			ns
BCLK Low Time	t_{BCLKL}	Slave mode		20			ns
BCLK or LRCLK Rise and Fall Time	t_R, t_F	Master mode, C_L = 15pF			5		ns
SDIN to BCLK Setup Time	t_{SETUP}			20			ns
LRCLK to BCLK Setup Time	$t_{SYNCSET}$	Slave mode		20			ns
SDIN to BCLK Hold Time	t_{HOLD}			20			ns
LRCLK to BCLK Hold Time	$t_{SYNCHOLD}$	Slave mode		20			ns
Minimum Delay Time from LSB BCLK Falling Edge to High-Impedance State	t_{HIZOUT}	Master mode, TDM_ = 1			42		ns
LRCLK Rising Edge to SDOUT MSB Delay	t_{SYNCTX}	C_L = 30pF, TDM_ = 1, FSW_ = 1				50	ns
BCLK to SDOUT Delay	t_{CLKTX}	C_L = 30pF	TDM_ = 1, BCLK rising edge			50	ns
			TDM_ = 0			50	
Delay Time from BCLK to LRCLK	$t_{CLKSYNC}$	Master mode	TDM_ = 1	-15		+15	ns
			TDM_ = 0			0.8 x t_{BCLKL}	
Delay Time from LRCLK to BCLK After LSB	$t_{ENDSYNC}$	Master mode	TDM_ = 1, FSW_ = 1	20			ns

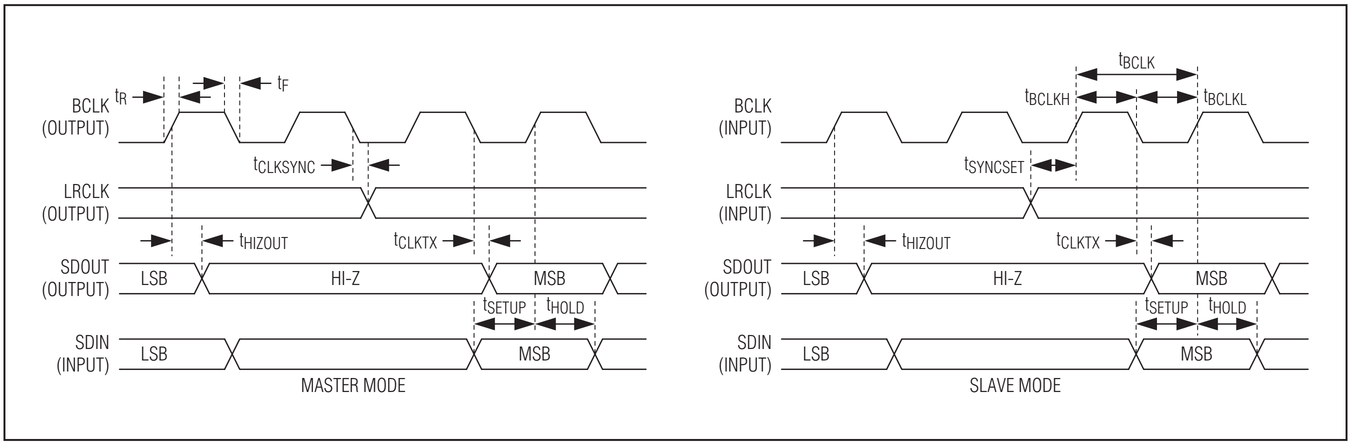


Figure 1. Non-TDM Audio Interface Timing Diagrams (TDM_ = 0)

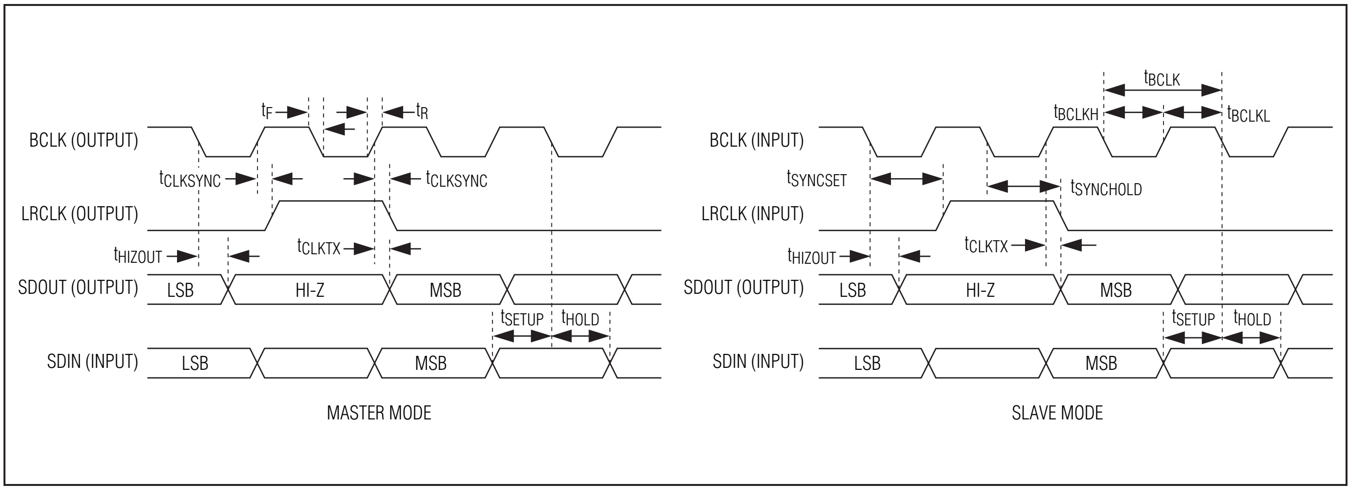


Figure 2. TDM Audio Interface Timing Diagram (TDM_ = 1, FSW_ = 0)

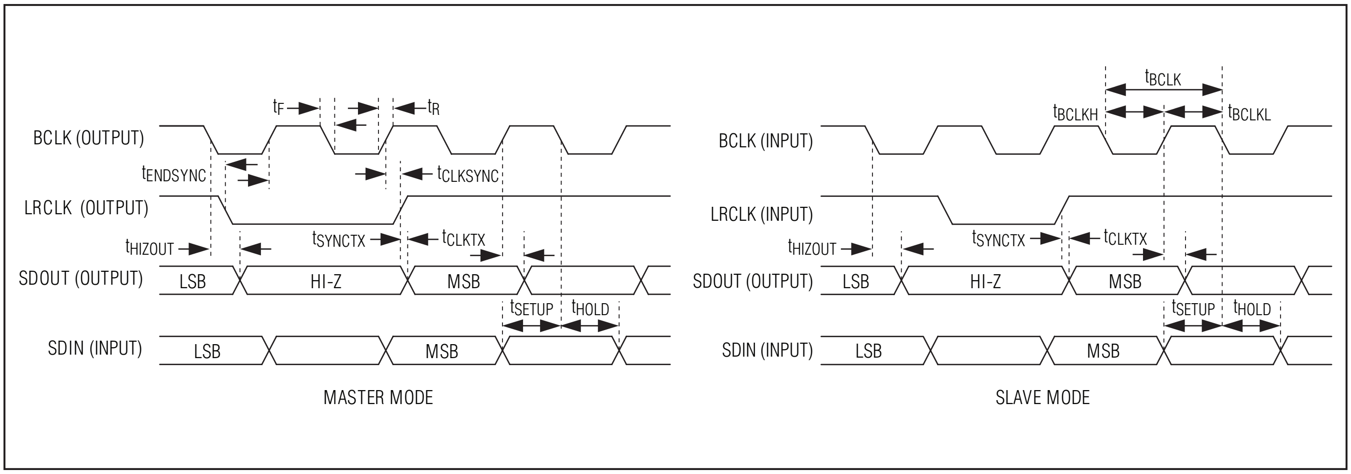


Figure 3. TDM Audio Interface Timing Diagram (TDM_ = 1, FSW_ = 1)

DIGITAL MICROPHONE TIMING CHARACTERSTICS

(V_{AVDD} = V_{HPVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIGMICCLK Frequency	f_{MICCLK}	MICCLK = 00		PCLK/8		MHz
		MICCLK = 01		PCLK/6		
		MICCLK = 10		64 x f_{LRCLK}		
DIGMICDATA to DIGMICCLK Setup Time	$t_{SU,MIC}$	Either clock edge	20			ns
DIGMICDATA to DIGMICCLK Hold Time	$t_{HD,MIC}$	Either clock edge	0			ns

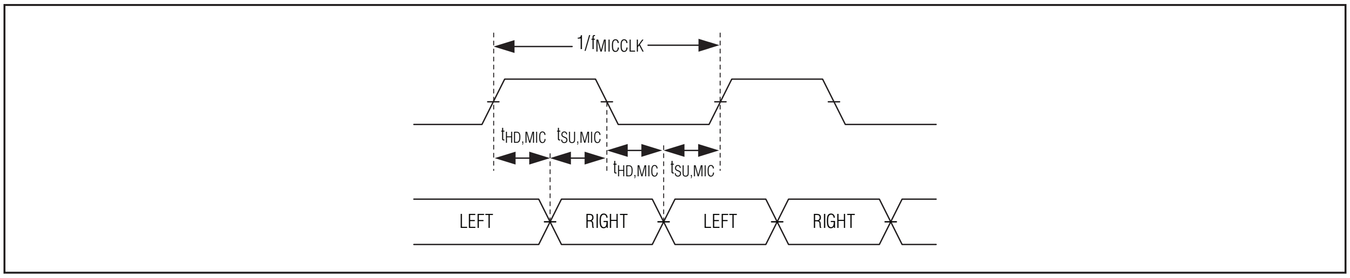


Figure 4. Digital Microphone Timing Diagram

I2C TIMING CHARACTERISTICS

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Serial-Clock Frequency	f_{SCL}	Guaranteed by SCL pulse-width low and high	0		400	kHz
Bus Free Time Between STOP and START Conditions	t_{BUF}		1.3			µs
Hold Time (Repeated) START Condition	$t_{HD,STA}$		0.6			µs
SCL Pulse-Width Low	t_{LOW}		1.3			µs
SCL Pulse-Width High	t_{HIGH}		0.6			µs
Setup Time for a Repeated START Condition	$t_{SU,STA}$		0.6			µs
Data Hold Time	$t_{HD,DAT}$	R_{PU} = 475Ω, CB = 100pF, 400pF	0		900	ns
Data Setup Time	$t_{SU,DAT}$		100			ns
SDA and SCL Receiving Rise Time	t_R	(Note 10)	20 + $0.1C_B$		300	ns
SDA and SCL Receiving Fall Time	t_F	(Note 10)	20 + $0.1C_B$		300	ns
SDA Transmitting Fall Time	t_F	R_{PU} = 475Ω, C_B = 100pF, 400pF (Note 10)	20 + $0.05C_B$		250	ns
Setup Time for STOP Condition	$t_{SU,STO}$		0.6			µs
Bus Capacitance	C_B	Guaranteed by SDA transmitting fall time			400	pF
Pulse Width of Suppressed Spike	t_{SP}		0		50	ns

I2C TIMING CHARACTERISTICS (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, T_A = +25°C, unless otherwise noted.) (Note 1)

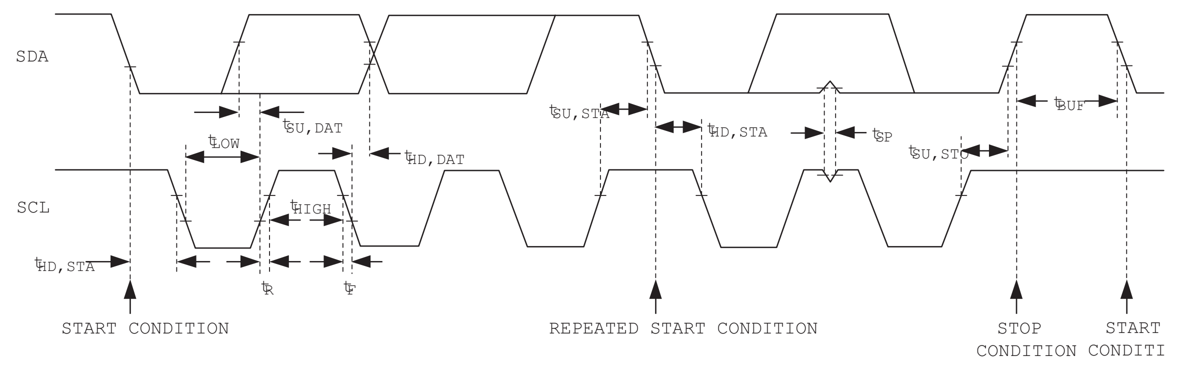


Figure 5. I2C Interface Timing Diagram

Note 1: The IC is 100% production tested at T_A = +25°C. Specifications over temperature limits are guaranteed by design.

Note 2: Analog supply current = I_{AVDD} + I_{HPVDD}. Speaker supply current = $I_{SPKLVDD}$ + $I_{SPKRVDD}$. Digital supply current = I_{DVDD} + I_{DVDDS1} + I_{DVDDS2}.

Note 3: Clocking all zeros into the DAC.

Note 4: Dynamic range measured using the EIAJ method. -60dBFS, 1kHz output signal, A-weighted and normalized to 0dBFS. f = 20Hz to 20kHz.

Note 5: Gain measured relative to the 0dB setting.

Note 6: The filter specification is accurate only for synchronous clocking modes, where NI is a multiple of 0x1000.

Note 7: 0dBFS for DAC input. $1V_{P-P}$ for INA/INB inputs.

Note 8: LRCLK may be any rate in the indicated range. Asynchronous or noninteger MCLK/LRCLK ratios may exhibit some full-scale performance degradation compared to synchronous integer related MCLK/LRCLK ratios.

Note 9: In master-mode operation, the accuracy of the MCLK input proportionally determines the accuracy of the sample clock rate.

Note 10: C_B is in pF.

Power Consumption

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, MAS = 0.)

MODE	I_{AVDD} (mA)	I_{PVDD} (mA)	I_{SPKVDD} + $I_{SPKLVDD}$ (mA)	I_{DVDD} (mA)	I_{DVDDS1} + I_{DVDDS2} (mA)	POWER (mW)	DYNAMIC RANGE (dB)
Playback to Headphone Only							
DAC Playback 48kHz Stereo HP DAC → HP Low power mode, 24-bit, music filters, 256Fs	**1.25**	**0.47**	**0.00**	**1.35**	**0.01**	**5.55**	**97**
DAC Playback 48kHz Stereo HP DAC → HP Low power mode, 24-bit, music filters, 256Fs, 0.1mW/channel, R_{HP} = 32Ω	**1.25**	**1.81**	**0.00**	**1.56**	**0.01**	**8.32**	**97**

Power Consumption (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V, MAS = 0.)

MODE	I_{AVDD} (mA)	I_{PVDD} (mA)	I_{SPKVDD} + $I_{SPKLVDD}$ (mA)	I_{DVDD} (mA)	I_{DVDDS1} + I_{DVDDS2} (mA)	POWER (mW)	DYNAMIC RANGE (dB)
DAC Playback to Headphone							
DAC Playback 48kHz Stereo HP DAC → HP 24-bit, music filters, 256Fs	**2.04**	**1.27**	**0.00**	**1.53**	**0.01**	**8.72**	**101**
DAC Playback 48kHz Stereo HP DAC → HP 24-bit, music filters, 256Fs, 0.1mW/channel, R_{HP} = 32Ω	**2.04**	**2.11**	**0.00**	**1.74**	**0.01**	**10.63**	**101**
DAC Playback 44.1kHz Stereo HP DAC → HP 24-bit, music filters	**2.03**	**1.27**	**0.00**	**1.41**	**0.01**	**8.46**	**101**
DAC Playback 44.1kHz Stereo HP DAC → HP Low power mode, 24-bit, music filters	**1.25**	**0.47**	**0.00**	**1.25**	**0.01**	**5.34**	**98**
DAC Playback 8kHz Stereo HP DAC → HP 16-bit, voice filters	**2.04**	**1.27**	**0.00**	**1.07**	**0.00**	**7.89**	**96**
DAC Playback 8kHz Stereo HP DAC → HP 16-bit, low power mode, voice filters	**1.26**	**0.47**	**0.00**	**0.90**	**0.00**	**4.72**	**96**
DAC Playback 8kHz Mono HP DAC → HP 16-bit, low power mode, voice filters	**0.77**	**0.29**	**0.00**	**0.79**	**0.00**	**3.33**	**98**
Line Playback Stereo HP INA → HP Single-ended inputs	**2.40**	**1.27**	**0.00**	**0.02**	**0.00**	**6.67**	**95**
DAC Playback to Class D Speaker							
DAC Playback 48kHz Stereo SPK DAC → SPK 24-bit, music filters	**2.31**	**0.00**	**6.33**	**2.14**	**0.01**	**31.44**	**92**

Power Consumption (continued)

($V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2}$ = 1.8V, $V_{SPKLVDD} = V_{SPKRVDD}$ = 3.7V, MAS = 0.)

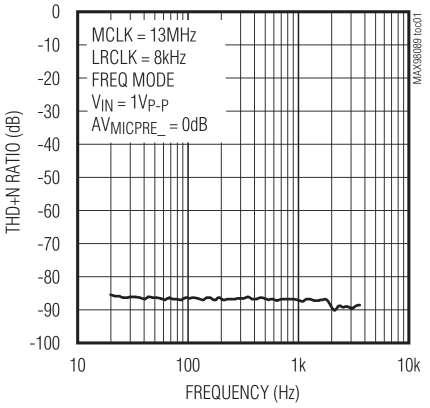
MODE	I_{AVDD} (mA)	I_{PVDD} (mA)	I_{SPKVDD} + $I_{SPKLVDD}$ (mA)	I_{DVDD} (mA)	I_{DVDDS1} + I_{DVDDS2} (mA)	POWER (mW)	DYNAMIC RANGE (dB)
DAC Playback 48kHz Mono SPK DAC → SPK 24-bit, music filters	**1.35**	**0.00**	**3.23**	**1.84**	**0.01**	**17.69**	**92**
Line Playback Mono SPK INA → SPKL Differential inputs	**1.01**	**0.00**	**3.24**	**0.03**	**0.00**	**13.83**	**93**
Full Duplex							
Full-Duplex 8kHz Mono RCV MIC1 → ADC DAC → REC 16-bit, voice filters	**6.32**	**0.00**	**1.54**	**1.24**	**0.01**	**19.33**	**Record = 93** **Playback = 94**
Full-Duplex 8kHz Stereo HP MIC1/2 → ADC DAC → HP 16-bit, mixer, voice filters	**11.19**	**1.27**	**0.48**	**1.28**	**0.01**	**26.43**	**Record = 93** **Playback = 96**
Full-Duplex 8kHz Stereo HP MIC1/2 → ADC DAC → HP 16-bit, low power mode, voice filters	**7.12**	**0.47**	**0.48**	**1.10**	**0.02**	**17.44**	**Record = 93** **Playback = 96**
Line Record							
Line Stereo Record 48kHz INA → ADC 24-bit, low power, music filters	**6.19**	**0.00**	**0.20**	**1.31**	**0.15**	**14.47**	**91**
Line Stereo Record 48kHz INA → ADC Direct pin input, 24bit, low power, music filters	**5.69**	**0.00**	**0.20**	**1.31**	**0.12**	**13.53**	**93**

Typical Operating Characteristics

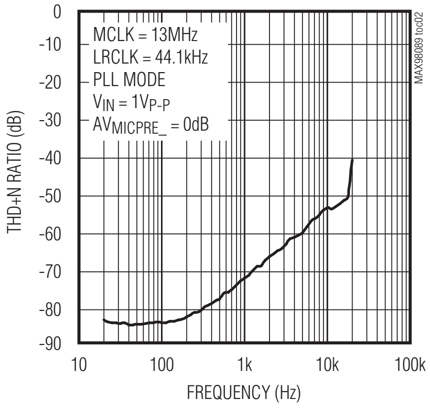
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

Microphone to ADC

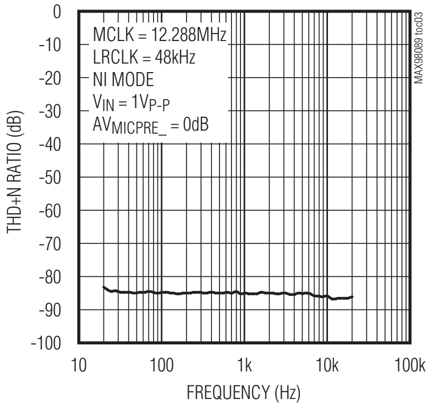
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (MIC TO ADC)



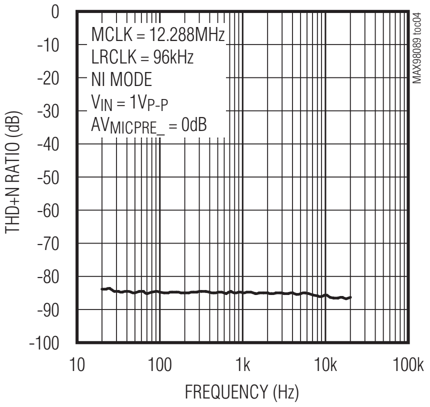
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (MIC TO ADC)



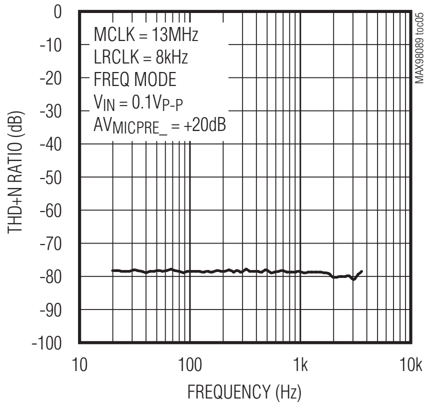
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (MIC TO ADC)



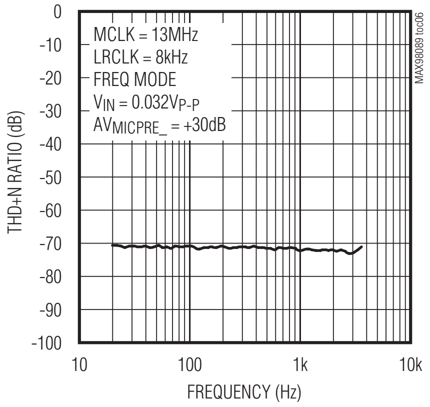
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (MIC TO ADC)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (MIC TO ADC)



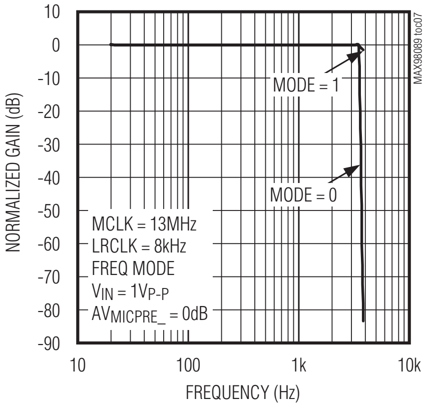
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (MIC TO ADC)



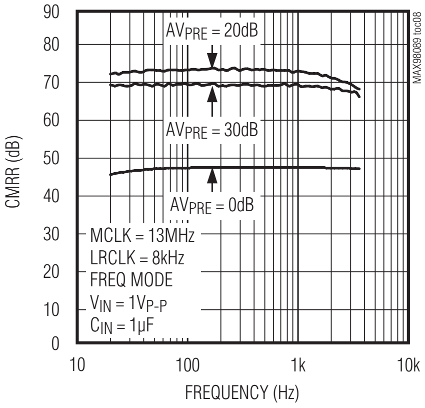
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

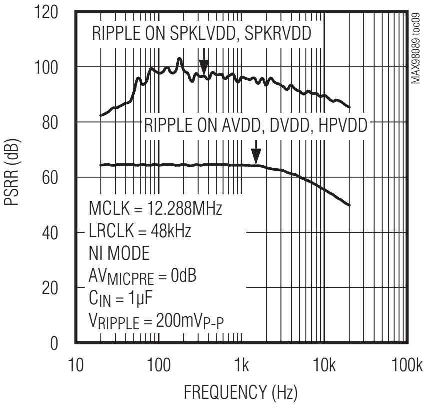
GAIN vs. FREQUENCY (MIC TO ADC)



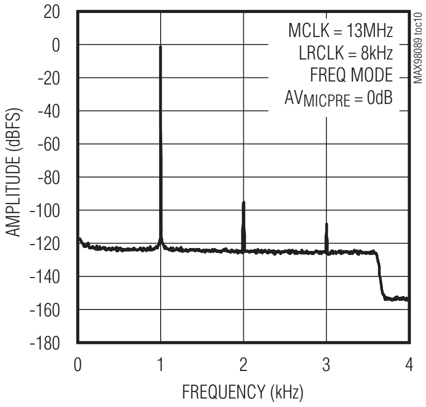
COMMON-MODE REJECTION RATIO vs. FREQUENCY (MIC TO ADC)



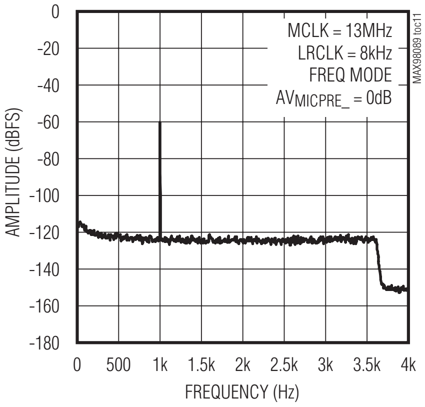
POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (MIC TO ADC)



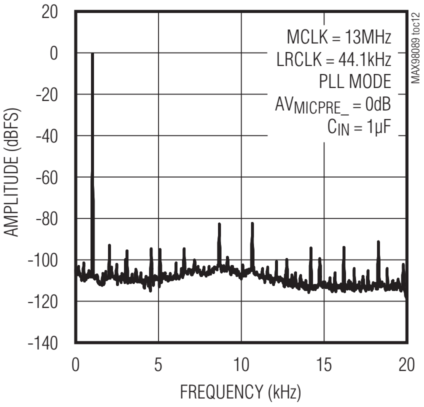
FFT, 0dBFS (MIC TO ADC)



FFT, -60dBFS (MIC TO ADC)

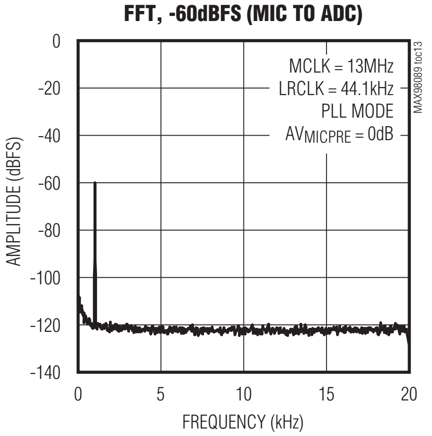


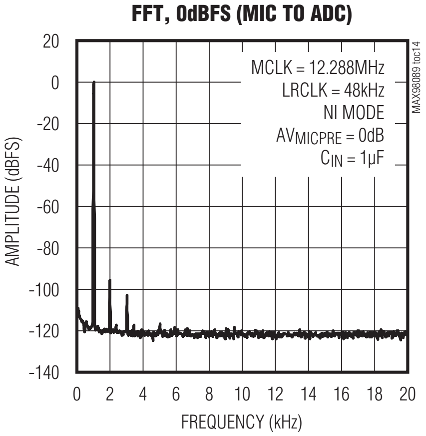
FFT, 0dBFS (MIC TO ADC)

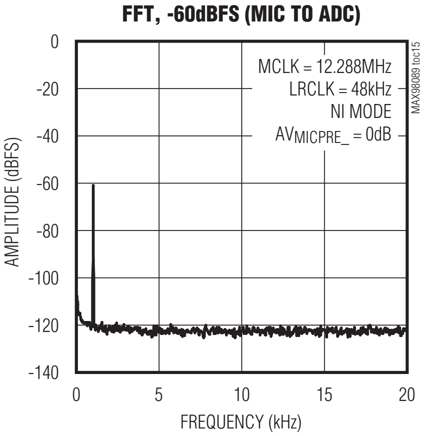


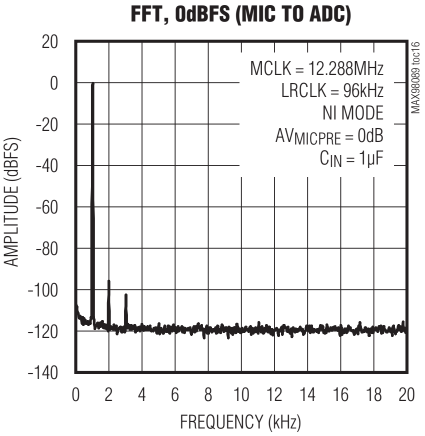
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)





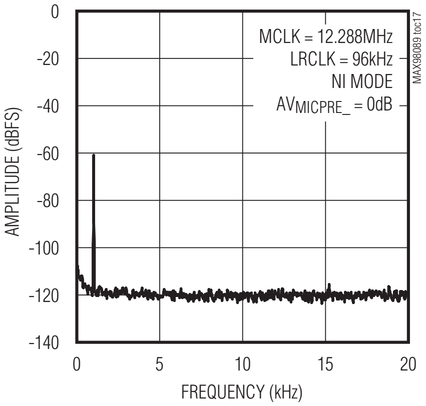




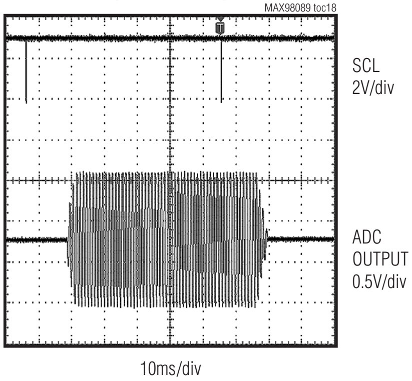
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

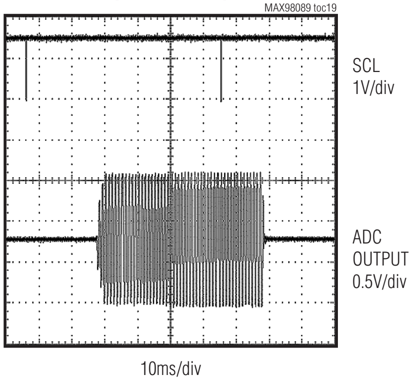
FFT, -60dBFS (MIC TO ADC)



ADC ENABLE/DISABLE RESPONSE (MIC TO ADC)



SOFTWARE TURN-ON/OFF RESPONSE (MIC TO ADC)

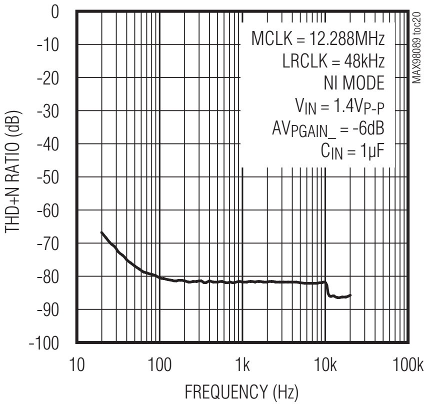


Typical Operating Characteristics (continued)

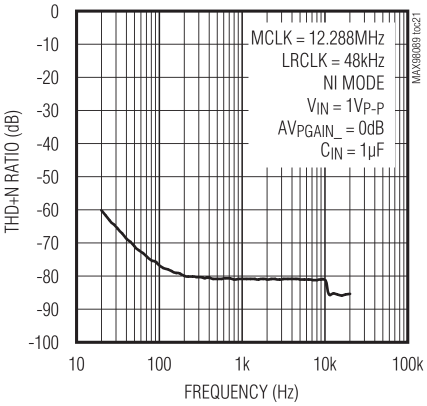
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

Line to ADC

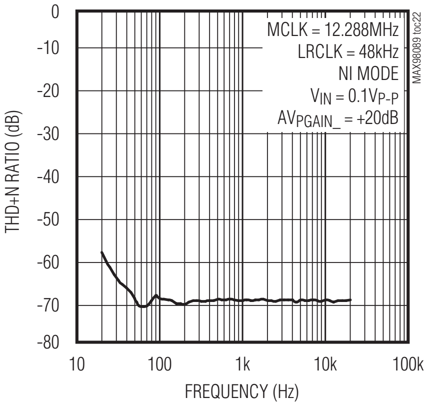
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO ADC)



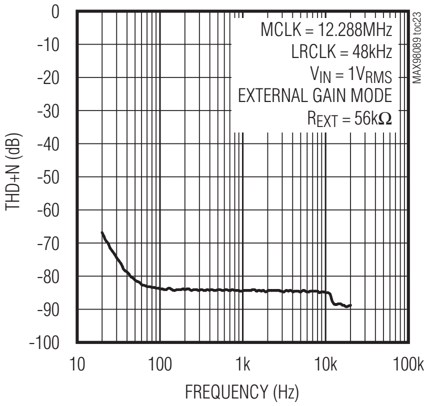
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO ADC)



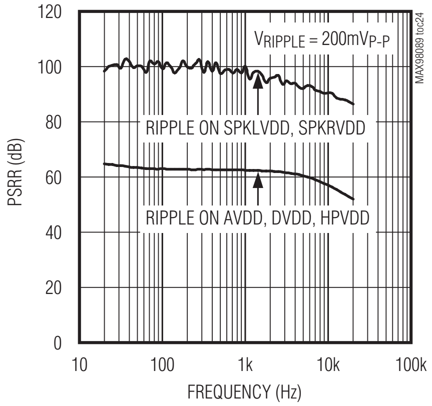
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO ADC)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE-IN TO ADC)



POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (LINE TO ADC)

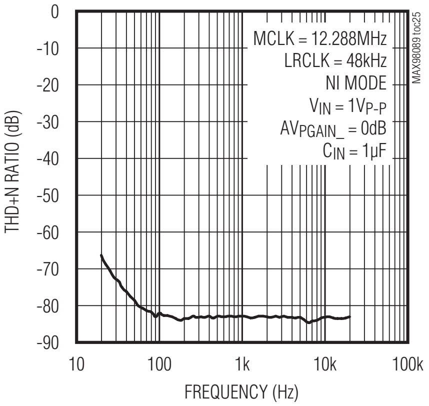


Typical Operating Characteristics (continued)

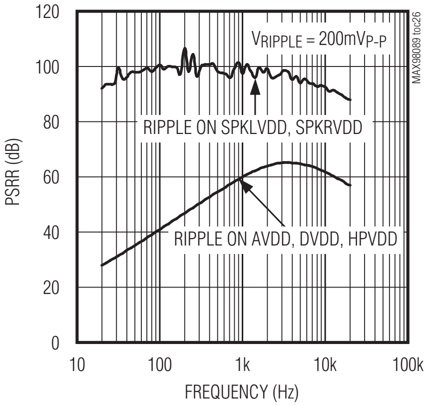
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

Line-In Pin Direct to ADC

TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO ADC PIN DIRECT)

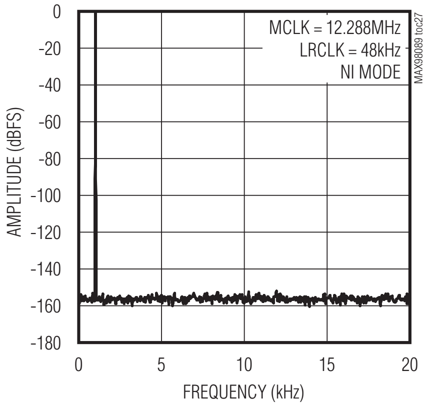


POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (LINE TO ADC PIN DIRECT)

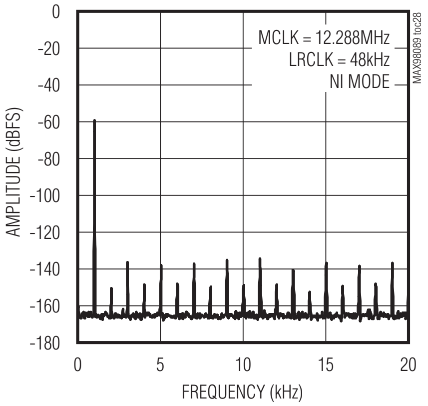


Digital Loopback

FFT, 0dBFS (SDINS1 TO SDINS2 DIGITAL LOOPBACK)



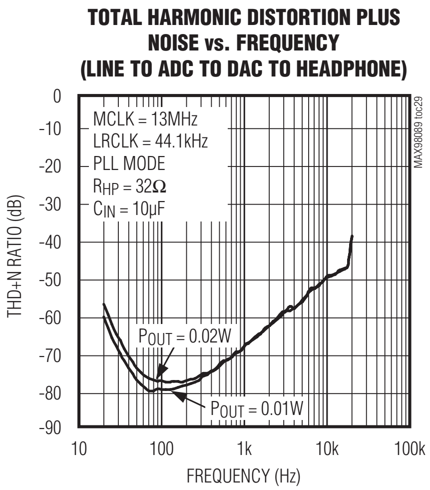
FFT, -60dBFS (SDINS1 TO SDINS2 DIGITAL LOOPBACK)

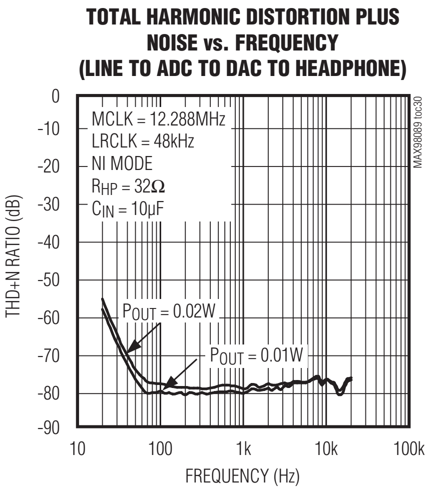


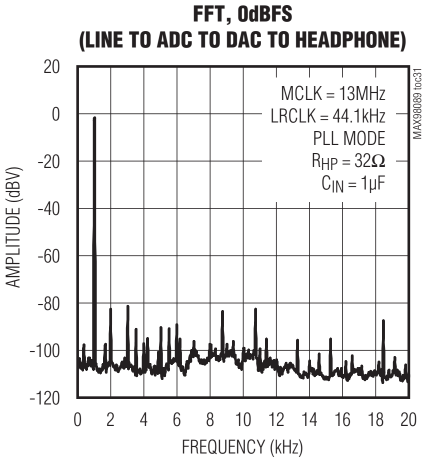
Typical Operating Characteristics (continued)

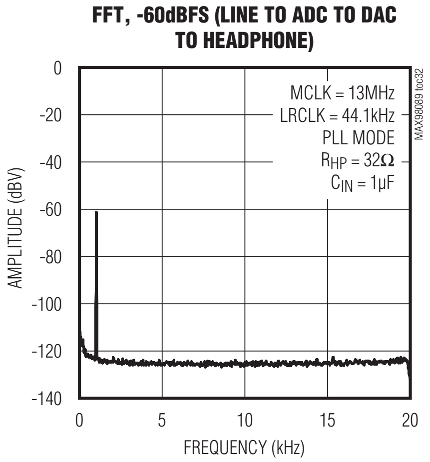
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

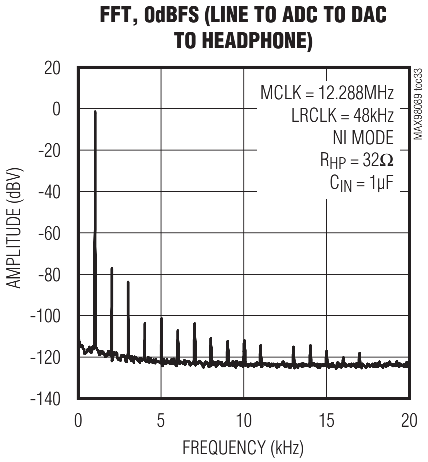
Analog Loopback

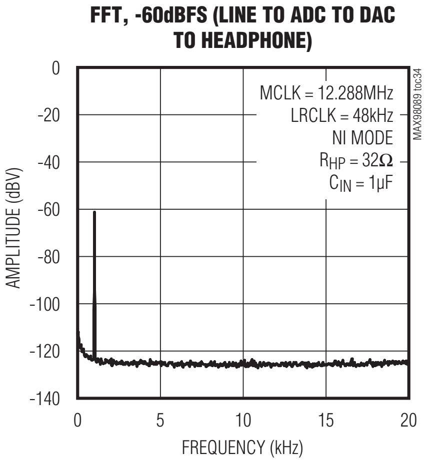

TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO ADC TO DAC TO HEADPHONE)


TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO ADC TO DAC TO HEADPHONE)


FFT, 0dBFS (LINE TO ADC TO DAC TO HEADPHONE)


FFT, -60dBFS (LINE TO ADC TO DAC TO HEADPHONE)

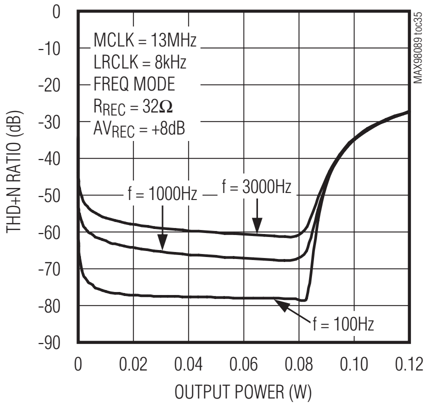

FFT, 0dBFS (LINE TO ADC TO DAC TO HEADPHONE)

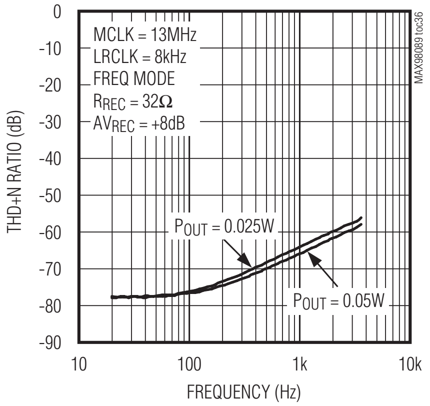

FFT, -60dBFS (LINE TO ADC TO DAC TO HEADPHONE)

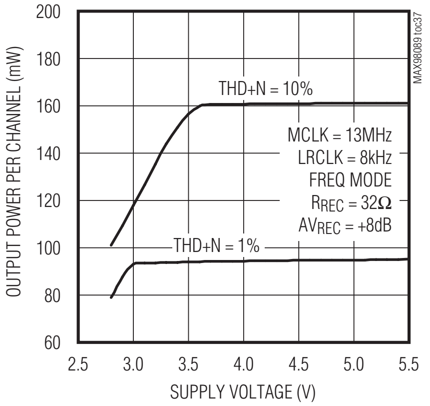
Typical Operating Characteristics (continued)

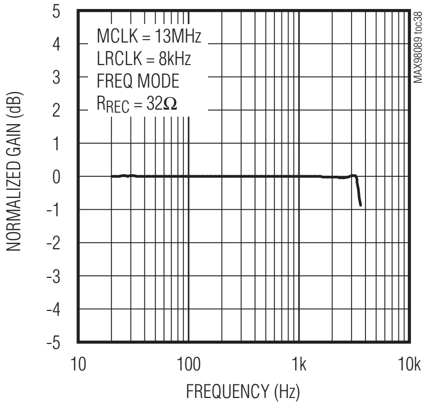
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

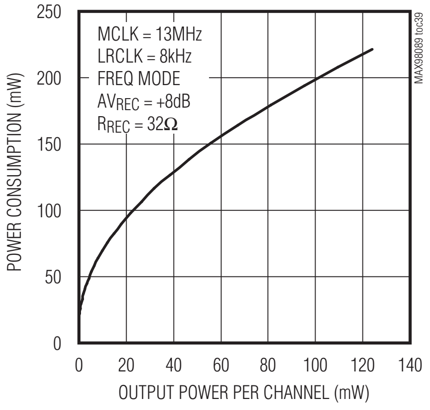
DAC to Receiver

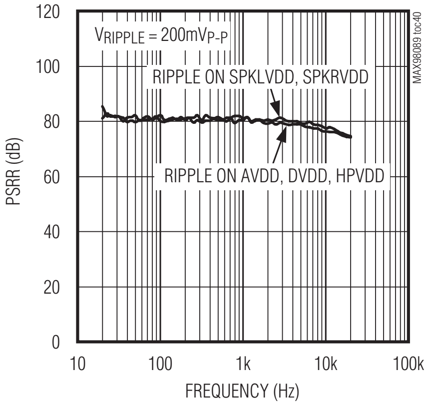

TOTAL HARMONIC DISTORTION vs. OUTPUT POWER (DAC TO RECEIVER)


TOTAL HARMONIC DISTORTION vs. FREQUENCY (DAC TO RECEIVER)


OUTPUT POWER vs. SUPPLY VOLTAGE (DAC TO RECEIVER)

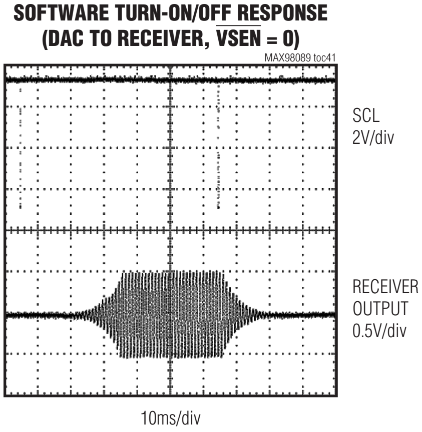

GAIN vs. FREQUENCY (DAC TO RECEIVER)

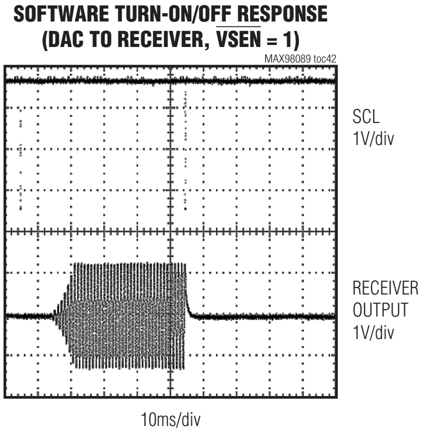

POWER CONSUMPTION vs. OUTPUT POWER (DAC TO RECEIVER)

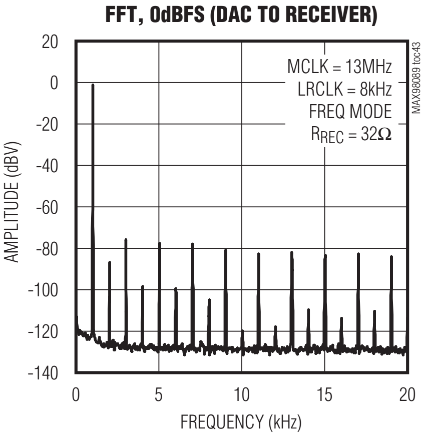

POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (DAC TO RECEIVER)

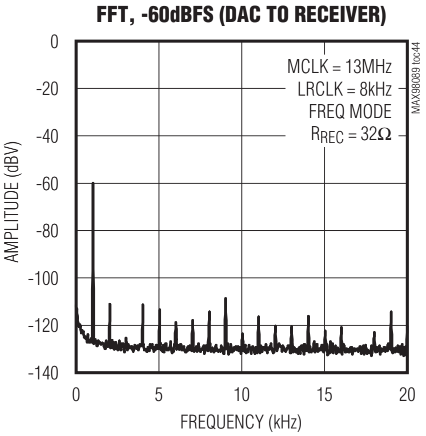
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)







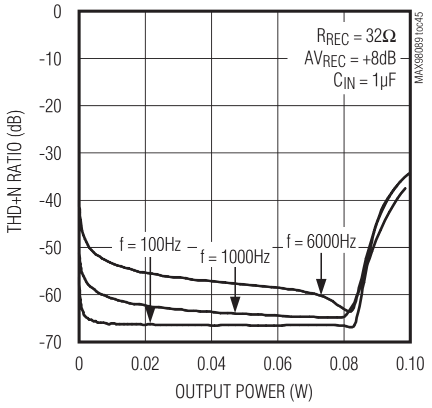


Typical Operating Characteristics (continued)

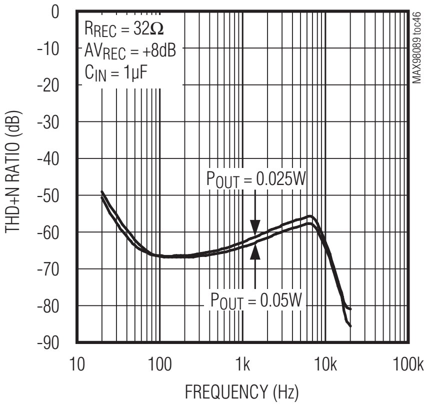
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

Line to Receiver

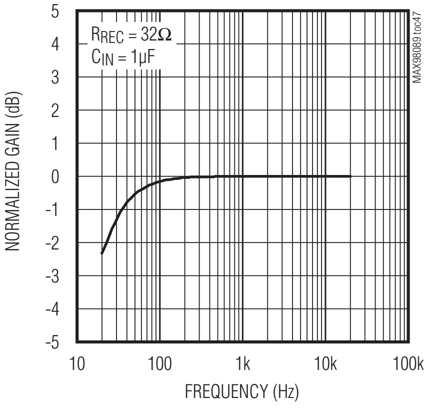
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (LINE TO RECEIVER)



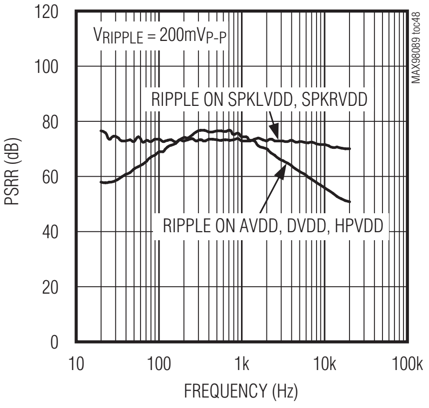
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO RECEIVER)



GAIN vs. FREQUENCY (LINE TO RECEIVER)



POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (LINE TO RECEIVER)

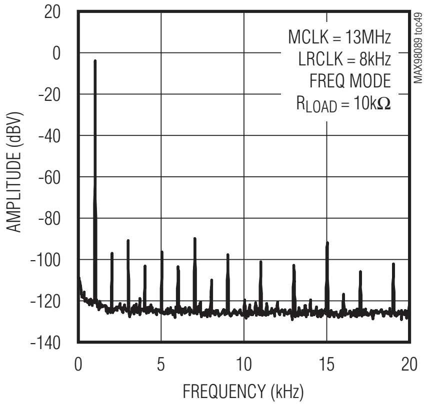


Typical Operating Characteristics (continued)

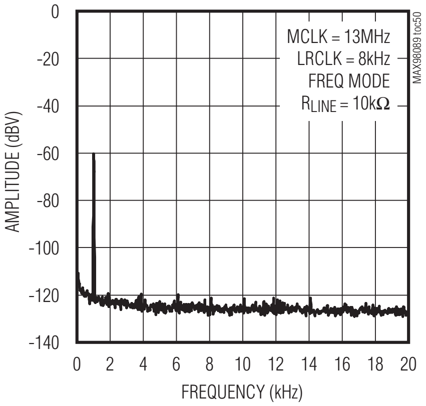
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

DAC-to-Line Output

INBAND OUTPUT SPECTRUM, 0dBFS (DAC TO LINE)

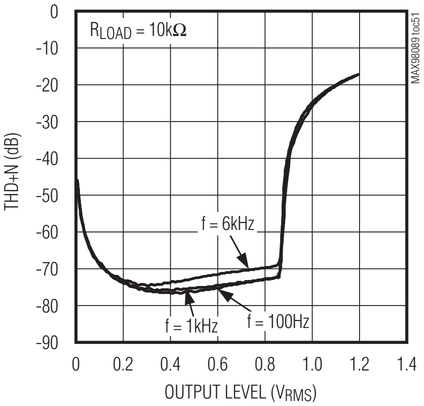


INBAND OUTPUT SPECTRUM, -60dBFS (DAC TO LINE)

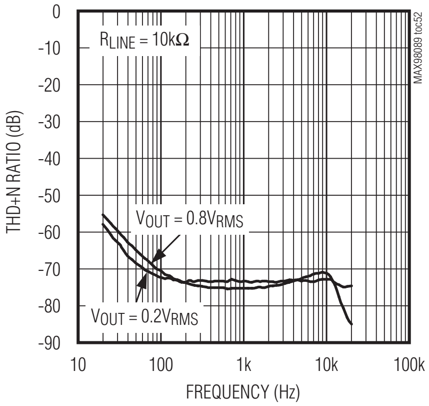


Line-to-Line Output

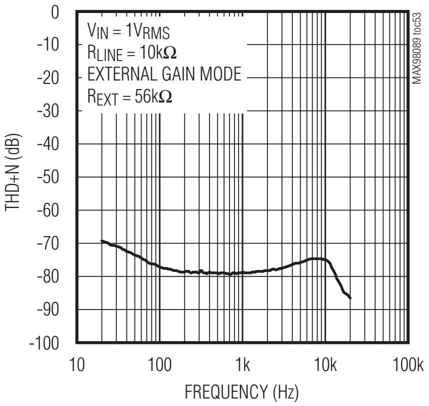
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT LEVEL (LINE-IN TO LINE-OUT)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE IN TO LINE OUT)



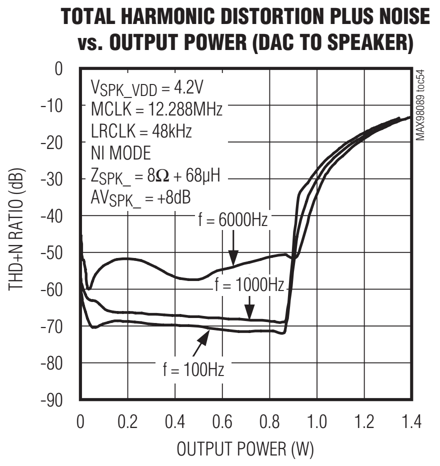
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE-IN TO LINE-OUT)



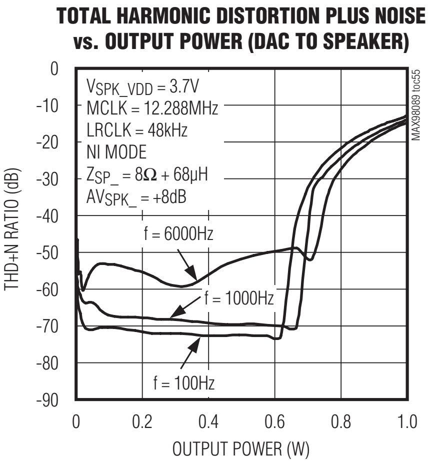
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

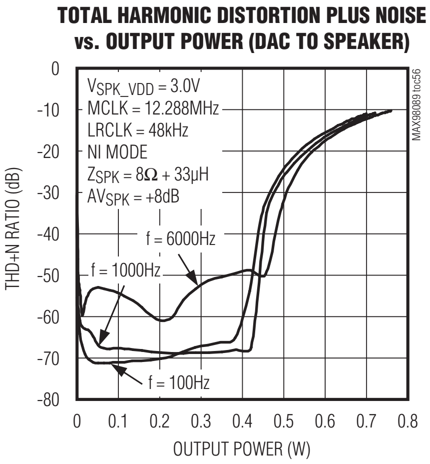
DAC to Speaker



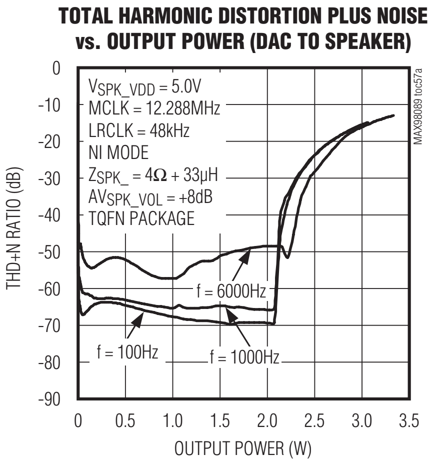
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



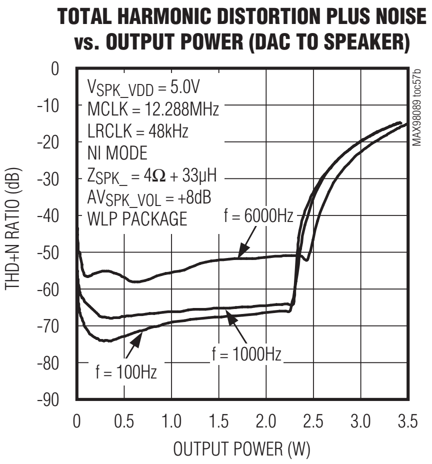
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)

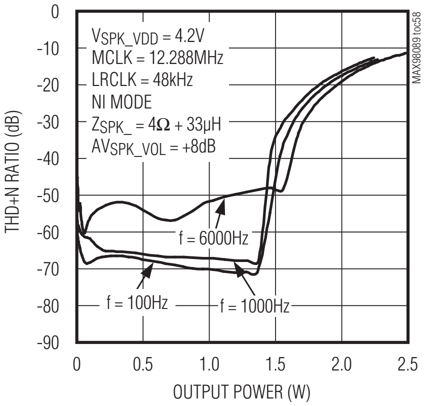


TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)

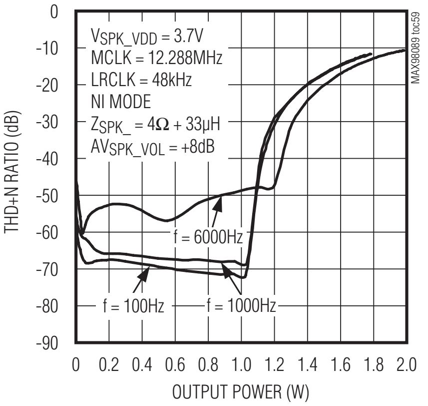
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

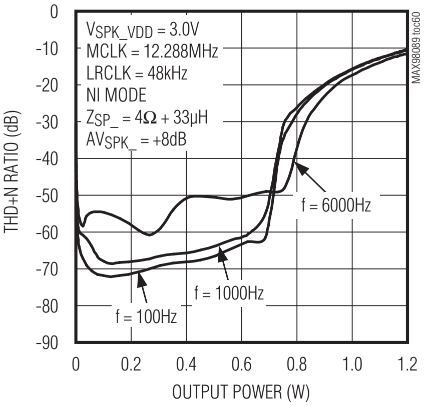
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



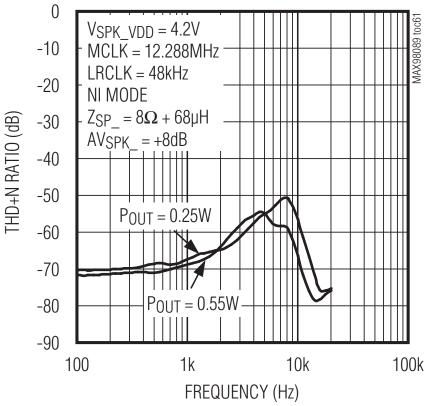
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



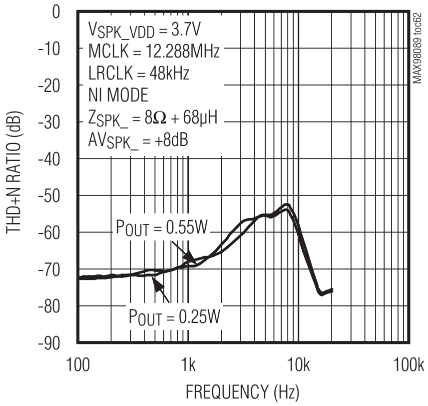
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



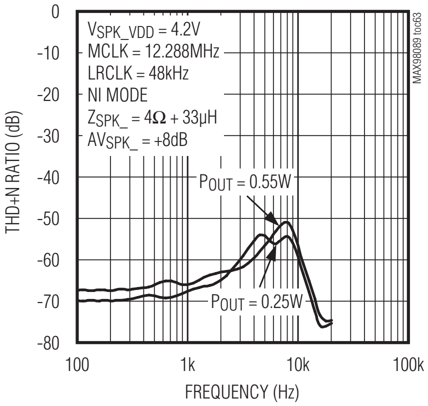
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO SPEAKER)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO SPEAKER)



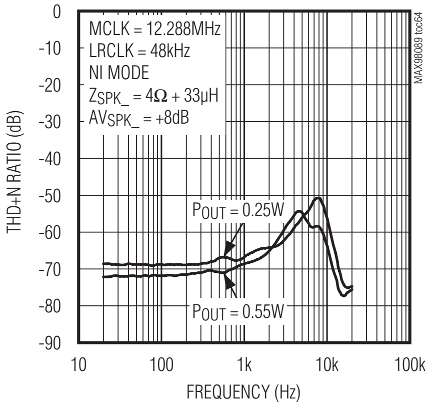
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO SPEAKER)



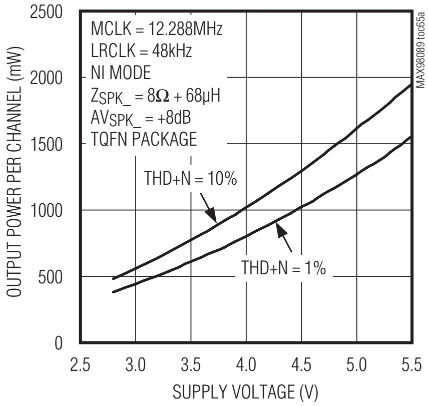
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

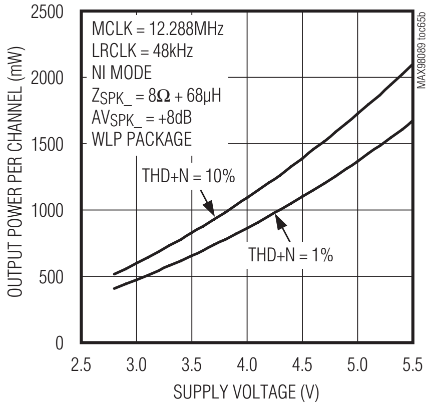
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO SPEAKER)



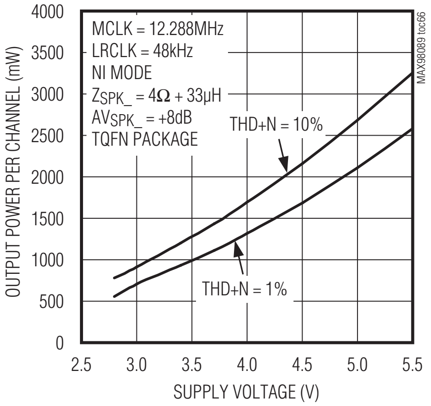
OUTPUT POWER vs. SUPPLY VOLTAGE (DAC TO SPEAKER)



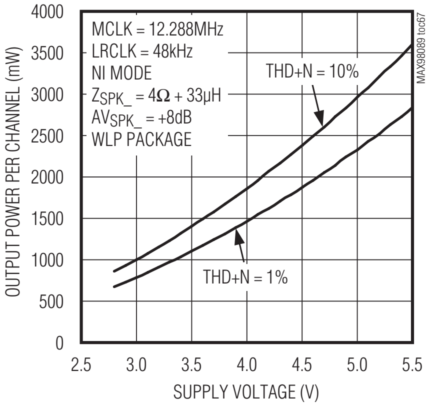
OUTPUT POWER vs. SUPPLY VOLTAGE (DAC TO SPEAKER)



OUTPUT POWER vs. SUPPLY VOLTAGE (DAC TO SPEAKER)

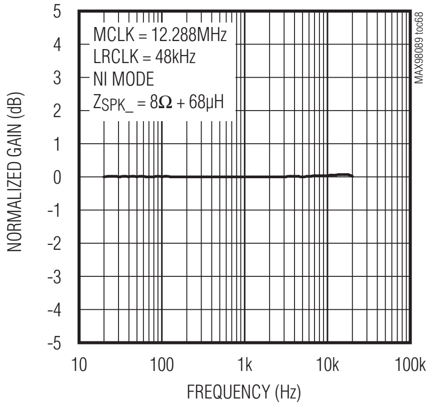


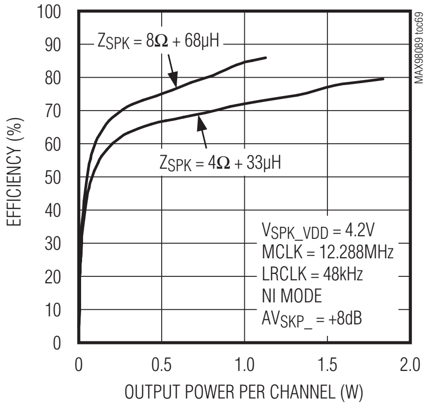
OUTPUT POWER vs. SUPPLY VOLTAGE (DAC TO SPEAKER)

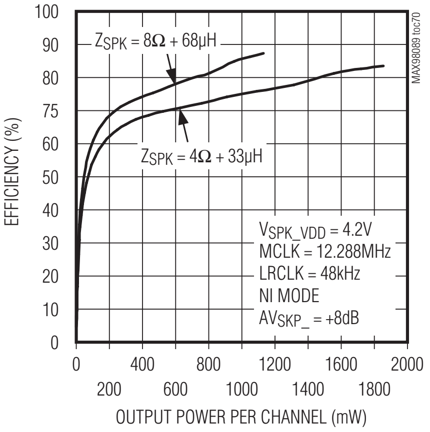


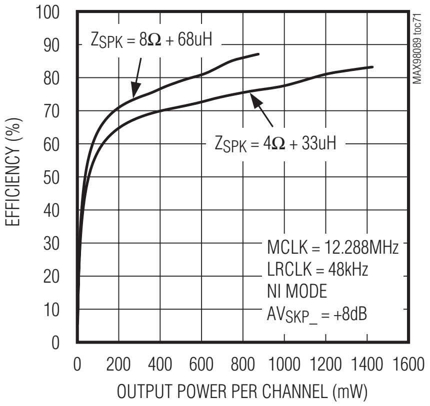
Typical Operating Characteristics (continued)

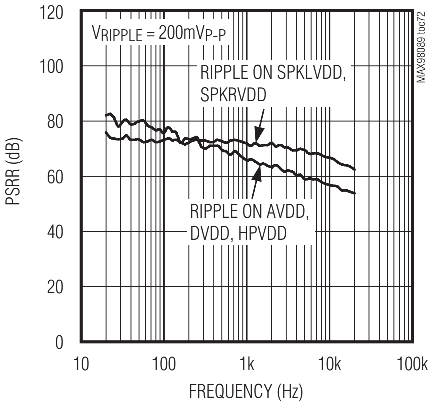
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)


GAIN vs. FREQUENCY (DAC TO SPEAKER)


EFFICIENCY vs. OUTPUT POWER (DAC TO SPEAKER)


EFFICIENCY vs. OUTPUT POWER (DAC TO SPEAKER)

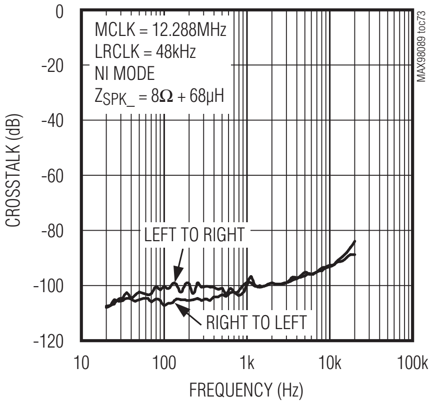

EFFICIENCY vs. OUTPUT POWER (DAC TO SPEAKER)


POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (DAC TO SPEAKER)

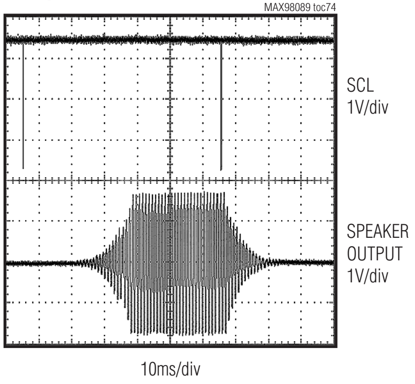
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

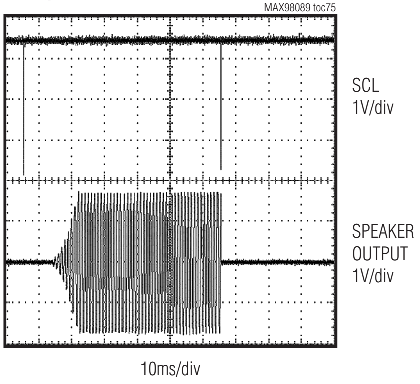
CROSSTALK vs. FREQUENCY (DAC TO SPEAKER)



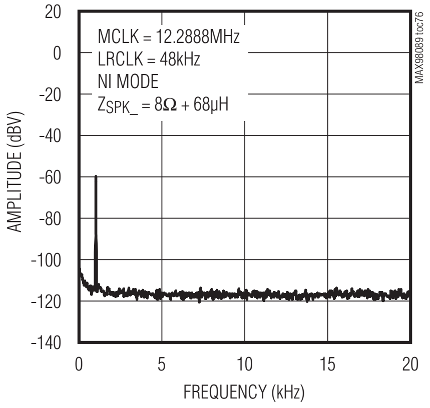
SOFTWARE TURN-ON/OFF RESPONSE (DAC TO SPEAKER, $\overline{VSEN}$ = 0)



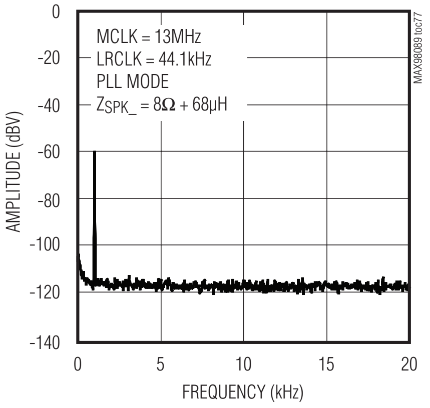
SOFTWARE TURN-ON/OFF RESPONSE (DAC TO SPEAKER, $\overline{VSEN}$ = 1)



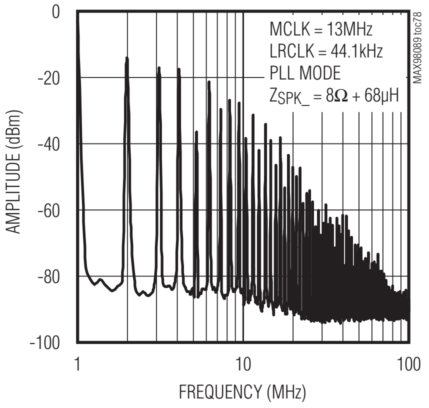
FFT, -60dBFS (DAC TO SPEAKER)



FFT, -60dBFS (DAC TO SPEAKER)



WIDEBAND FFT (DAC TO SPEAKER)

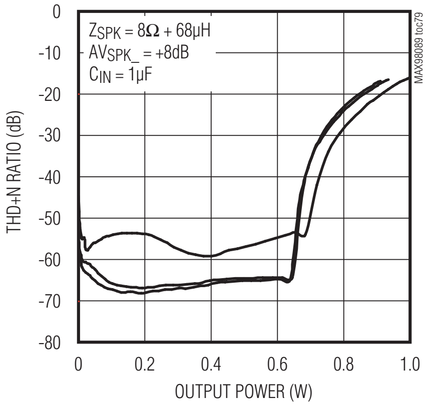


Typical Operating Characteristics (continued)

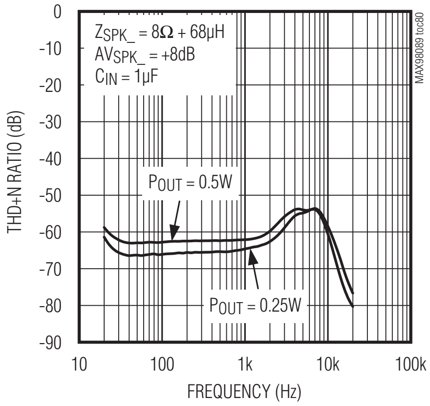
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

Line to Speaker

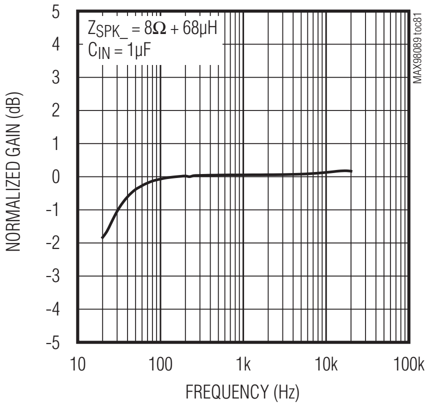
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (LINE TO SPEAKER)



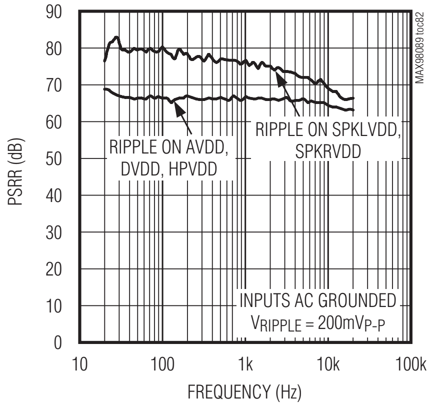
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO SPEAKER)



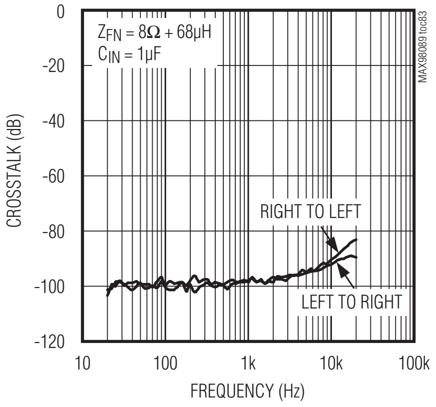
GAIN vs. FREQUENCY (LINE TO SPEAKER)



POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (LINE TO SPEAKER)



CROSSTALK vs. FREQUENCY (LINE TO SPEAKER)

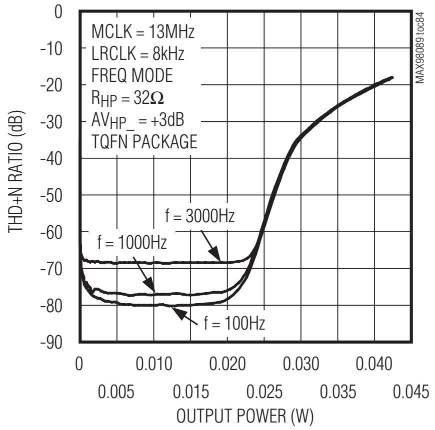


Typical Operating Characteristics (continued)

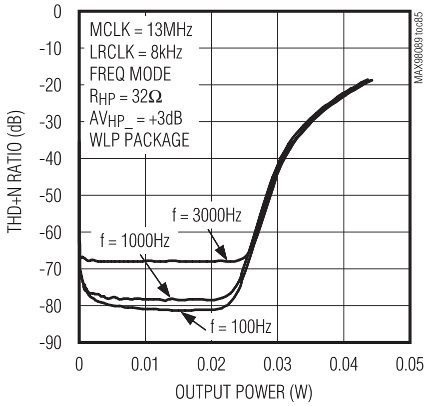
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

DAC to Headphone

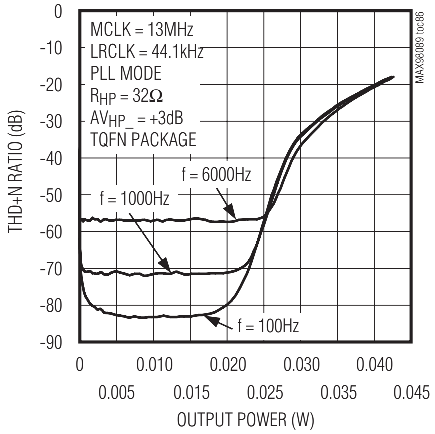
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



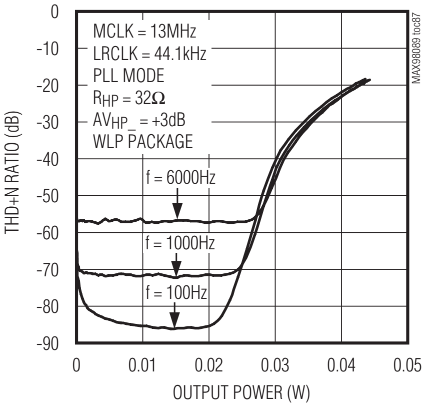
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



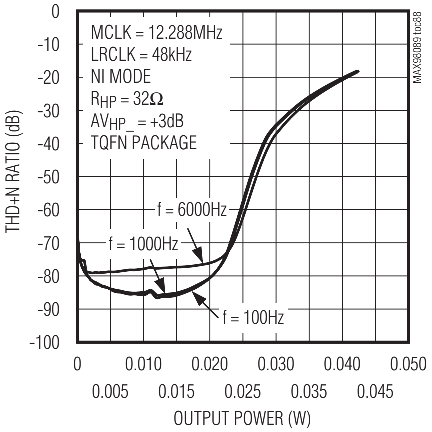
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



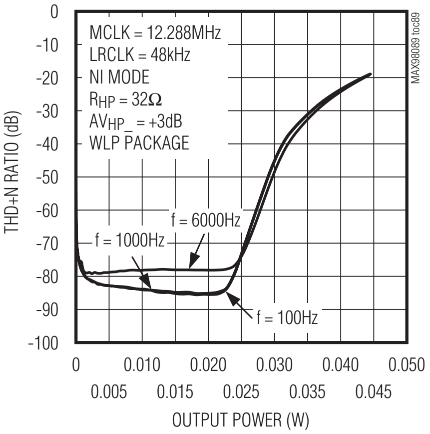
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



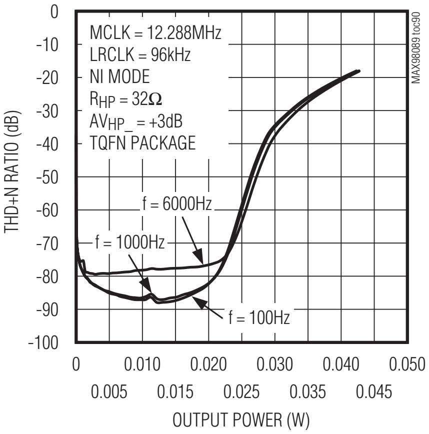
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

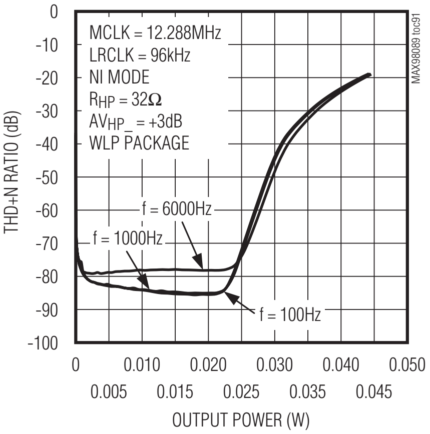
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



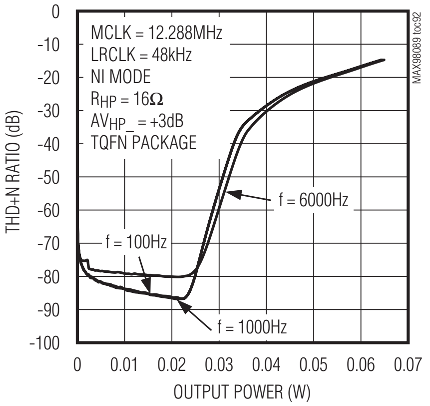
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



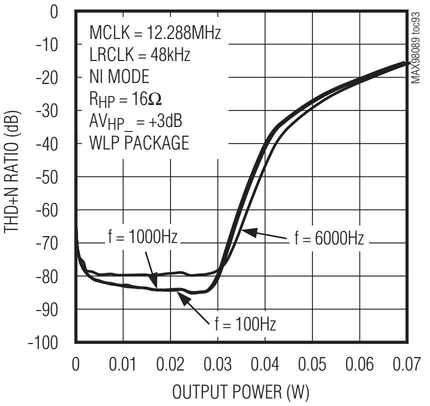
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



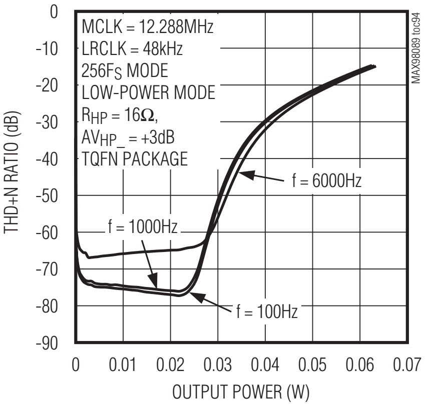
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



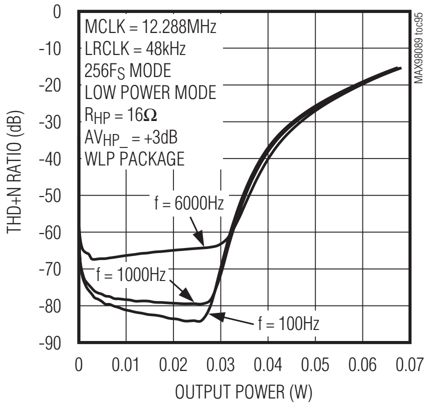
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



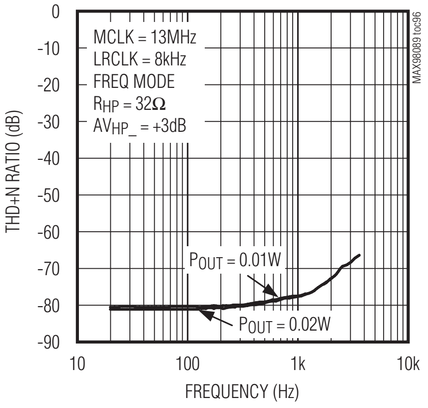
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N\text{-}C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

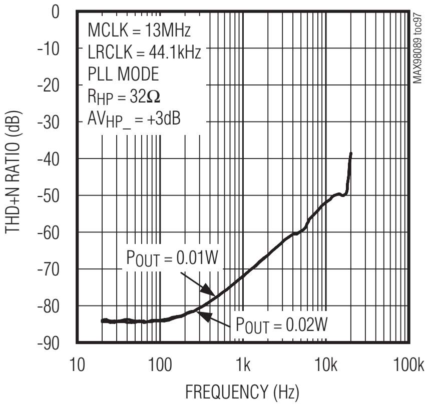
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



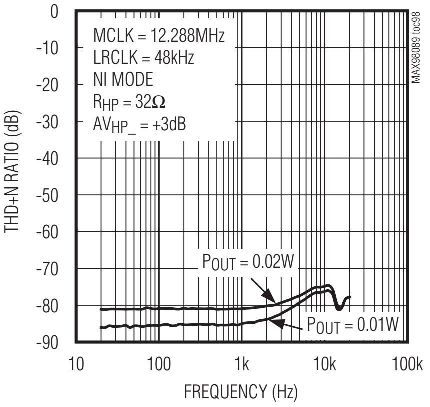
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



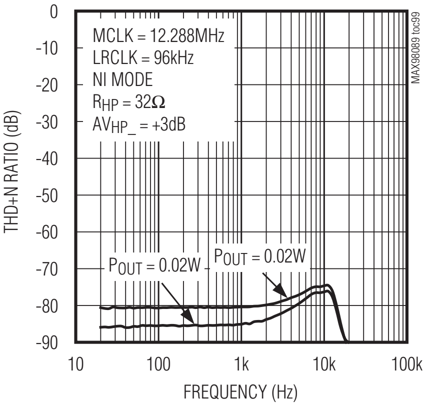
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



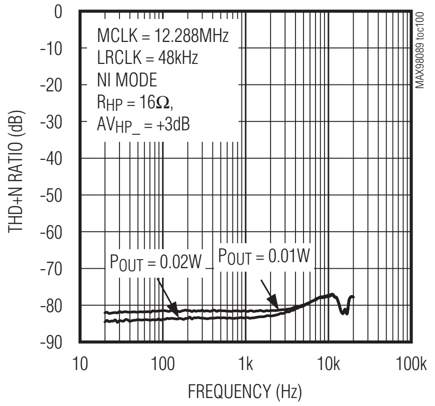
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



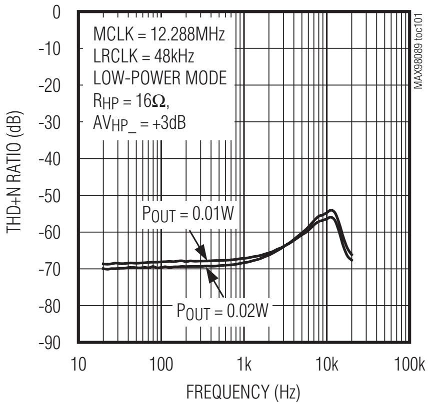
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

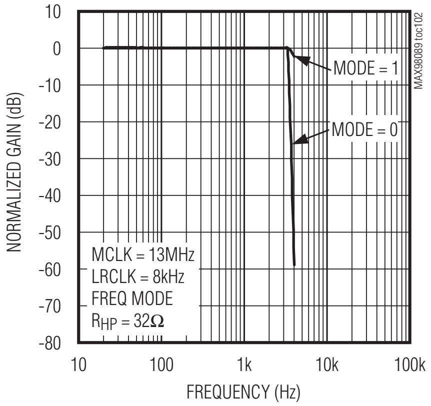
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



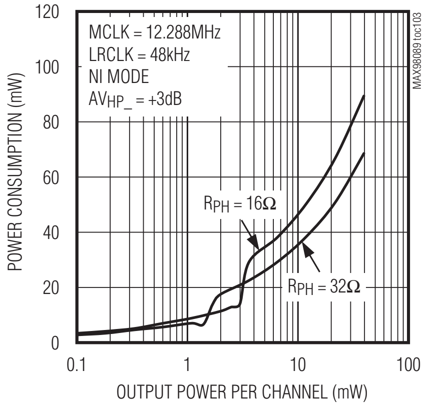
GAIN vs. FREQUENCY (DAC TO HEADPHONE)



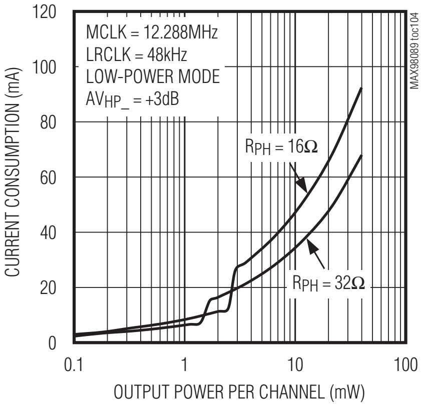
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

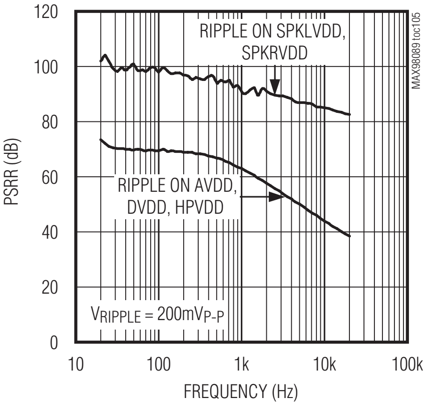
POWER CONSUMPTION vs. OUTPUT POWER (DAC TO HEADPHONE)



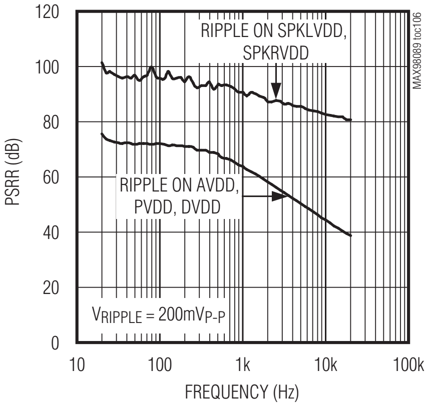
CURRENT CONSUMPTION vs. OUTPUT POWER (DAC TO HEADPHONE)



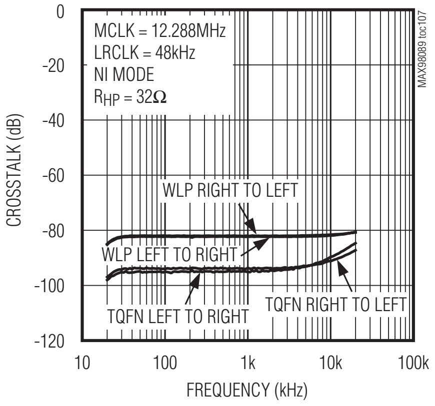
POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (DAC TO HEADPHONE)



POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (DAC TO HEADPHONE)

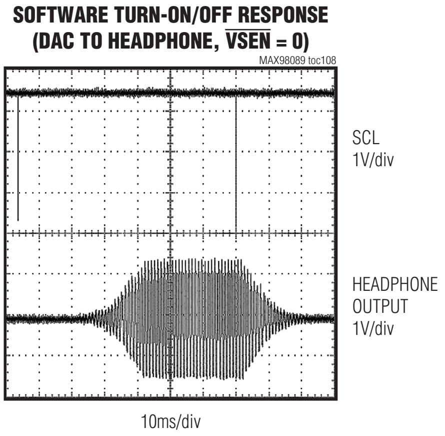


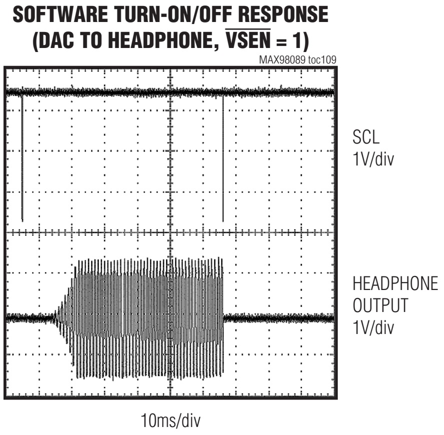
CROSSTALK vs. FREQUENCY (DAC TO HEADPHONE)

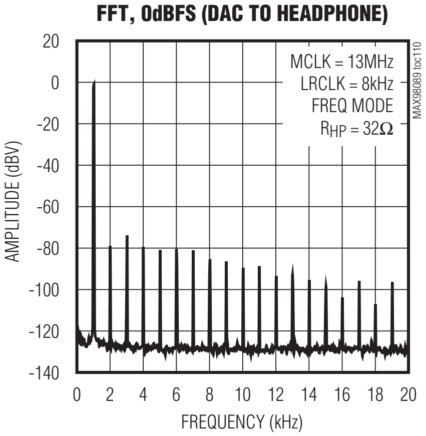


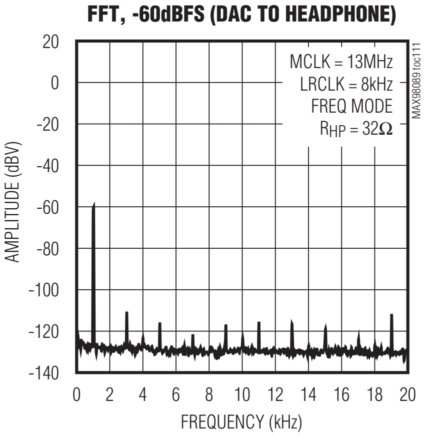
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)



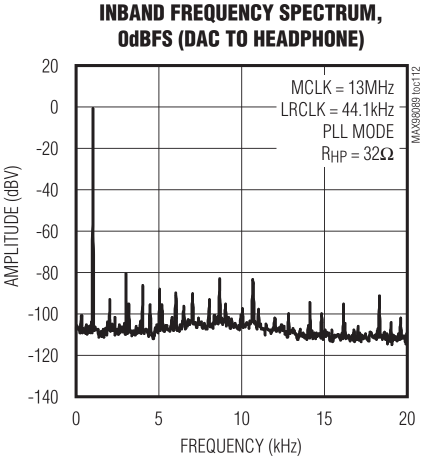


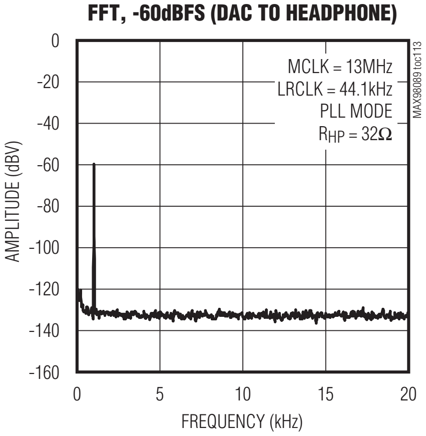


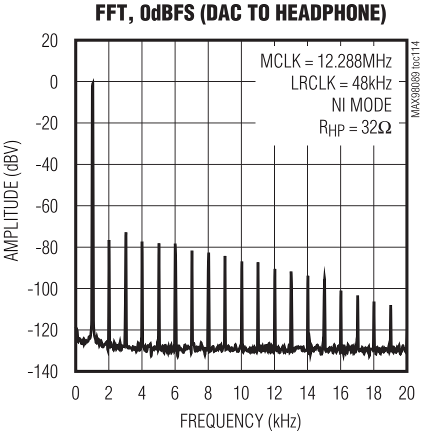


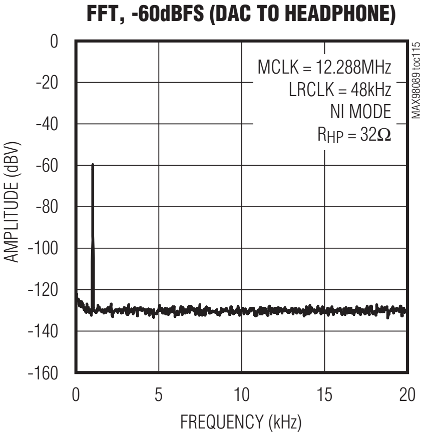
Typical Operating Characteristics (continued)

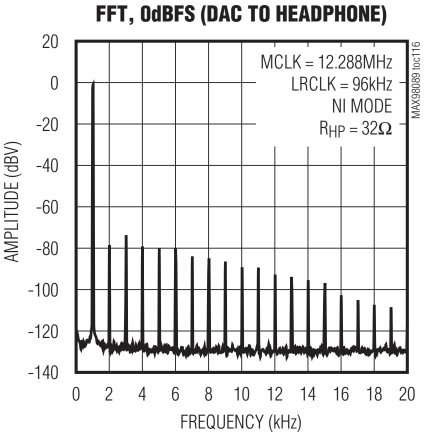
(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)







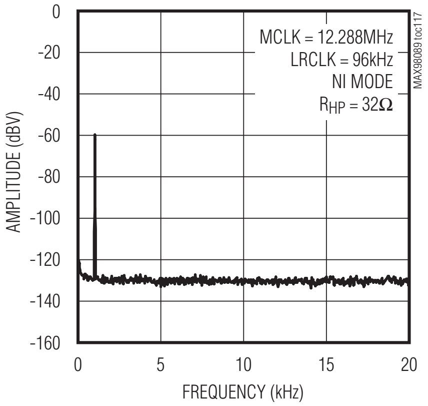




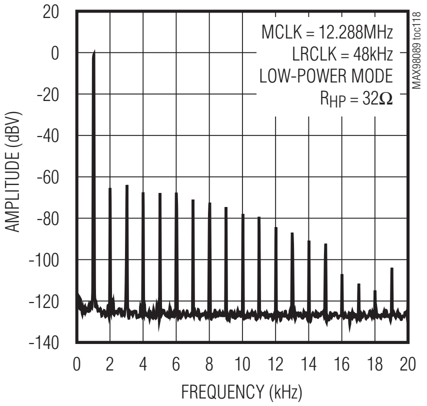
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

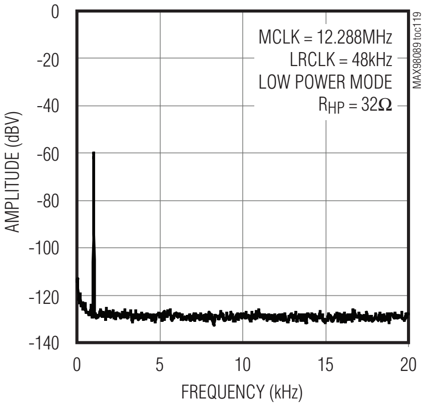
FFT, -60dBFS (DAC TO HEADPHONE)



FFT, 0dBFS (DAC TO HEADPHONE)

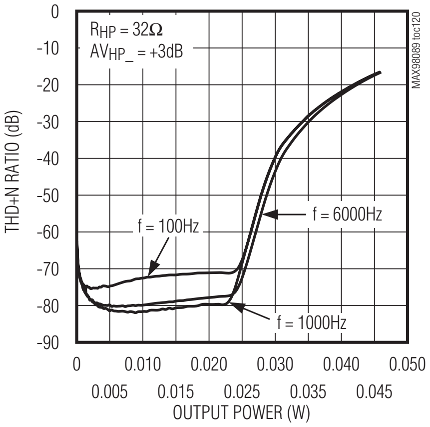


FFT, -60dBFS (DAC TO HEADPHONE)

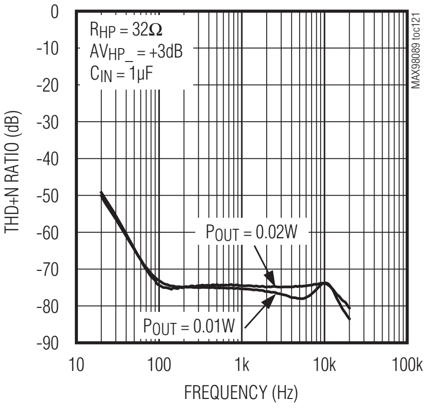


Line to Headphone

TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (LINE TO HEADPHONE)

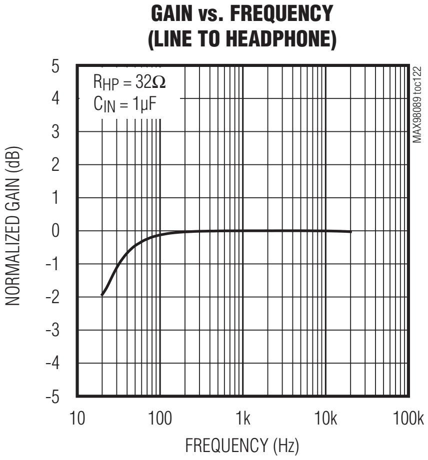


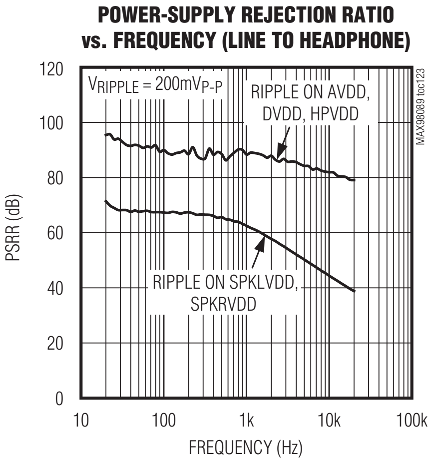
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO HEADPHONE)

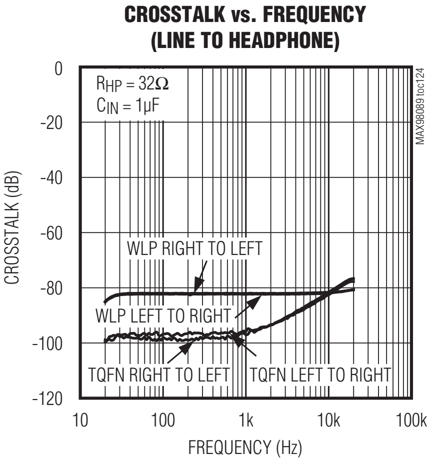


Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)



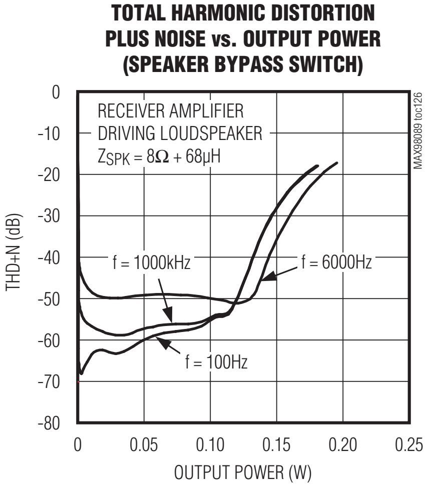


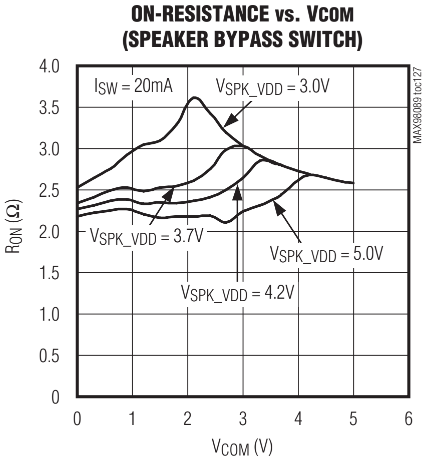


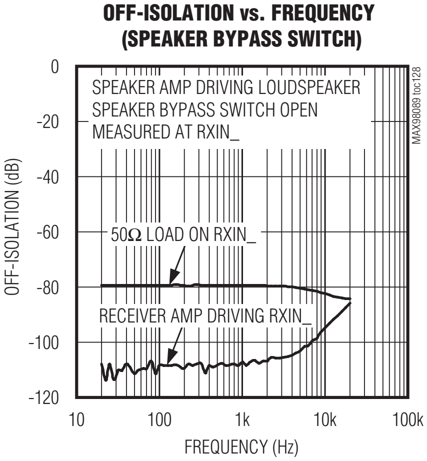
Typical Operating Characteristics (continued)

(V_{AVDD} = V_{PVDD} = V_{DVDD} = V_{DVDDS1} = V_{DVDDS2} = 1.8V, $V_{SPKLVDD}$ = $V_{SPKRVDD}$ = 3.7V. Speaker loads (Z_{SPK}) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out (R_{LOUT}) connected from LOUTL or LOUTR to SPKLGND, C_{REF} = 2.2µF, $C_{MICBIAS}$ = C_{REG} = 1µF, $C_{C1N-C1P}$ = 1µF, C_{HPVDD} = C_{HPVSS} = 1µF. $AV_{MICPRE\_}$ = +20dB, $AV_{MICPGA\_}$ = 0dB, $AV_{DACATTN}$ = 0dB, $AV_{DACGAIN}$ = 0dB, AV_{ADCLVL} = 0dB, $AV_{ADCGAIN}$ = 0dB, $AV_{PGAIN\_}$ = 0dB, $AV_{HP\_}$ = 0dB, AV_{REC} = 0dB, $AV_{SPK\_}$ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.)

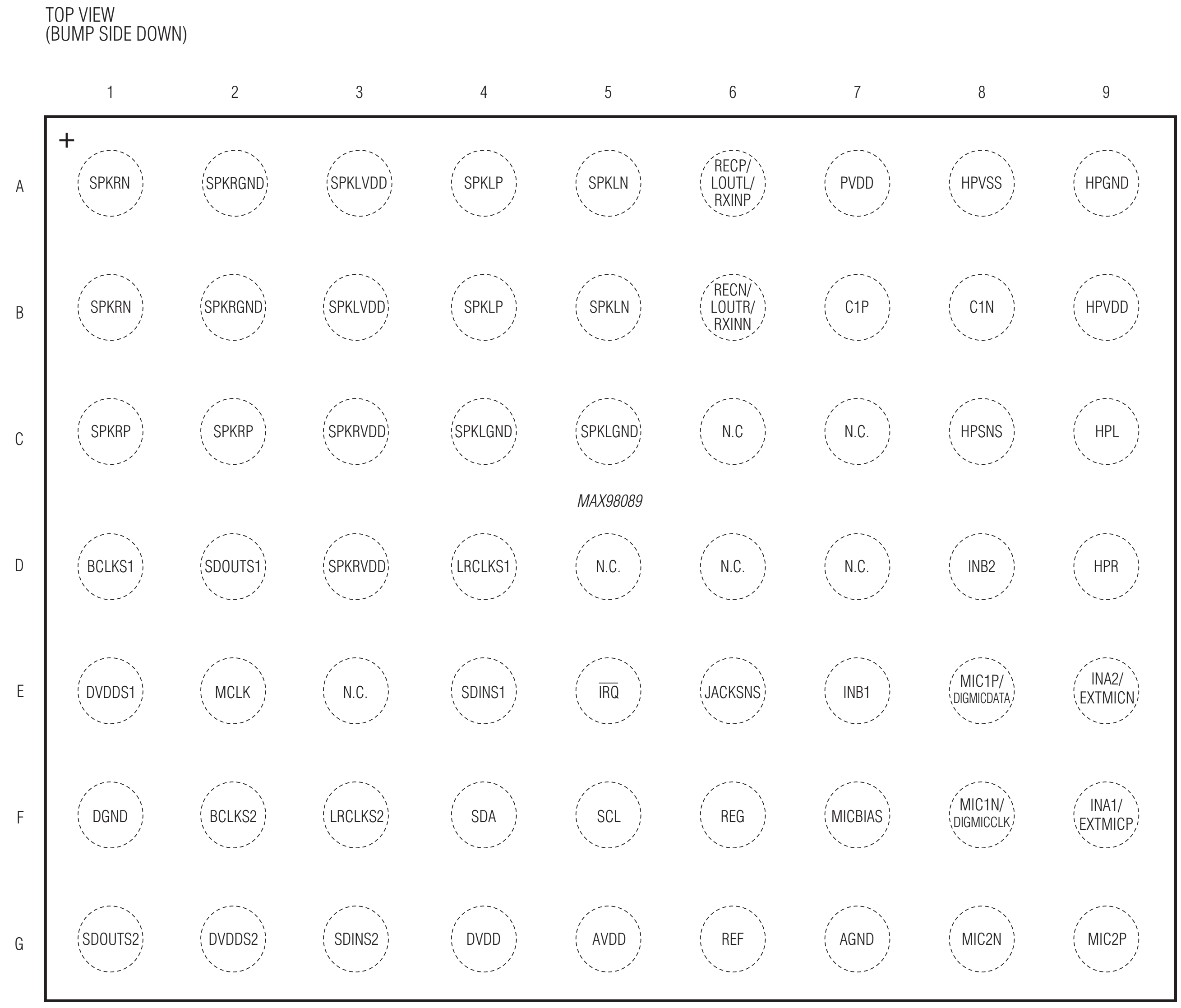
Speaker Bypass Switch





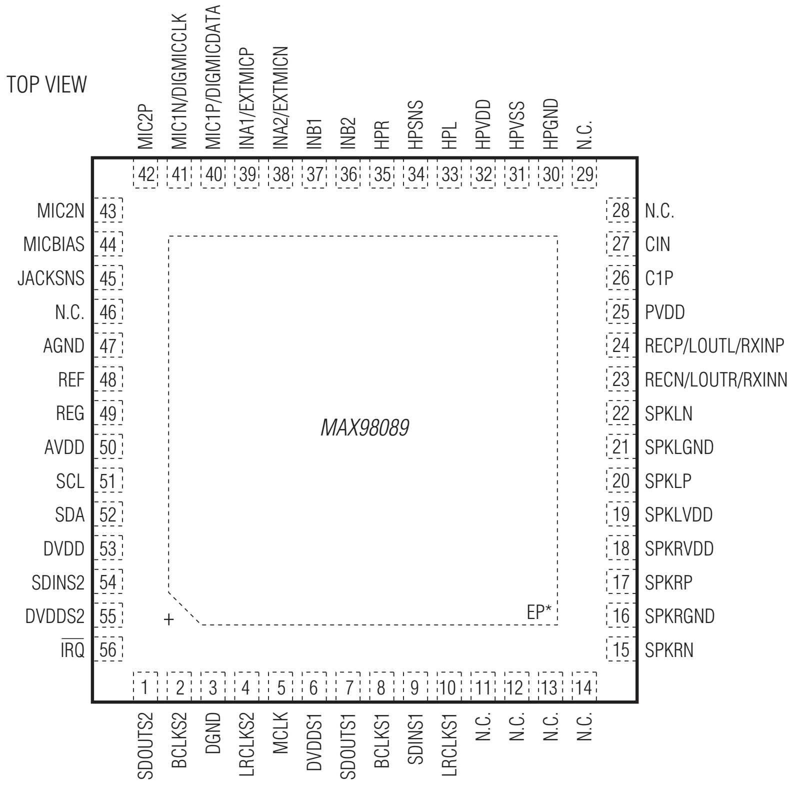


Bump Configuration



	1	2	3	4	5	6	7	8	9
A	SPKRN	SPKRGND	SPKLVDD	SPKLP	SPKLN	RECP/ LOUTL/ RXINP	PVDD	HPVSS	HPGND
B	SPKRN	SPKRGND	SPKLVDD	SPKLP	SPKLN	RECN/ LOUTR/ RXINN	C1P	C1N	HPVDD
C	SPKRP	SPKRP	SPKRVDD	SPKLGND	SPKLGND	N.C	N.C.	HPSNS	HPL
D	BCLKS1	SDOUTS1	SPKRVDD	LRCLKS1	N.C.	N.C.	N.C.	INB2	HPR
E	DVDDS1	MCLK	N.C.	SDINS1	$\overline{\text{IRQ}}$	JACKSNS	INB1	MIC1P/ DIGMICDATA	INA2/ EXTMICN
F	DGND	BCLKS2	LRCLKS2	SDA	SCL	REG	MICBIAS	MIC1N/ DIGMICCLK	INA1/ EXTMICP
G	SDOUTS2	DVDDS2	SDINS2	DVDD	AVDD	REF	AGND	MIC2N	MIC2P

Pin Configuration



TQFN
(7mm x 7mm x 0.75mm)

*EP = EXPOSED PAD. CONNECT TO GROUND PLANE.

Bump/Pin Description

BUMP (WLP)	PIN (TQFN-EP)	NAME	FUNCTION
A1, B1	15	SPKRN	Negative Right-Channel Class D Speaker Output
A2, B2	16	SPKRGND	Right-Speaker Ground
A3, B3	19	SPKLVDD	Left-Speaker, REF, Receiver Amp Power Supply. Bypass to SPKLGND with a 1µF and a 10µF capacitor.
A4, B4	20	SPKLP	Positive Left-Channel Class D Speaker Output
A5, B5	22	SPKLN	Negative Left-Channel Class D Speaker Output
A6	24	RECP/LOUTL/ RXINP	Positive Receiver Amplifier Output or Left Line Output. Can be positive bypass switch input when receiver amp is shut down.
A7	25	PVDD	Headphone Power Supply. Bypass to HPGND with a 1µF and a 10µF capacitor.
A8	31	HPVSS	Inverting Charge-Pump Output. Bypass to HPGND with a 1µF ceramic capacitor.
A9	30	HPGND	Headphone Ground
B6	23	RECN/LOUTR/ RXINN	Negative Receiver Amplifier Output or Right Line Output. Can be negative bypass switch input when receiver amp is shut down.
B7	26	C1P	Charge-Pump Flying Capacitor Positive Terminal. Connect a 1µF ceramic capacitor between C1N and C1P.
B8	27	C1N	Charge-Pump Flying Capacitor Negative Terminal. Connect a 1µF ceramic capacitor between C1N and C1P.
B9	32	HPVDD	Noninverting Charge-Pump Output. Bypass to HPGND with a 1µF ceramic capacitor.
C1, C2	17	SPKRP	Positive Right-Channel Class D Speaker Output
C3, D3	18	SPKRVDD	Right-Speaker Power Supply. Bypass to SPKRGND with a 1µF capacitor.
C4, C5	21	SPKLGND	Left-Speaker Ground
C6, C7, D5, D6, D7, E3	11–14, 28, 29, 46	N.C.	No Connection
C8	34	HPSNS	Headphone Amplifier Ground Sense. Connect to the headphone jack ground terminal for optimal performance or connect to PCB ground.
C9	33	HPL	Left-Channel Headphone Output
D1	8	BCLKS1	S1 Digital Audio Bit Clock Input/Output. BCLKS1 is an input when the IC is in slave mode and an output when in master mode. The input/output voltage is referenced to DVDDS1.
D2	7	SDOUTS1	S1 Digital Audio Serial-Data ADC Output. The output voltage is referenced to DVDDS1.
D4	10	LRCLKS1	S1 Digital Audio Left-Right Clock Input/Output. LRCLKS1 is the audio sample rate clock and determines whether S1 audio data is routed to the left or right channel. In TDM mode, LRCLKS1 is a frame sync pulse. LRCLKS1 is an input when the IC is in slave mode and an output when in master mode.
D8	36	INB2	Single-Ended Line Input B2. Also positive differential line input B.
D9	35	HPR	Right-Channel Headphone Output

Bump/Pin Description (continued)

BUMP (WLP)	PIN (TQFN-EP)	NAME	FUNCTION
E1	6	DVDDS1	S1 Digital Audio Interface Power-Supply Input. Bypass to DGND with a 1µF capacitor.
E2	5	MCLK	Master Clock Input. Acceptable input frequency range is 10MHz to 60MHz.
E4	9	SDINS1	S1 Digital Audio Serial-Data DAC Input. The input/output voltage is referenced to DVDDS1.
E5	56	$\overline{\text{IRQ}}$	Hardware Interrupt Output. $\overline{\text{IRQ}}$ can be programmed to pull low when bits in status register 0x00 change state. Read status register 0x00 to clear $\overline{\text{IRQ}}$ once set. Repeat faults have no effect on $\overline{\text{IRQ}}$ until it is cleared by reading the I^{2}C status register 0x00. Connect a 10kΩ pullup resistor to DVDD for full output swing.
E6	45	JACKSNS	Jack Sense. Detects the insertion and removal of a jack. In typical applications, connect JACKSNS to the MIC pole of the jack. See the *Jack Detection* section.
E7	37	INB1	Single-Ended Line Input B1. Also negative differential line input B.
E8	40	MIC1P/ DIGMICDATA	Positive Differential Microphone 1 Input. AC-couple a microphone with a series 1µF capacitor. Can be retasked as a digital microphone data input.
E9	38	INA2/ EXTMICN	Single-Ended Line Input A2. Also positive differential line input A or negative differential external microphone input.
F1	3	DGND	Digital Ground
F2	2	BCLKS2	S2 Digital Audio Bit Clock Input/Output. BCLKS2 is an input when the IC is in slave mode and an output when in master mode. The input/output voltage is referenced to DVDDS2.
F3	4	LRCLKS2	S2 Digital Audio Left-Right Clock Input/Output. LRCLKS2 is the audio sample rate clock and determines whether audio data on S2 is routed to the left or right channel. In TDM mode, LRCLKS2 is a frame sync pulse. LRCLKS2 is an input when the IC is in slave mode and an output when in master mode. The input/output voltage is referenced to DVDDS2.
F4	52	SDA	I^{2}C Serial-Data Input/Output. Connect a pullup resistor to DVDD for full output swing.
F5	51	SCL	I^{2}C Serial-Clock Input. Connect a pullup resistor to DVDD for full output swing.
F6	49	REG	Common-Mode Voltage Reference. Bypass to AGND with a 1µF capacitor.
F7	44	MICBIAS	Low-Noise Bias Voltage. Outputs a 2.2V microphone bias. An external 2.2kΩ resistor should be placed between MICBIAS and the microphone output.
F8	41	MIC1N/ DIGMICCLK	Negative Differential Microphone 1 Input. AC-couple a microphone with a series 1µF capacitor. Can be retasked as a digital microphone clock output.
F9	39	INA1/ EXTMICP	Single-Ended Line Input A1. Also negative differential line input A or positive differential external microphone input.

Bump/Pin Description (continued)

BUMP (WLP)	PIN (TQFN-EP)	NAME	FUNCTION
G1	1	SDOUTS2	S2 Digital Audio Serial-Data ADC Output. The output voltage is referenced to DVDDS2.
G2	55	DVDDS2	S2 Digital Audio Interface Power-Supply Input. Bypass to DGND with a 1µF capacitor.
G3	54	SDINS2	S2 Digital Audio Serial-Data DAC Input. The input voltage is referenced to DVDDS2.
G4	53	DVDD	Digital Power Supply. Supply for the digital core and I^2C interface. Bypass to DGND with a 1µF capacitor.
G5	50	AVDD	Analog Power Supply. Bypass to AGND with a 1µF capacitor.
G6	48	REF	Converter Reference. Bypass to AGND with a 2.2µF capacitor.
G7	47	AGND	Analog Ground
G8	43	MIC2N	Negative Differential Microphone 2 Input. AC-couple a microphone with a series 1µF capacitor.
G9	42	MIC2P	Positive Differential Microphone 2 Input. AC-couple a microphone with a series 1µF capacitor.
—	—	EP	Exposed Pad (TQFN Only). Connect the exposed pad to the PCB ground plane.

Detailed Description

The MAX98089 is a fully integrated stereo audio codec with FLEXSOUND technology and integrated amplifiers.

Two differential microphone amplifiers can accept signals from three analog inputs. One input can be retasked to support two digital microphones. Any combination of two microphones (analog or digital) can be recorded simultaneously. The analog signals are amplified up to 50dB and recorded by the stereo ADC. The digital record path supports voice filtering with selectable preset highpass filters and high stopband attenuation at $f_S/2$. An automatic gain control (AGC) circuit monitors the digitized signal and automatically adjusts the analog microphone gain to make best use of the ADC's dynamic range. A noise gate attenuates signals below the user-defined threshold to minimize the noise output by the ADC.

The IC includes two analog line inputs. One of the line inputs can be optionally retasked as a third analog microphone input. Both line inputs support either stereo single-ended input signals or mono differential signals. The line inputs are preamplified and then routed to the ADC for recording and/or to the output amplifiers for playback. The single-ended line inputs signals from INA1 and INA2 can bypass the PGAs, and be connected directly to the ADC input to provide the best dynamic range.

Integrated analog switches allow two differential microphone signals to be routed out the third microphone input to an external device. This eliminates the need for an external analog switch in systems that have two devices recording signals from the same microphone.

Through two digital audio interfaces, the device can transmit one stereo audio signal and receive two stereo audio signals in a wide range of formats including I^2S, PCM, and up to four mono slots in TDM. Each interface can be connected to either of two audio ports (S1 and S2) for communication with external devices. Both audio interfaces support 8kHz to 96kHz sample rates. Each input signal is independently equalized using 5-band parametric equalizers. A multiband automatic level control (ALC) boosts signals by up to 12dB. One signal path additionally supports the same voiceband filtering as the ADC path.

The IC includes a stereo Class D speaker amplifier, a high-efficiency Class H stereo headphone amplifier, and a differential receiver amplifier that can be configured as a single-ended stereo line output.

When the receiver amplifier is disabled, analog switches allow RECP/RXINP and RECN/RXINN to be reused for signal routing. In systems where a single transducer is used for both the loudspeaker and receiver, an external receiver amplifier can be routed to the left speaker through RECP/RXINP and RECN/RXINN, bypassing the Class D amplifier. If the internal receiver amplifier is used, then leave RECP/RXINP and RECN/RXINN unconnected. In systems where an external amplifier drives both the receiver and the MAX98089's line input, one of the differential signals can be disconnected from the receiver when not needed by passing it through the analog switch that connects RECP/RXINP to RECN/RXINN.

The stereo Class D amplifier provides efficient amplification for two speakers. The amplifier includes active emissions limiting to minimize the radiated emissions (EMI) traditionally associated with Class D. In most systems, no output filtering is required to meet standard EMI limits.

To optimize speaker sound quality, the IC includes an excursion limiter, a distortion limiter, and a power limiter. The excursion limiter is a dynamic highpass filter with variable corner frequency that increases in response to high signal levels. Low-frequency energy typically causes more distortion than useful sound at high signal levels, so attenuating low frequencies allows the speaker to play louder without distortion or damage. At lower signal levels, the filter corner frequency reduces to pass more low frequency energy when the speaker can handle it. The distortion limiter reduces the volume when the output signal exceeds a preset distortion level. This ensures that regardless of input signal and battery voltage, excessive distortion is never heard by the user. The power limiter monitors the continuous power into the loudspeaker and lowers the signal level if the speaker is at risk of overheating.

The stereo Class H headphone amplifier uses a dual-mode charge pump to maximize efficiency while outputting a ground-referenced signal. This eliminates the need for DC-blocking capacitors or a midrail bias for the headphone jack ground return. Ground sense reduces output noise caused by ground return current.

The IC integrates jack detection allowing the detection of insertion and removal of accessories as well as button presses.

I²C Slave Address

Configure the MAX98089 using the I²C control bus. The IC uses a slave address of 0x20 or 00100000 for write operations and 0x21 or 00100001 for read operations. See the *I²C Serial Interface* section for a complete interface description.

Registers

Table 1 lists all of the registers, their addresses, and power-on-reset states. Registers 0x00 to 0x03 and 0xFF are read-only while all of the other registers are read/write. Write zeros to all unused bits in the register table when updating the register, unless otherwise noted.

Table 1. Register Map

<table>
<tr><th>REGISTER</th><th>B7</th><th>B6</th><th>B5</th><th>B4</th><th>B3</th><th>B2</th><th>B1</th><th>B0</th><th>ADDRESS</th><th>DEFAULT</th><th>R/W</th><th>PAGE</th></tr>
<tr><td colspan="13">STATUS</td></tr>
<tr><td>Status</td><td>CLD</td><td>SLD</td><td>ULK</td><td>—</td><td>—</td><td>—</td><td>JDET</td><td>—</td><td>0x00</td><td>—</td><td>R</td><td>117</td></tr>
<tr><td>Microphone AGC/NG</td><td colspan="3">NG</td><td colspan="5">AGC</td><td>0x01</td><td>—</td><td>R</td><td>74</td></tr>
<tr><td>Jack Status</td><td colspan="2">JKSNS</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>0x02</td><td>—</td><td>R</td><td>115</td></tr>
<tr><td>Battery Voltage</td><td>—</td><td>—</td><td>—</td><td colspan="5">VBAT</td><td>0x03</td><td>—</td><td>R/W</td><td>116</td></tr>
<tr><td>Interrupt Enable</td><td>ICLD</td><td>ISLD</td><td>IULK</td><td>0</td><td>0</td><td>0</td><td>IJDET</td><td>0</td><td>0x0F</td><td>0x00</td><td>R/W</td><td>117</td></tr>
<tr><td colspan="13">MASTER CLOCK CONTROL</td></tr>
<tr><td>Master Clock</td><td>0</td><td>0</td><td colspan="2">PSCLK</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0x10</td><td>0x00</td><td>R/W</td><td>85</td></tr>
<tr><td colspan="13">DAI1 CLOCK CONTROL</td></tr>
<tr><td>Clock Mode</td><td colspan="4">SR1</td><td colspan="4">FREQ1</td><td>0x11</td><td>0x00</td><td>R/W</td><td>85, 86</td></tr>
<tr><td rowspan="2">Any Clock Control</td><td>PLL1</td><td colspan="7">NI1[14:8]</td><td>0x12</td><td>0x00</td><td>R/W</td><td>86</td></tr>
<tr><td colspan="7">NI1[7:1]</td><td>NI1[0]</td><td>0x13</td><td>0x00</td><td>R/W</td><td>86</td></tr>
<tr><td colspan="13">DAI1 CONFIGURATION</td></tr>
<tr><td>Format</td><td>MAS1</td><td>WCI1</td><td>BCI1</td><td>DLY1</td><td>0</td><td>TDM1</td><td>FSW1</td><td>WS1</td><td>0x14</td><td>0x00</td><td>R/W</td><td>80</td></tr>
<tr><td>Clock</td><td colspan="2">ADC_OSR1</td><td>DAC_OSR1</td><td>0</td><td>0</td><td colspan="3">BSEL1</td><td>0x15</td><td>0x00</td><td>R/W</td><td>81</td></tr>
<tr><td>I/O Configuration</td><td colspan="2">SEL1</td><td>LTEN1</td><td>LBEN1</td><td>DMONO1</td><td>HIZOFF1</td><td>SDOEN1</td><td>SDIEN1</td><td>0x16</td><td>0x00</td><td>R/W</td><td>81, 82</td></tr>
<tr><td>Time-Division Multiplex</td><td colspan="2">SLOTL1</td><td colspan="2">SLOTR1</td><td colspan="4">SLOTDLY1</td><td>0x17</td><td>0x00</td><td>R/W</td><td>82</td></tr>
<tr><td>Filters</td><td>MODE1</td><td colspan="3">AVFLT1</td><td>DHF1</td><td colspan="3">DVFLT1</td><td>0x18</td><td>0x00</td><td>R/W</td><td>90</td></tr>
<tr><td colspan="13">DAI2 CLOCK CONTROL</td></tr>
<tr><td>Clock Mode</td><td colspan="4">SR2</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0x19</td><td>0x00</td><td>R/W</td><td>85</td></tr>
<tr><td rowspan="2">Any Clock Control</td><td>PLL2</td><td colspan="7">NI2[14:8]</td><td>0x1A</td><td>0x00</td><td>R/W</td><td>86</td></tr>
<tr><td colspan="7">NI2[7:1]</td><td>NI2[0]</td><td>0x1B</td><td>0x00</td><td>R/W</td><td>86</td></tr>
<tr><td colspan="13">DAI2 CONFIGURATION</td></tr>
<tr><td>Format</td><td>MAS2</td><td>WCI2</td><td>BCI2</td><td>DLY2</td><td>0</td><td>TDM2</td><td>FSW2</td><td>WS2</td><td>0x1C</td><td>0x00</td><td>R/W</td><td>80</td></tr>
<tr><td>Clock</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td colspan="3">BSEL2</td><td>0x1D</td><td>0x00</td><td>R/W</td><td>81</td></tr>
<tr><td>I/O Configuration</td><td colspan="2">SEL2</td><td>0</td><td>LBEN2</td><td>DMONO2</td><td>HIZOFF2</td><td>SDOEN2</td><td>SDIEN2</td><td>0x1E</td><td>0x00</td><td>R/W</td><td>81, 82</td></tr>
</table>

Table 1. Register Map (continued)

REGISTER	B7	B6	B5	B4	B3	B2	B1	B0	ADDRESS	DEFAULT	R/W	PAGE
Time-Division Multiplex	SLOTL2		SLOTR2		SLOTDLY2				0x1F	0x00	R/W	82
Filters	0	0	0	0	DHF2	0	0	DCB2	0x20	0x00	R/W	96
SRC												
Sample Rate Converter	0	0	0	SRMIX_MODE	SRMIX_ENL	SRMIX_ENR	SRC_ENL	SRC_ENR	0x21	0x00	R/W	89
MIXERS												
DAC Mixer	MIXDAL				MIXDAR				0x22	0x00	R/W	96
Left ADC Mixer	MIXADL								0x23	0x00	R/W	73
Right ADC Mixer	MIXADR								0x24	0x00	R/W	73
Left Headphone Amplifier Mixer	MIXHPL								0x25	0x00	R/W	110
Right Headphone Amplifier Mixer	MIXHPR								0x26	0x00	R/W	110
Headphone Amplifier Mixer Control	0	0	MIXHPR_PATHSEL	MIXHPL_PATHSEL	MIXHPR_GAIN		MIXHPL_GAIN		0x27	0x00	R/W	110
Left Receiver Amplifier Mixer	MIXRECL								0x28	0x00	R/W	98
Right Receiver Amplifier Mixer	MIXRECR								0x29	0x00	R/W	98
Receiver Amplifier Mixer Control	LINE_MODE	0	0	0	MIXRECR_GAIN		MIXRECL_GAIN		0x2A	0x00	R/W	98
Left Speaker Amplifier Mixer	MIXSPL								0x2B	0x00	R/W	101
Right Speaker Amplifier Mixer	MIXSPR								0x2C	0x00	R/W	101
Speaker Amplifier Mixer Control	0	0	0	0	MIXSPR_GAIN		MIXSPL_GAIN		0x2D	0x00	R/W	101

Table 1. Register Map (continued)

REGISTER	B7	B6	B5	B4	B3	B2	B1	B0	ADDRESS	DEFAULT	R/W	PAGE
LEVEL CONTROL												
Sidetone	DSTS		0	DVST					0x2E	0x00	R/W	78
DAI1 Playback Level	DV1M	0	DV1G		DV1				0x2F	0x00	R/W	95
DAI1 Playback Level	0	0	0	$\overline{\text{EQCLP1}}$	DVEQ1				0x30	0x00	R/W	94
DAI2 Playback Level	DV2M	0	0	0	DV2				0x31	0x00	R/W	95
DAI2 Playback Level	0	0	0	$\overline{\text{EQCLP2}}$	DVEQ2				0x32	0x00	R/W	94
Left ADC Level	0	0	AVLG		AVL				0x33	0x00	R/W	77
Right ADC Level	0	0	AVRG		AVR				0x34	0x00	R/W	77
Microphone 1 Input Level	0	PA1EN		PGAM1					0x35	0x00	R/W	70
Microphone 2 Input Level	0	PA2EN		PGAM2					0x36	0x00	R/W	70
INA Input Level	0	INAEXT	0	0	0	PGAINA			0x37	0x00	R/W	72
INB Input Level	0	INBEXT	0	0	0	PGAINB			0x38	0x00	R/W	72
Left Headphone Amplifier Volume Control	HPLM	0	0	HPVOLL					0x39	0x00	R/W	111
Right Headphone Amplifier Volume Control	HPRM	0	0	HPVOLR					0x3A	0x00	R/W	111
Left Receiver Amplifier Volume Control	RECLM	0	0	RECVOLL					0x3B	0x00	R/W	99
Right Receiver Amplifier Volume Control	RECRM	0	0	RECVOLR					0x3C	0x00	R/W	99

Table 1. Register Map (continued)

REGISTER	B7	B6	B5	B4	B3	B2	B1	B0	ADDRESS	DEFAULT	R/W	PAGE
Left Speaker Amplifier Volume Control	SPLM	0	0	SPVOLL					0x3D	0x00	R/W	102
Right Speaker Amplifier Volume Control	SPRM	0	0	SPVOLR					0x3E	0x00	R/W	102
MICROPHONE AGC												
Configuration	AGCSRC	AGCRLS			AGCATK		AGCHLD		0x3F	0x00	R/W	74, 75
Threshold	ANTH				AGCTH				0x40	0x00	R/W	75
SPEAKER SIGNAL PROCESSING												
Excursion Limiter Filter	0	DHPUCF			0	0	DHPLCF		0x41	0x00	R/W	104
Excursion Limiter Threshold	0	0	0	0	0	DHPTH			0x42	0x00	R/W	104
ALC	ALCEN	ALCRLS			ALCMB	ALCTH			0x43	0x00	R/W	93, 104
Power Limiter	PWRTH				0	PWRK			0x44	0x00	R/W	105
Power Limiter	PWRT2				PWRT1				0x45	0x00	R/W	106
Distortion Limiter	THDCLP				0	0	0	THDT1	0x46	0x00	R/W	107
CONFIGURATION												
Audio Input	INADIFF	INBDIFF	0	0	0	0	0	0	0x47	0x00	R/W	72
Microphone	MICCLK		DIGMICL	DIGMICR	0	0	EXTMIC		0x48	0x00	R/W	70
Level Control	$\overline{\text{VS2EN}}$	$\overline{\text{VSEN}}$	$\overline{\text{ZDEN}}$	0	0	0	EQ2EN	EQ1EN	0x49	0x00	R/W	94, 113
Bypass Switches	INABYP	0	0	MIC2BYP	0	0	RECBYP	SPKBYP	0x4A	0x00	R/W	71, 112
Jack Detection	JDETEN	0	0	0	0	0	JDEB		0x4B	0x00	R/W	115
POWER MANAGEMENT												
Input Enable	INAEN	INBEN	0	0	MBEN	0	ADLEN	ADREN	0x4C	0x00	R/W	67
Output Enable	HPLEN	HPREN	SPLEN	SPREN	RECLEN	RECREN	DALEN	DAREN	0x4D	0x00	R/W	68
Top-Level Bias Control	BGEN	SPREGEN	VCMEN	BIASEN	0	0	0	JDWK	0x4E	0xF0	R/W	68
DAC Low Power Mode 1	DAI2_DAC_LP				DAI1_DAC_LP				0x4F	0x00	R/W	87
DAC Low Power Mode 2	0	0	0	0	DAC2_IP_DITH_EN	DAC1_IP_DITH_EN	CGM2_EN	CGM1_EN	0x50	0x0F	R/W	87
System Shutdown	$\overline{\text{SHDN}}$	VBATEN	0	0	PERFMODE	HPPLYBACK	PWRSV8K	PWRSV	0x51	0x00	R/W	67, 116

Table 1. Register Map (continued)

REGISTER	B7	B6	B5	B4	B3	B2	B1	B0	ADDRESS	DEFAULT	R/W	PAGE
DSP COEFFICIENTS												
EQ Band 1 (DAI1/DAI2)	K_1[15:8]								0x52/0x84	0xXX	R/W	93
	K_1[7:0]								0x53/0x85	0xXX	R/W	93
	K1_1[15:8]								0x54/0x86	0xXX	R/W	93
	K1_1[7:0]								0x55/0x87	0xXX	R/W	93
	K2_1[15:8]								0x56/0x88	0xXX	R/W	93
	K2_1[7:0]								0x57/0x89	0xXX	R/W	93
	c1_1[15:8]								0x58/0x8A	0xXX	R/W	93
	c1_1[7:0]								0x59/0x8B	0xXX	R/W	93
	c2_1[15:8]								0x5A/0x8C	0xXX	R/W	93
	c2_1[7:0]								0x5B/0x8D	0xXX	R/W	93
EQ Band 2 (DAI1/DAI2)	K_2[15:8]								0x5C/0x8E	0xXX	R/W	93
	K_2[7:0]								0x5D/0x8F	0xXX	R/W	93
	K1_2[15:8]								0x5E/0x90	0xXX	R/W	93
	K1_2[7:0]								0x5F/0x91	0xXX	R/W	93
	K2_2[15:8]								0x60/0x92	0xXX	R/W	93
	K2_2[7:0]								0x61/0x93	0xXX	R/W	93
	c1_2[15:8]								0x62/0x94	0xXX	R/W	93
	c1_2[7:0]								0x63/0x95	0xXX	R/W	93
	c2_2[15:8]								0x64/0x96	0xXX	R/W	93
	c2_2[7:0]								0x65/0x97	0xXX	R/W	93
EQ Band 3 (DAI1/DAI2)	K_3[15:8]								0x66/0x98	0xXX	R/W	93
	K_3[7:0]								0x67/0x99	0xXX	R/W	93
	K1_3[15:8]								0x68/0x9A	0xXX	R/W	93
	K1_3[7:0]								0x69/0x9B	0xXX	R/W	93
	K2_3[15:8]								0x6A/0x9C	0xXX	R/W	93
	K2_3[7:0]								0x6B/0x9D	0xXX	R/W	93
	c1_3[15:8]								0x6C/0x9E	0xXX	R/W	93
	c1_3[7:0]								0x6D/0x9F	0xXX	R/W	93
	c2_3[15:8]								0x6E/0xAE	0xXX	R/W	93
	c2_3[7:0]								0x6F/0xA1	0xXX	R/W	93
EQ Band 4 (DAI1/DAI2)	K_4[15:8]								0x70/0xA2	0xXX	R/W	93
	K_4[7:0]								0x71/0xA3	0xXX	R/W	93
	K1_4[15:8]								0x72/0xA4	0xXX	R/W	93
	K1_4[7:0]								0x73/0xA5	0xXX	R/W	93
	K2_4[15:8]								0x74/0xA6	0xXX	R/W	93
	K2_4[7:0]								0x75/0xA7	0xXX	R/W	93
	c1_4[15:8]								0x76/0xA8	0xXX	R/W	93
	c1_4[7:0]								0x77/0xA9	0xXX	R/W	93
	c2_4[15:8]								0x78/0xAA	0xXX	R/W	93
	c2_4[7:0]								0x79/0xAB	0xXX	R/W	93

Table 1. Register Map (continued)

REGISTER	B7	B6	B5	B4	B3	B2	B1	B0	ADDRESS	DEFAULT	R/W	PAGE
EQ Band 5 (DAI1/DAI2)	K_5[15:8]								0x7A/0xAC	0xXX	R/W	93
	K_5[7:0]								0x7B/0xAD	0xXX	R/W	93
	K1_5[15:8]								0x7C/0xAE	0xXX	R/W	93
	K1_5[7:0]								0x7D/0xAF	0xXX	R/W	93
	K2_5[15:8]								0x7E/0xB0	0xXX	R/W	93
	K2_5[7:0]								0x7F/0xB1	0xXX	R/W	93
	c1_5[15:8]								0x80/0xB2	0xXX	R/W	93
	c1_5[7:0]								0x81/0xB3	0xXX	R/W	93
	c2_5[15:8]								0x82/0xB4	0xXX	R/W	93
	c2_5[7:0]								0x83/0xB5	0xXX	R/W	93
Excursion Limiter Biquad (DAI1/DAI2)	a1[15:8]								0xB6/0xC0	0xXX	R/W	93
	a1[7:0]								0xB7/0xC1	0xXX	R/W	93
	a2[15:8]								0xB8/0xC2	0xXX	R/W	93
	a2[7:0]								0xB9/0xC3	0xXX	R/W	93
	b0[15:8]								0xBA/0xC4	0xXX	R/W	93
	b0[7:0]								0xBB/0xC5	0xXX	R/W	93
	b1[15:8]								0xBC/0xC6	0xXX	R/W	93
	b1[7:0]								0xBD/0xC7	0xXX	R/W	93
	b2[15:8]								0xBE/0xC8	0xXX	R/W	93
	b2[7:0]								0xBF/0xC9	0xXX	R/W	93
REVISION ID												
Rev ID	REV								0xFF	0x40	R	118

Power Management

The IC includes comprehensive power management to allow the disabling of all unused circuits, minimizing supply current.

Table 2. Power Management Registers

REGISTER	BIT	NAME	DESCRIPTION
0x51	7	$\overline{\text{SHDN}}$	**Global Shutdown.** Disables everything except the headset detection circuitry, which is controlled separately. 0 = Device Shutdown 1 = Device Enabled
	6	VBATEN	See the *Battery Measurement* section.
	3	PERFMODE	**Performance Mode.** Selects DAC to headphone playback performance mode. 0 = High performance playback mode. 1 = Low power playback mode.
	2	HPPLYBCK	**Headphone Only Playback Mode.** Configures System Bias Control register bits for low power playback when using DAC to headphone playback path only. When enabled, this bit overrides the System Bias Control register settings. When disabled, the System Bias Control register is used to enable system bias blocks. Set both HPPLYBCK and PERFMODE for lowest power consumption when using DAC to headphone playback path only. 0 = Disabled 1 = Enabled
	1	PWRSV8K	**8kHz Power Save Mode.** PWRSV8K configures the ADC for reduced power consumption when f_S = 8kHz. PWRSV8K can be used in conjunction with PWRSV when f_S = 8kHz for more power savings. 0 = Normal, high-performance mode. 1 = Low power mode.
	0	PWRSV	**Power Save Mode.** PWRSV configures the ADC for reduced power consumption for all sample rates. PWRSV can be used in conjunction with PWRSV8K for more power savings. 0 = Normal, high-performance mode. 1 = Low-power mode.
0x4C	7	INAEN	**Line Input A Enable** 0 = Disabled 1 = Enabled
	6	INBEN	**Line Input B Enable** 0 = Disabled 1 = Enabled
	3	MBEN	**Microphone Bias Enable** 0 = Disabled 1 = Enabled
	1	ADLEN	**Left ADC Enable** 0 = Disabled 1 = Enabled
	0	ADREN	**Right ADC Enable** 0 = Disabled 1 = Enabled

Table 2. Power Management Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
0x4D	7	HPLEN	**Left Headphone Enable** 0 = Disabled 1 = Enabled
	6	HPREN	**Right Headphone Enable** 0 = Disabled 1 = Enabled
	5	SPLEN	**Left Speaker Enable** 0 = Disabled 1 = Enabled
	4	SPREN	**Right Speaker Enable** 0 = Disabled 1 = Enabled
	3	RECLEN	**Receiver/Left Line Output Enable.** Use this bit to enable the differential receiver output or left line output. 0 = Disabled 1 = Enabled
	2	RECREN	**Right Line Output Enable.** Use this bit to enable the right line output. 0 = Disabled 1 = Enabled
	1	DALEN	**Left DAC Enable** 0 = Disabled 1 = Enabled
	0	DAREN	**Right DAC Enable** 0 = Disabled 1 = Enabled
0x4E	7	BGEN	**Bandgap Enable.** Must be enabled for proper operation of the 2.5V regulator and associated circuitry. 0 = Disabled 1 = Enabled
	6	SPREGEN	**2.5V Regulator Enable.** SPREGEN enables a 2.5V internal regulator required for the ADC, speaker and receiver/line out amplifier. The 2.5V regulator is powered by SPKLVDD. 0 = Disabled 1 = Enabled
	5	VCMEN	**Common-Mode Voltage Resistor String Enable.** VCMEN enables the common mode voltage for the input and output amplifiers in the codec. 0 = Disabled 1 = Enabled
	4	BIASEN	**Chip Bias Enable.** BIASEN needs to be set for the codec amplifiers to be enabled. 0 = Disabled 1 = Enabled
	0	JDWK	See the *Jack Detection* section.

Microphone Inputs

The device includes three differential microphone inputs and a low-noise microphone bias for powering the microphones (Figure 6). One microphone input can also be configured as a digital microphone input accepting signals from up to two digital microphones. Any two microphones, analog or digital, can be recorded simultaneously.

In the typical application, one microphone input is used for the handset microphone and the other is used as an accessory microphone. In systems using a background noise microphone, INA can be retasked as another microphone input.

In systems where the codec is not the only device recording microphone signals, connect microphones to MIC2P/MIC2N and EXTMICP/EXTMICN. MIC1P/MIC1N then become outputs that route the microphone signals to an external device as needed. Two devices can then record microphone signals without needing external analog switches.

Analog microphone signals are amplified by two stages of gain and then routed to the ADCs. The first stage offers selectable 0dB, 20dB, or 30dB settings. The second stage is a programmable-gain amplifier (PGA) adjustable from 0dB to 20dB in 1dB steps. To maximize the signal-to-noise ratio, use the gain in the first stage whenever possible. Zero-crossing detection is included on the PGA to minimize zipper noise while making gain changes.

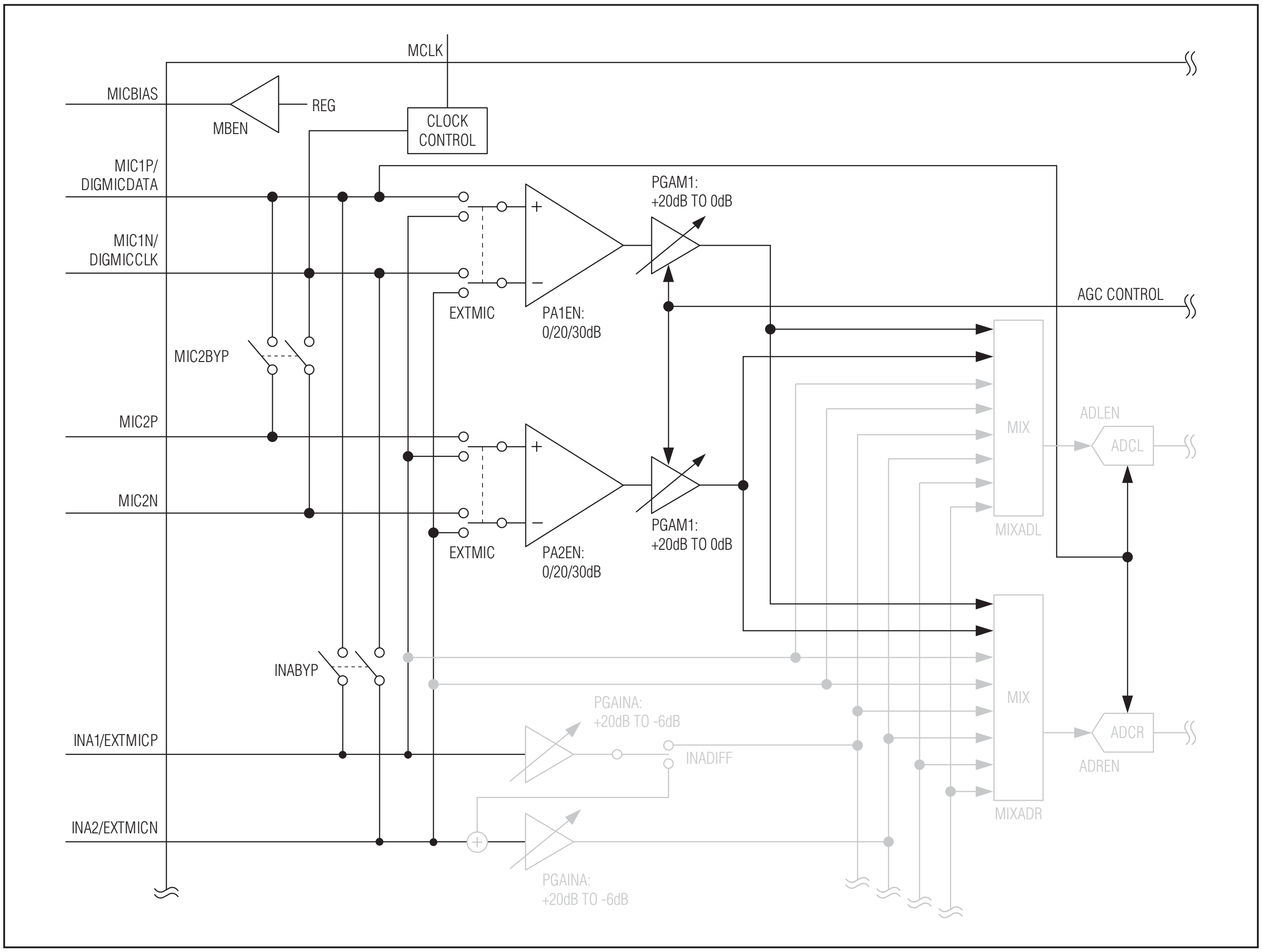


Figure 6. Microphone Input Block Diagram

Table 3. Microphone Input Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th>DESCRIPTION</th></tr>
<tr><td rowspan="7">0x35/0x36</td><td>6</td><td rowspan="2">PA1EN/PA2EN</td><td rowspan="2">MIC1/MIC2 Preamplifier Gain
Course microphone gain adjustment.
00 = Preamplifier disabled
01 = 0dB
10 = 20dB
11 = 30dB</td></tr>
<tr><td>5</td></tr>
<tr><td>4</td><td rowspan="5">PGAM1/PGAM2</td><td rowspan="5">MIC1/MIC2 PGA
Fine microphone gain adjustment.
<table>
<tr><th>VALUE</th><th>GAIN (dB)</th><th>VALUE</th><th>GAIN (dB)</th></tr>
<tr><td>0x00</td><td>+20</td><td>0x0B</td><td>+9</td></tr>
<tr><td>0x01</td><td>+19</td><td>0x0C</td><td>+8</td></tr>
<tr><td>0x02</td><td>+18</td><td>0x0D</td><td>+7</td></tr>
<tr><td>0x03</td><td>+17</td><td>0x0E</td><td>+6</td></tr>
<tr><td>0x04</td><td>+16</td><td>0x0F</td><td>+5</td></tr>
<tr><td>0x05</td><td>+15</td><td>0x10</td><td>+4</td></tr>
<tr><td>0x06</td><td>+14</td><td>0x11</td><td>+3</td></tr>
<tr><td>0x07</td><td>+13</td><td>0x12</td><td>+2</td></tr>
<tr><td>0x08</td><td>+12</td><td>0x13</td><td>+1</td></tr>
<tr><td>0x09</td><td>+11</td><td>0x14 to 0x1F</td><td>0</td></tr>
<tr><td>0x0A</td><td>+10</td><td></td><td></td></tr>
</table></td></tr>
<tr><td>3</td></tr>
<tr><td>2</td></tr>
<tr><td>1</td></tr>
<tr><td>0</td></tr>
<tr><td rowspan="6">0x48</td><td>7</td><td rowspan="2">MICCLK</td><td rowspan="2">Digital Microphone Clock Frequency
Select a frequency that is within the digital microphone’s clock frequency range. Set OSR1 = 1 when using a digital microphone.
00 = PCLK/8
01 = PCLK/6
10 = 64 x LRCLK
11 = Reserved</td></tr>
<tr><td>6</td></tr>
<tr><td>5</td><td>DIGMICL</td><td>Left Digital Microphone Enable
Set PA1EN = 00 for proper operation.
0 = Disabled
1 = Enabled</td></tr>
<tr><td>4</td><td>DIGMICR</td><td>Right Digital Microphone Enable
Set PA1EN = 00 for proper operation.
0 = Disabled
1 = Enabled</td></tr>
<tr><td>1</td><td rowspan="2">EXTMIC</td><td rowspan="2">External Microphone Connection
Routes INA_/EXTMIC_ to the microphone preamplifiers. Set INAEN = 0 when using INA_/EXTMIC_ as a microphone input.
00 = Disabled
01 = MIC1 input
10 = MIC2 input
11 = Reserved</td></tr>
<tr><td>0</td></tr>
</table>

Table 3. Microphone Input Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
0x4A	7	INABYP	**INA_/EXTMIC_ to MIC1_ Bypass Switch** 0 = Disabled 1 = Enabled
	4	MIC2BYP	**MIC1_ to MIC2_ Bypass Switch** 0 = Disabled 1 = Enabled
	1	RECBYP	See the *Output Bypass Switches* section.
	0	SPKBYP	

Line Inputs

The device includes two sets of line inputs (Figure 7). Each set can be configured as a stereo single-ended input or as a mono differential input. Each input includes adjustable gain to match a wide range of input signal levels. If a custom gain is needed, the external gain mode provides a trimmed feedback resistor. Set the gain by choosing the appropriate input resistor and using the following formula:

$$AV_{PGAIN} = 20 \text{ x } \log (20k\Omega/R_{IN})$$

The external gain mode also allows summing multiple signals into a single input, by connecting multiple input resistors as show in Figure 8, and/or inputting signals larger than $1V_{P-P}$ by adjusting the ration of the $20k\Omega/R_{IN}$ less than 1.

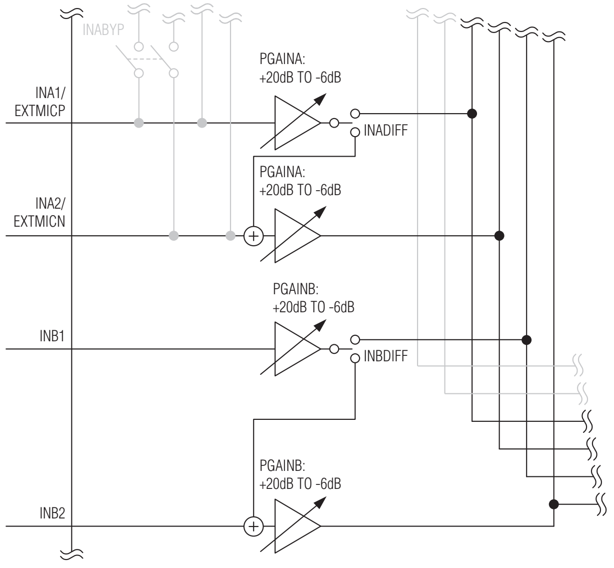


Figure 7. Line Input Block Diagram

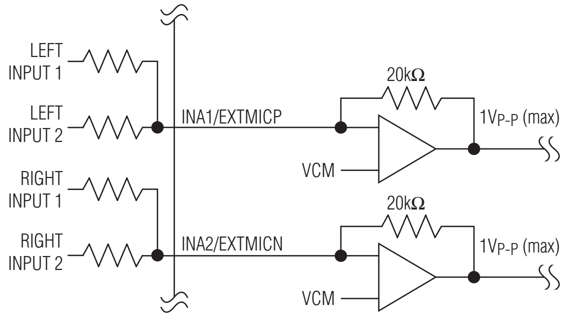


Figure 8. Summing Multiple Input Signals into INA/INB

Table 4. Line Input Registers

REGISTER	BIT	NAME	DESCRIPTION
0x37/0x38	6	INAEXT/INBEXT	**Line Input A/B External Gain** Switches out the internal input resistor and selects a trimmed 20kΩ feedback resistor. Use an external input resistor to set the gain of the line input. 0 = Disabled 1 = Enabled
	2	PGAINA/ PGAINB	**Line Input A/B Internal Gain Settings** 000 = +20dB 001 = +14dB 010 = +3dB 011 = 0dB 100 = -3dB 101 = -6dB 110 = -6dB 111 = -6dB
	1		
	0		
0x47	7	INADIFF	**Line Input A Differential Enable** 0 = Stereo single-ended input 1 = Mono differential input
	6	INBDIFF	**Line Input B Differential Enable** 0 = Stereo single-ended input 1 = Mono differential input

ADC Input Mixers

The IC's stereo ADC accepts input from the microphone amplifiers, line inputs amplifiers, and directly from the INA1 and INA2. The ADC mixer routes any combination of the eight audio inputs to the left and right ADCs (Figure 9).

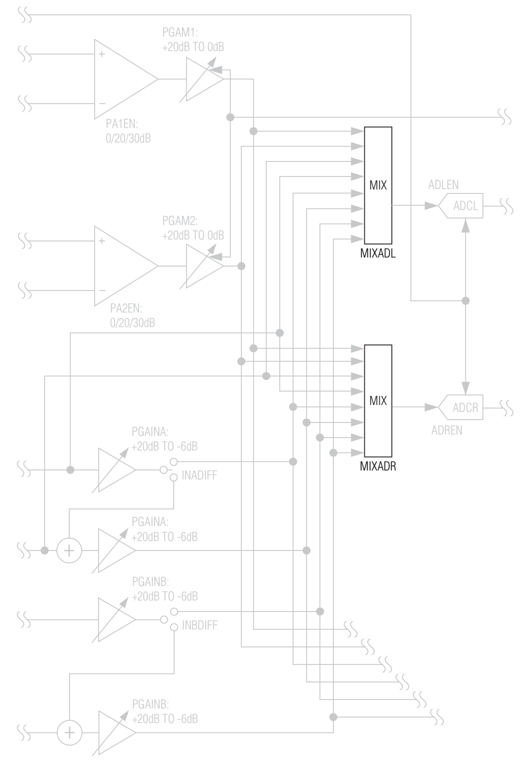


Figure 9. ADC Input Mixer Block Diagram

Table 5. ADC Input Mixer Register

REGISTER	BIT	NAME	DESCRIPTION
0x23/0x24	7	MIXADL/MIXADR	**Left/Right ADC Input Mixer** Selects which analog inputs are recorded by the left/right ADC. 1xxxxxxx = MIC1 x1xxxxxx = MIC2 xx1xxxxx = INA1 pin direct xxx1xxxx = INA2 pin direct xxxx1xxx = INA1 xxxxx1xx = INA2 (INADIFF = 0) or INA2 - INA1 (INADIFF = 1) xxxxxx1x = INB1 xxxxxxx1 = INB2 (INBDIFF = 0) or INB2 - INB1 (INBDIFF = 1)
	6		
	5		
	4		
	3		
	2		
	1		
	0		

Record Path Signal Processing

The device's record signal path includes both automatic gain control (AGC) for the microphone inputs and a digital noise gate at the output of the ADC (Figure 10).

Microphone AGC

The IC's AGC monitors the signal level at the output of the ADC and then adjusts the MIC1 and MIC2 analog PGA settings automatically. When the signal level is below the predefined threshold, the gain is increased up to its maximum (20dB). If the signal exceeds the threshold, the gain is reduced to prevent the output signal level exceeding the threshold. When AGC is enabled, the microphone PGA is not user programmable. The AGC provides a more constant signal level and improves the available ADC dynamic range.

Noise Gate

Since the AGC increases the levels of all signals below a user-defined threshold, the noise floor is effectively increased by 20dB. To counteract this, the noise gate reduces the gain at low signal levels. Unlike typical noise gates that completely silence the output below a defined level, the noise gate in the IC applies downward expansion. The noise gate attenuates the output at a rate of 1dB for each 2dB the signal is below the threshold with a maximum attenuation of 12dB.

The noise gate can be used in conjunction with the AGC or on its own. When the AGC is enabled, the noise gate reduces the output level only when the AGC has set the gain to the maximum setting. Figure 11 shows the gain response resulting from using the AGC and noise gate.

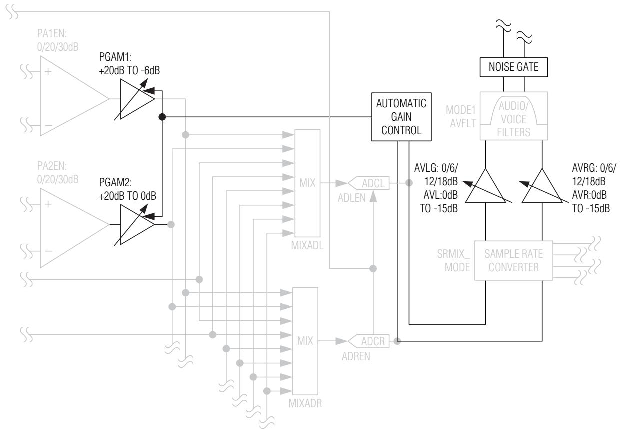


Figure 10. Record Path Signal Processing Block Diagram

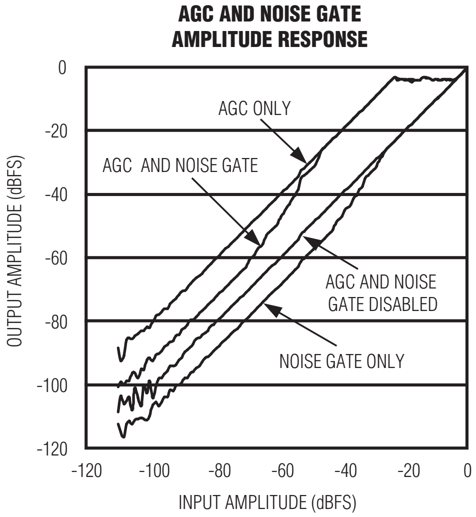


Figure 11. AGC and Noise Gate Input vs. Output Gain

Table 6. Record Path Signal Processing Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th>DESCRIPTION</th></tr>
<tr><td rowspan="8">0x01</td><td>7</td><td rowspan="3">NG</td><td rowspan="3">Noise Gate Attenuation
Reports the current noise gate attenuation.
000 = 0dB
001 = 1dB
010 = 2dB
011 = 3dB to 5dB
100 = 6dB to 7dB
101 = 8dB to 9dB
110 = 10dB to 11dB
111 = 12dB</td></tr>
<tr><td>6</td></tr>
<tr><td>5</td></tr>
<tr><td>4</td><td rowspan="5">AGC</td><td rowspan="5">AGC Gain
Reports the current AGC gain setting.
<table>
<tr><th>VALUE</th><th>GAIN (dB)</th><th>VALUE</th><th>GAIN (dB)</th></tr>
<tr><td>0x00</td><td>+20</td><td>0x0B</td><td>+9</td></tr>
<tr><td>0x01</td><td>+19</td><td>0x0C</td><td>+8</td></tr>
<tr><td>0x02</td><td>+18</td><td>0x0D</td><td>+7</td></tr>
<tr><td>0x03</td><td>+17</td><td>0x0E</td><td>+6</td></tr>
<tr><td>0x04</td><td>+16</td><td>0x0F</td><td>+5</td></tr>
<tr><td>0x05</td><td>+15</td><td>0x10</td><td>+4</td></tr>
<tr><td>0x06</td><td>+14</td><td>0x11</td><td>+3</td></tr>
<tr><td>0x07</td><td>+13</td><td>0x12</td><td>+2</td></tr>
<tr><td>0x08</td><td>+12</td><td>0x13</td><td>+1</td></tr>
<tr><td>0x09</td><td>+11</td><td>0x14 to 0x1F</td><td>0</td></tr>
<tr><td>0x0A</td><td>+10</td><td></td><td></td></tr>
</table></td></tr>
<tr><td>3</td></tr>
<tr><td>2</td></tr>
<tr><td>1</td></tr>
<tr><td>0</td></tr>
<tr><td rowspan="4">0x3F</td><td>7</td><td>AGCSRC</td><td>AGC/Noise Gate Signal Source
Determines which ADC channel the AGC and noise gates analyze. Gain is adjusted on both channels regardless of the AGCSRC setting.
0 = Left ADC output
1 = Maximum of either the left or right ADC output</td></tr>
<tr><td>6</td><td rowspan="3">AGCRLS</td><td rowspan="3">AGC Release Time
Defined as the duration from start to finish of gain increase in the region shown in Figure 12.
000 = 78ms
001 = 156ms
010 = 312ms
011 = 625ms
100 = 1.25s
101 = 2.5s
110 = 5s
111 = 10s</td></tr>
<tr><td>5</td></tr>
<tr><td>4</td></tr>
</table>

Table 6. Record Path Signal Processing Registers (continued)

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="4">0x3F</td><td>3</td><td rowspan="2">AGCATK</td><td colspan="4" rowspan="2">AGC Attack Time
Defined as the time required to reduce gain by 63% of the total gain reduction (one time constant of the exponential response). Attack times are longer for low AGC threshold levels. See Figure 12 for details.
00 = 2ms
01 = 7.2ms
10 = 31ms
11 = 123ms</td></tr>
<tr><td>2</td></tr>
<tr><td>1</td><td rowspan="2">AGCHLD</td><td colspan="4" rowspan="2">AGC Hold Time
The delay before the AGC release begins. The hold time counter starts whenever the signal drops below the AGC threshold and is reset by any signal that exceeds the threshold. Set AGCHLD to enable the AGC circuit. See Figure 12 for details.
00 = AGC disabled
01 = 50ms
10 = 100ms
11 = 400ms</td></tr>
<tr><td>0</td></tr>
<tr><td rowspan="20">0x40</td><td>7</td><td rowspan="10">ANTH</td><td colspan="4">Noise Gate Threshold
Gain is reduced for signals below the threshold to quiet noise. The thresholds are relative to the ADC’s full-scale output voltage.</td></tr>
<tr><td rowspan="3">6</td><td>VALUE</td><td>THRESHOLD (dBFS)</td><td>VALUE</td><td>THRESHOLD (dBFS)</td></tr>
<tr><td>0x0</td><td>Noise gate disabled</td><td>0x8</td><td>-45</td></tr>
<tr><td>0x1</td><td>Reserved</td><td>0x9</td><td>-41</td></tr>
<tr><td rowspan="3">5</td><td>0x2</td><td>Reserved</td><td>0xA</td><td>-38</td></tr>
<tr><td>0x3</td><td>-64</td><td>0xB</td><td>-34</td></tr>
<tr><td>0x4</td><td>-62</td><td>0xC</td><td>-30</td></tr>
<tr><td rowspan="3">4</td><td>0x5</td><td>-58</td><td>0xD</td><td>-27</td></tr>
<tr><td>0x6</td><td>-53</td><td>0xE</td><td>-22</td></tr>
<tr><td>0x7</td><td>-50</td><td>0xF</td><td>-16</td></tr>
<tr><td>3</td><td rowspan="10">AGCTH</td><td colspan="4">AGC Threshold
Gain is reduced when signals exceed the threshold to prevent clipping. The thresholds are relative to the ADC’s full-scale voltage.</td></tr>
<tr><td rowspan="3">2</td><td>VALUE</td><td>THRESHOLD (dBFS)</td><td>VALUE</td><td>THRESHOLD (dBFS)</td></tr>
<tr><td>0x0</td><td>-3</td><td>0x8</td><td>-11</td></tr>
<tr><td>0x1</td><td>-4</td><td>0x9</td><td>-12</td></tr>
<tr><td rowspan="3">1</td><td>0x2</td><td>-5</td><td>0xA</td><td>-13</td></tr>
<tr><td>0x3</td><td>-6</td><td>0xB</td><td>-14</td></tr>
<tr><td>0x4</td><td>-7</td><td>0xC</td><td>-15</td></tr>
<tr><td rowspan="3">0</td><td>0x5</td><td>-8</td><td>0xD</td><td>-16</td></tr>
<tr><td>0x6</td><td>-9</td><td>0xE</td><td>-17</td></tr>
<tr><td>0x7</td><td>-10</td><td>0xF</td><td>-18</td></tr>
</table>

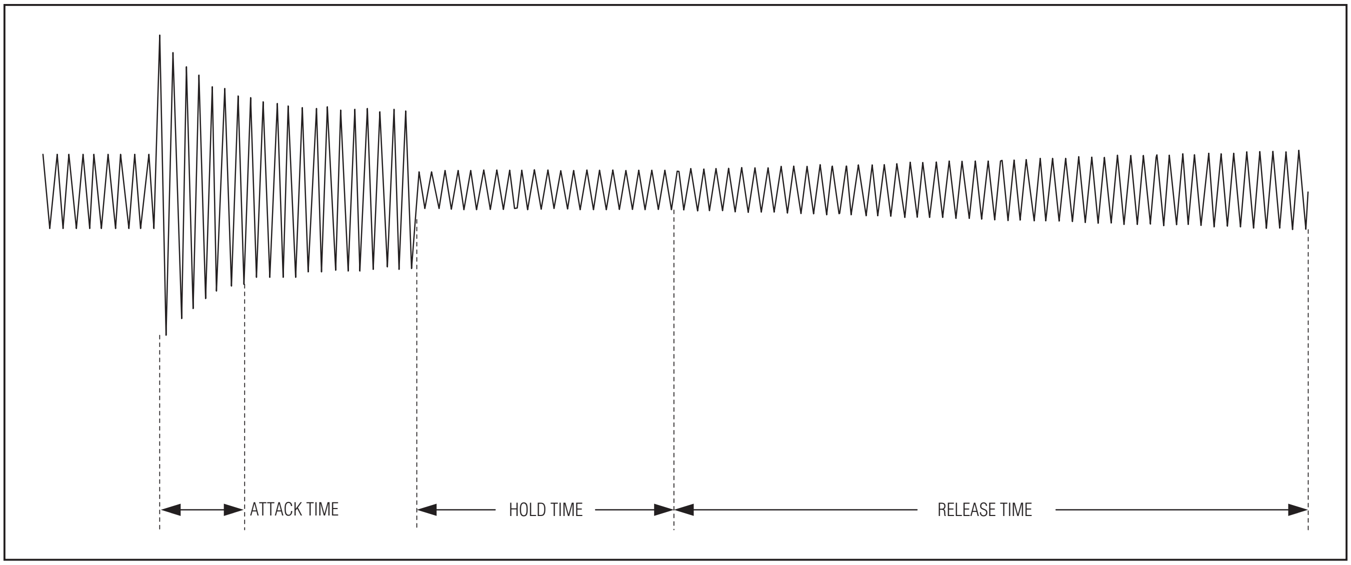


Figure 12. AGC Timing

ADC Record Level Control

The IC includes separate digital level control for the left and right ADC outputs (Figure 13). To optimize dynamic range, use analog gain to adjust the signal level and set the digital level control to 0dB whenever possible. Digital level control is primarily used when adjusting the record level for digital microphones.

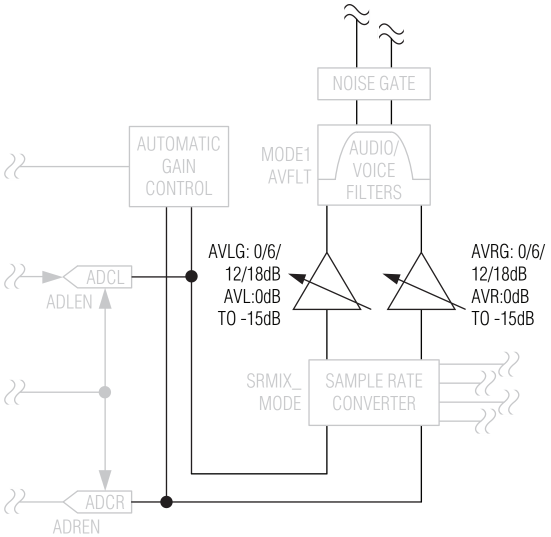


Figure 13. ADC Record Level Control Block Diagram

Table 7. ADC Record Level Control Register

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="12">0x33/0x34</td><td>5</td><td rowspan="2">AVLG/AVRG</td><td colspan="4" rowspan="2">Left/Right ADC Gain
00 = 0dB
01 = 6dB
10 = 12dB
11 = 18dB</td></tr>
<tr><td>4</td></tr>
<tr><td rowspan="2">3</td><td rowspan="10">AVL/AVR</td><td colspan="4">Left/Right ADC Level</td></tr>
<tr><td>VALUE</td><td>GAIN (dB)</td><td>VALUE</td><td>GAIN (dB)</td></tr>
<tr><td rowspan="2">2</td><td>0x0</td><td>+3</td><td>0x8</td><td>-5</td></tr>
<tr><td>0x1</td><td>+2</td><td>0x9</td><td>-6</td></tr>
<tr><td rowspan="3">1</td><td>0x2</td><td>+1</td><td>0xA</td><td>-7</td></tr>
<tr><td>0x3</td><td>0</td><td>0xB</td><td>-8</td></tr>
<tr><td>0x4</td><td>-1</td><td>0xC</td><td>-9</td></tr>
<tr><td rowspan="3">0</td><td>0x5</td><td>-2</td><td>0xD</td><td>-10</td></tr>
<tr><td>0x6</td><td>-3</td><td>0xE</td><td>-11</td></tr>
<tr><td>0x7</td><td>-4</td><td>0xF</td><td>-12</td></tr>
</table>

Sidetone

Enable sidetone during full-duplex operation to add a low-level copy of the recorded audio signal to the playback audio signal (Figure 14) through DAI1 playback path. Sidetone is commonly used in telephony to allow the speaker to hear himself speak, providing a more natural user experience. The IC implements sidetone digitally. Doing so helps prevent unwanted feedback into the playback signal path and better matches the playback audio signal. Sidestone is available in voice mode only.

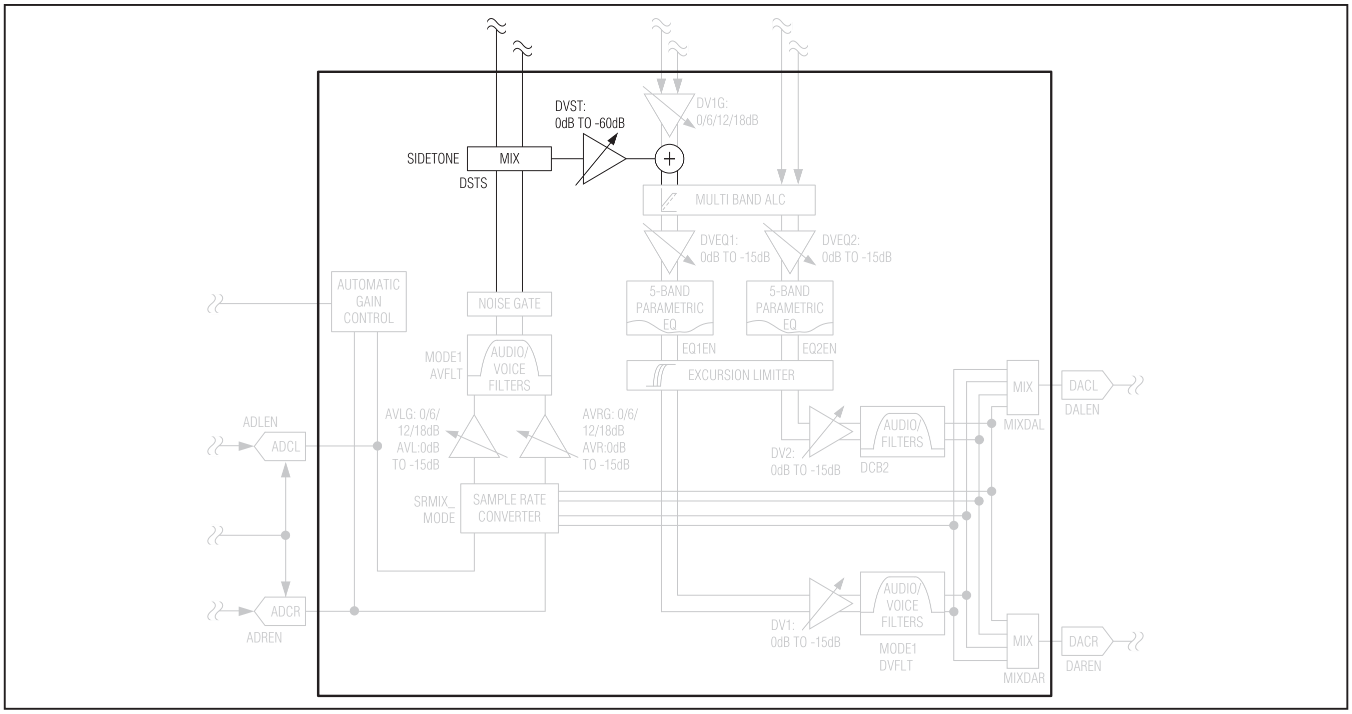


Figure 14. Sidetone Block Diagram

Table 8. Sidetone Register

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="22">0x2E</td><td>7</td><td rowspan="2">DSTS</td><td colspan="4" rowspan="2">Sidetone Source
Selects which ADC output is fed back as sidetone. When mixing the left and right ADC outputs, each is attenuated by 6dB to prevent full-scale signals from clipping.
00 = Sidetone disabled
01 = Left ADC
10 = Right ADC
11 = Left + Right ADC</td></tr>
<tr><td>6</td></tr>
<tr><td rowspan="2">4</td><td rowspan="20">DVST</td><td colspan="4">Sidetone Level
Adjusts the sidetone signal level. All levels are referenced to the ADC’s full-scale output.</td></tr>
<tr><th>VALUE</th><th>LEVEL (dB)</th><th>VALUE</th><th>LEVEL (dB)</th></tr>
<tr><td rowspan="4">3</td><td>0x00</td><td>Sidetone disabled</td><td>0x10</td><td>-30.5</td></tr>
<tr><td>0x01</td><td>-0.5</td><td>0x11</td><td>-32.5</td></tr>
<tr><td>0x02</td><td>-2.5</td><td>0x12</td><td>-34.5</td></tr>
<tr><td>0x03</td><td>-4.5</td><td>0x13</td><td>-36.5</td></tr>
<tr><td rowspan="4">2</td><td>0x04</td><td>-6.5</td><td>0x14</td><td>-38.5</td></tr>
<tr><td>0x05</td><td>-8.5</td><td>0x15</td><td>-40.5</td></tr>
<tr><td>0x06</td><td>-10.5</td><td>0x16</td><td>-42.5</td></tr>
<tr><td>0x07</td><td>-12.5</td><td>0x17</td><td>-44.5</td></tr>
<tr><td rowspan="4">1</td><td>0x08</td><td>-14.5</td><td>0x18</td><td>-46.5</td></tr>
<tr><td>0x09</td><td>-16.5</td><td>0x19</td><td>-48.5</td></tr>
<tr><td>0x0A</td><td>-18.5</td><td>0x1A</td><td>-50.5</td></tr>
<tr><td>0x0B</td><td>-20.5</td><td>0x1B</td><td>-52.5</td></tr>
<tr><td rowspan="4">0</td><td>0x0C</td><td>-22.5</td><td>0x1C</td><td>-54.5</td></tr>
<tr><td>0x0D</td><td>-24.5</td><td>0x1D</td><td>-56.6</td></tr>
<tr><td>0x0E</td><td>-26.5</td><td>0x1E</td><td>-58.5</td></tr>
<tr><td>0x0F</td><td>-28.5</td><td>0x1F</td><td>-60.5</td></tr>
</table>

Digital Audio Interfaces

The IC includes two separate playback signal paths and one record signal path. Digital audio interface 1 (DAI1) is used to transmit the recorded stereo audio signal and receive a stereo audio signal for playback. Digital audio interface 2 (DAI2) is used to receive a second stereo audio signal. Use DAI1 for all full-duplex operations and for all voice signals. Use DAI2 for music and to mix two playback audio signals. The digital audio interfaces are separate from the audio ports to enable either interface to communicate with any external device connected to either audio port.

Each audio interface can be configured in a variety of formats including left justified, I^{2}S, PCM, and time division multiplexed (TDM). TDM mode supports up to 4 mono audio slots in each frame. The IC can use up to 2 mono slots per interface, leaving the remaining two slots available for another device. Table 9 shows how to configure the device for common digital audio formats. Figures 16 and 17 show examples of common audio formats. By default, SDOUTS1 and SDOUTS2 are set high impedance when the IC is not outputting data to facilitate sharing the bus. Configure the interface in TDM mode using only slot 1 to transmit and receive mono PCM voice data.

The IC’s digital audio interfaces support both ADC to DAC loop-through and digital loopback. Loop-through allows the signal converted by the ADC to be routed to the DAC for playback. The signal is routed from the record path to the playback path in the digital audio interface to allow the IC’s full complement of digital signal processing to be used. Loopback allows digital data input to either SDINS1 or SDINS2 to be routed from one interface to the other for output on SDOUTS2 or SDOUTS1. Both interfaces must be configured for the same sample rate, but the interface format need not be the same. This allows the IC to route audio data from one device to another, converting the data format as needed. Figure 15 shows the available digital signal routing options.

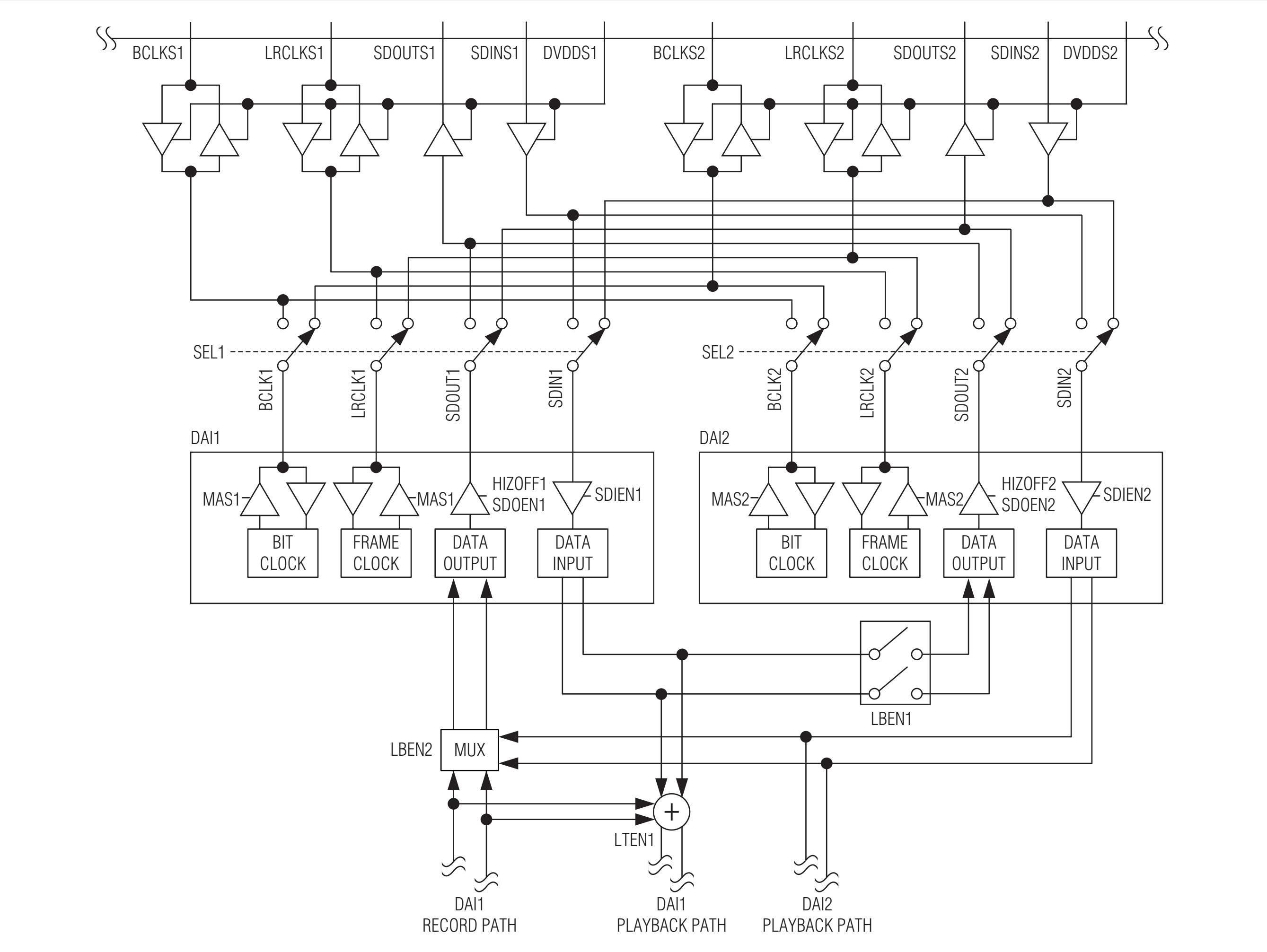


Figure 15. Digital Audio Signal Routing

Table 9. Common Digital Audio Formats

MODE	WCI1/WCI2	BCI1/BCI2	DLY1/DLY2	TDM1/TDM2	SLOTL1/SLOTL2	SLOTR1/SLOTR2
Left Justified	1	0	0	0	X	X
I^2S	0	0	1	0	X	X
PCM	X	1	X	1	0	0
TDM	X	1	X	1	Set as desired	

X = Don’t care.

Table 10. Digital Audio Interface Registers

REGISTER	BIT	NAME	DESCRIPTION
0x14/0x1C	7	MAS1/MAS2	**DAI1/DAI2 Master Mode** In master mode, DAI1/DAI2 outputs LRCLK and BCLK. In slave mode, DAI1/DAI2 accept LRCLK and BCLK as inputs. 0 = Slave mode 1 = Master mode
	6	WCI1/WCI2	**DAI1/DAI2 Word Clock Invert** TDM1/TDM2 = 0: 0 = Left-channel data is transmitted while LRCLK is low. 1 = Right-channel data is transmitted while LRCLK is low. TDM1/TDM2 = 1: Always set WCI = 0.
	5	BCI1/BCI2	**DAI1/DAI2 Bit Clock Invert** BCI1/BCI2 must be set to 1 when TDM1/TDM2 = 1. 0 = SDIN is accepted on the rising edge of BCLK. SDOUT is valid on the rising edge of BCLK. 1 = SDIN is accepted on the falling edge of BCLK. SDOUT is valid on the falling edge of BCLK. Master Mode: 0 = LRCLK transitions on the falling edge of BCLK. 1 = LRCLK transitions on the rising edge of BCLK.
	4	DLY1/DLY2	**DAI1/DAI2 Data Delay** DLY1/DLY2 has no effect when TDM1/TDM2 = 1. 0 = The most significant data bit is clocked on the first active BCLK edge after an LRCLK transition. 1 = The most significant data bit is clocked on the second active BCLK edge after an LRCLK transition.
	2	TDM1/TDM2	**DAI1/DAI2 Time-Division Multiplex Mode (TDM Mode)** Set TDM1/TDM2 when communicating with devices that use a frame synchronization pulse on LRCLK instead of a square wave. 0 = Disabled 1 = Enabled (BCI1/BCI2 must be set to 1)
	1	FSW1/FSW2	**DAI1/DAI2 Wide Frame Sync Pulse** Increases the width of the frame sync pulse to the full data width when TDM1/TDM2 = 1. FSW1/FSW2 has no effect when TDM1/TDM2 = 0. 0 = Disabled 1 = Enabled
	0	WS1/WS2	**DAI1/DAI2 Audio Data Bit Depth** Determines the maximum bit depth of audio being transmitted and received. Data is always 16 bit when TDM1/TMD2 = 0. 0 = 16 bits 1 = 24 bits

Table 10. Digital Audio Interface Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
0x15/0x1D	7	ADC_OSR1 (0x15 ONLY)	**ADC Oversampling Ratio** Use the higher setting for maximum performance. Use the lower setting for reduced power consumption at the expense of performance. 00 = 96x 01 = 64x 10 = Reserved 11 = Reserved
	6		
	5	DAC_OSR1 (0x15 ONLY)	**DAC Oversample Clock (Select PCLK/2 for higher performance. Select PCLK/4 for lower power consumption.)** 1 = DAC input clock = PCLK/2 0 = DAC input clock = PCLK/4
	2	BSEL1/ BSEL2	**DAI1/DAI2 BCLK Output Frequency** When operating in master mode, BSEL1/BSEL2 set the frequency of BCLK. When operating in slave mode, BSEL1/BSEL2 have no effect. Select the lowest BCLK frequency that clocks all data input to the DAC and output by the ADC. 000 = BCLK disabled 001 = 64 x LRCLK 010 = 48 x LRCLK 011 = 128 x LRCLK (invalid for DHF1/DHF2 = 1) 100 = PCLK/2 101 = PCLK/4 110 = PCLK/8 111 = PCLK/16
	1		
	0		
0x16/0x1E	7	SEL1/SEL2	**DAI1/DAI2 Audio Port Selector** Selects which port is used by DAI1/DAI2. 00 = None 01 = Port S1 10 = Port S2 11 = Reserved
	6		
	5	LTEN1	**DAI1 Digital Loopthrough** Connects the output of the record signal path to the input of the playback path. Data input to DAI1 from an external device is mixed with the recorded audio signal. 0 = Disabled 1 = Enabled
	4	LBEN1/ LBEN2	**DAI1/DAI2 Digital Audio Interface Loopback** LBEN1 routes the digital audio input to DAI1 back out on DAI2. LBEN2 routes the digital audio input to DAI2 back out on DAI1. Selecting LBEN2 disables the ADC output data. 0 = Disabled 1 = Enabled
	3	DMONO1/ DMONO2	**DAI1/DAI2 DAC Mono Mix** Mixes the left and right digital input to mono and routes the combined signal to the left and right playback paths. The left and right input data is attenuated by 6dB prior to the mono mix. 0 = Disabled 1 = Enabled

Table 10. Digital Audio Interface Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
0x16/0x1E	2	HIZOFF1/ HIZOFF2	**Disable DAI1/DAI2 Output High-Impedance Mode** Normally SDOUT is set high impedance between data words. Set HIZOFF1/HIZOFF2 to force a level on SDOUT at all times. 0 = Disabled 1 = Enabled
	1	SDOEN1/ SDOEN2	**DAI1/DAI2 Record Path Output Enable** DAI2 outputs data only if LBEN1 = 1. 0 = Disabled 1 = Enabled
	0	SDIEN1/ SDIEN2	**DAI1/DAI2 Playback Path Input Enable** 0 = Disabled 1 = Enabled
0x17/0x1F	7	SLOTL1/ SLOTL2	**TDM Left Time Slot** Selects which of the four slots is used for left data on DAI1/DAI2. If the same slot is selected for left and right audio, left audio is placed in the slot. 00 = Slot 1 01 = Slot 2 10 = Slot 3 11 = Slot 4
	6		
	5	SLOTR1/ SLOTR2	**TDM Right Time Slot** Selects which of the four slots is used for right data on DAI1/DAI2. If the same slot is selected for left and right audio, left audio is placed in the slot. 00 = Slot 1 01 = Slot 2 10 = Slot 3 11 = Slot 4
	4		
	3	SLOTDLY1/ SLOTDLY2	**TDM Slot Delay** Adds 1 BCLK cycle delay to the data in the specified TDM slot. 1xxx = Slot 4 delayed x1xx = Slot 3 delayed xx1x = Slot 2 delayed xxx1 = Slot 1 delayed
	2		
	1		
	0		

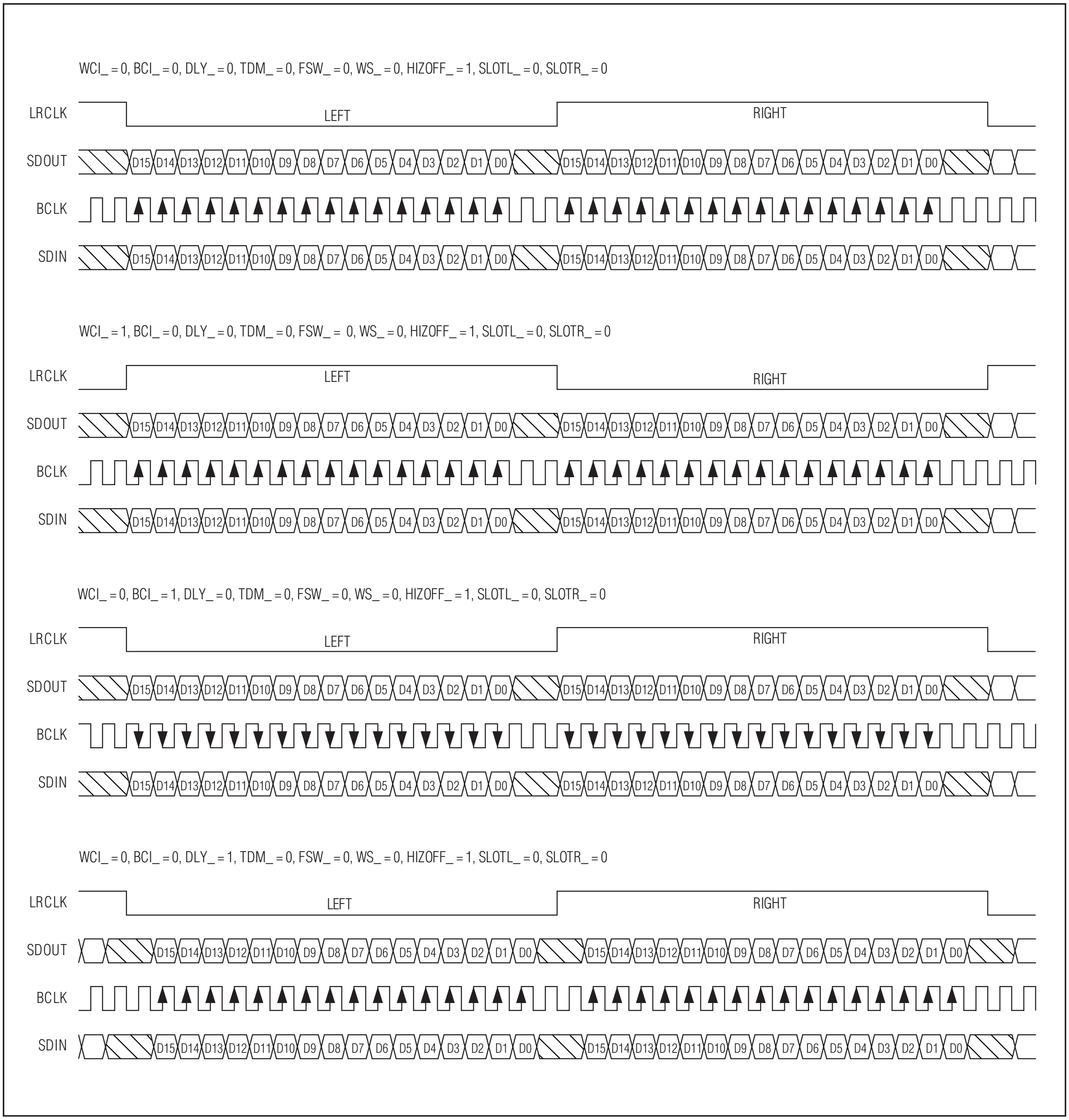


Figure 16. Non-TDM Data Format Examples

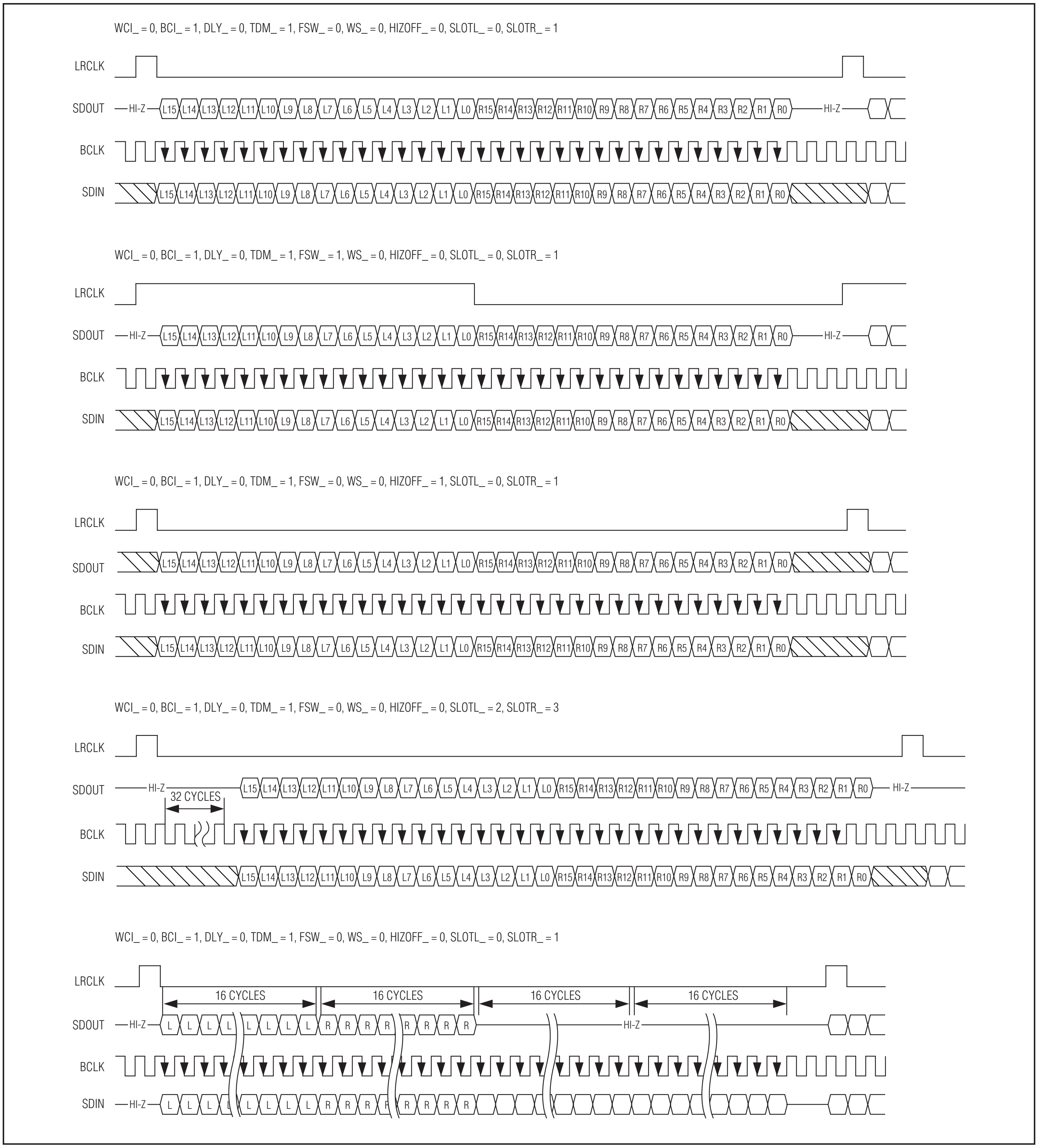


Figure 17. TDM Mode Data Format Examples

Clock Control

The digital signal paths in the IC require a master clock (MCLK) between 10MHz and 60MHz to function. The MAX98089 requires an internal clock between 10MHz and 20MHz. A prescaler divides MCLK by 1, 2, or 4 to create the internal clock (PCLK). PCLK is used to clock all portions of the IC.

The MAX98089 includes two digital audio signal paths, both capable of supporting any sample rate from 8kHz to 96kHz. Each path is independently configured to allow different sample rates. To accommodate a wide range of system architectures, four main clocking modes are supported:

- **PLL Mode:** When operating in slave mode, enable the PLL to lock onto any LRCLK input. This mode requires the least configuration, but provides the lowest performance. Use this mode to simplify initial setup or when normal mode and exact integer mode cannot be used.
- **Normal Mode:** This mode uses a 15-bit clock divider to set the sample rate relative to PCLK. This allows high flexibility in both the PCLK and LRCLK frequencies and can be used in either master or slave mode.
- **Exact Integer Mode (DAI1 only):** In both master and slave modes, common MCLK frequencies (12MHz, 13MHz, 16MHz, and 19.2MHz) can be programmed to operate in exact integer mode for both 8kHz and 16kHz sample rates. In these modes, the MCLK and LRCLK rates are selected by using the FREQ1 bits instead of the NI, and PLL control bits.
- **DAC Low-Power Mode:** This mode bypasses the PLL for reduce power consumptions and uses fixed counters to generate the clocks. The DAI__DAC_LP bits override the other clock settings.

Table 11. Clock Control Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="2">0x10</td><td>5</td><td rowspan="2">PSCLK</td><td colspan="4" rowspan="2">MCLK Prescaler
Generates PCLK, which is used by all internal circuitry.
00 = PCLK disabled
01 = 10MHz ≤ MCLK ≤ 20MHz (PCLK = MCLK)
10 = 20MHz ≤ MCLK ≤ 40MHz (PCLK = MCLK/2)
11 = 40MHz ≤ MCLK ≤ 60MHz (PCLK = MCLK/4)</td></tr>
<tr><td>4</td></tr>
<tr><td rowspan="10">0x11/0x19</td><td>7</td><td rowspan="10">SR1/SR2</td><td colspan="4">DAI1/DAI2 Sample Rate
Used by the ALC to correctly set the dual-band crossover frequency and the excursion limiter to set the predefined corner frequencies.</td></tr>
<tr><td rowspan="2">6</td><td>VALUE</td><td>SAMPLE RATE (kHz)</td><td>VALUE</td><td>SAMPLE RATE (kHz)</td></tr>
<tr><td>0x0</td><td>Reserved</td><td>0x8</td><td>48</td></tr>
<tr><td rowspan="4">5</td><td>0x1</td><td>8</td><td>0x9</td><td>88.2</td></tr>
<tr><td>0x2</td><td>11.025</td><td>0xA</td><td>96</td></tr>
<tr><td>0x3</td><td>16</td><td>0xB</td><td>Reserved</td></tr>
<tr><td>0x4</td><td>22.05</td><td>0xC</td><td>Reserved</td></tr>
<tr><td rowspan="3">4</td><td>0x5</td><td>24</td><td>0xD</td><td>Reserved</td></tr>
<tr><td>0x6</td><td>32</td><td>0xE</td><td>Reserved</td></tr>
<tr><td>0x7</td><td>44.1</td><td>0xF</td><td>Reserved</td></tr>
</table>

Table 11. Clock Control Registers (continued)

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th>DESCRIPTION</th></tr>
<tr><td rowspan="3">0x11</td><td>3</td><td rowspan="3">FREQ1</td><td rowspan="3">Exact Integer Mode
Overrides PLL1 and NI1 and configures a specific PCLK to LRCLK ratio.
<table>
<tr><th>VALUE</th><th>SAMPLE RATE</th><th>VALUE</th><th>SAMPLE RATE</th></tr>
<tr><td>0x0</td><td>Disabled</td><td>0x8</td><td>PCLK = 12MHz, LRCLK = 8kHz</td></tr>
<tr><td>0x1</td><td>Reserved</td><td>0x9</td><td>PCLK = 12MHz, LRCLK = 16kHz</td></tr>
<tr><td>0x2</td><td>Reserved</td><td>0xA</td><td>PCLK = 13MHz, LRCLK = 8kHz</td></tr>
<tr><td>0x3</td><td>Reserved</td><td>0xB</td><td>PCLK = 13MHz, LRCLK = 16kHz</td></tr>
<tr><td>0x4</td><td>Reserved</td><td>0xC</td><td>PCLK = 16MHz, LRCLK = 8kHz</td></tr>
<tr><td>0x5</td><td>Reserved</td><td>0xD</td><td>PCLK = 16MHz, LRCLK = 16kHz</td></tr>
<tr><td>0x6</td><td>Reserved</td><td>0xE</td><td>PCLK = 19.2MHz, LRCLK = 8kHz</td></tr>
<tr><td>0x7</td><td>Reserved</td><td>0xF</td><td>PCLK = 19.2MHz, LRCLK = 16kHz</td></tr>
</table></td></tr>
<tr><td>2</td></tr>
<tr><td>1</td></tr>
<tr><td rowspan="8">0x12/0x1A</td><td>7</td><td>PLL1/PLL2</td><td>PLL Mode Enable (Slave Mode Only)
PLL1/PLL2 enables a digital PLL that locks on to the externally supplied LRCLK frequency and automatically sets the LRCLK divider (NI1/NI2).
0 = Disabled
1 = Enabled</td></tr>
<tr><td>6</td><td rowspan="14">NI1/
NI2</td><td rowspan="14">Normal Mode LRCLK Divider
When PLL1/PLL2 = 0, the frequency of LRCLK is determined by NI1/NI2. See Table 12 for common NI values.
<table>
<tr><th>SAMPLE RATE</th><th>DHF1/DHF2</th><th>NI1/NI2 FORMULA</th></tr>
<tr><td>8kHz ≤ LRCLK ≤ 48kHz</td><td>0</td><td>$NI = \frac{65{,}536 \text{ x } 96 \text{ x } f_{LRCLK}}{f_{PCLK}}$</td></tr>
<tr><td>48kHz < LRCLK ≤ 96kHz</td><td>1</td><td>$NI = \frac{65{,}536 \text{ x } 48 \text{ x } f_{LRCLK}}{f_{PCLK}}$</td></tr>
</table>
f_{LRCLK} = LRCLK frequency
f_{PCLK} = Prescaled MCLK frequency (PCLK)</td></tr>
<tr><td>5</td></tr>
<tr><td>4</td></tr>
<tr><td>3</td></tr>
<tr><td>2</td></tr>
<tr><td>1</td></tr>
<tr><td>0</td></tr>
<tr><td rowspan="8">0x13/0x1B</td><td>7</td></tr>
<tr><td>6</td></tr>
<tr><td>5</td></tr>
<tr><td>4</td></tr>
<tr><td>3</td></tr>
<tr><td>2</td></tr>
<tr><td>1</td></tr>
<tr><td>0</td><td>NI1[0]/NI2[0]</td><td>Rapid Lock Mode
Program NI1/NI2 to the nearest valid ratio and set NI1[0]/NI2[0] when PLL1/PLL2 = 1 to enable rapid lock mode. Normally, the PLL automatically calculates and dynamically adjusts NI1/NI2. When rapid lock mode is properly configured, the PLL starting point is much closer to the correct value, thus speeding up lock time. Wait one LRCLK period after programming NI1/NI2 before setting PLL1/PLL2 = 1.</td></tr>
</table>

Table 11. Clock Control Registers (continued)

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="6">DESCRIPTION</th></tr>
<tr><td rowspan="10">0x4F</td><td>7</td><td rowspan="5">DAI2_DAC_LP</td><td colspan="6">DAI_ DAC Low Power Select.
These bits setup the clocks to be generated from fixed counters that bypass the PLL for DAC low power mode.</td></tr>
<tr><td rowspan="2">6</td><td>VALUE</td><td>SETTING</td><td>FILTER SELECT</td><td>VALUE</td><td>SETTING</td><td>FILTER SELECT</td></tr>
<tr><td>0x0</td><td>PLL derived clock</td><td>—</td><td>0x8</td><td>PCLK = 2304 x LRCLK</td><td>Voice</td></tr>
<tr><td>5</td><td>0x1</td><td>PCLK = 128 x LRCLK</td><td>Audio 96kHz</td><td>0x9</td><td>Reserved</td><td>—</td></tr>
<tr><td>4</td><td>0x2</td><td>PCLK = 192 x LRCLK</td><td>Audio 96kHz</td><td>0xA</td><td>Reserved</td><td>—</td></tr>
<tr><td rowspan="2">3</td><td rowspan="5">DAI1_DAC_LP</td><td>0x3</td><td>PCLK = 256 x LRCLK</td><td>Audio 48kHz</td><td>0xB</td><td>Reserved</td><td>—</td></tr>
<tr><td>0x4</td><td>PCLK = 384 x LRCLK</td><td>Audio 48kHz</td><td>0xC</td><td>Reserved</td><td>—</td></tr>
<tr><td>2</td><td>0x5</td><td>PCLK = 768 x LRCLK</td><td>Voice</td><td>0xD</td><td>Reserved</td><td>—</td></tr>
<tr><td>1</td><td>0x6</td><td>PCLK = 1152 x LRCLK</td><td>Voice</td><td>0xE</td><td>Reserved</td><td>—</td></tr>
<tr><td>0</td><td>0x7</td><td>PCLK = 1536 x LRCLK</td><td>Voice</td><td>0xF</td><td>Reserved</td><td>—</td></tr>
<tr><td rowspan="4">0x50</td><td>3</td><td>DAC2DITHEN</td><td colspan="6">DAI2 DAC Input Dither Enable
DAC2DITHEN is recommended to be set when DAI2_DAC_LP = 0000.
0 = Disabled
1 = Enabled</td></tr>
<tr><td>2</td><td>DAC1DITHEN</td><td colspan="6">DAI1 DAC Input Dither 1 Enable
DAC1DITHEN is recommended to be set when DAI1_DAC_LP = 0000.
0 = Disabled
1 = Enabled</td></tr>
<tr><td>1</td><td>CGM2_EN</td><td colspan="6">DAI2 Clock Gen Module Enable
CGM1_EN has to be set along with CGM2_EN to enable the clock generation for the DAI2 DAC playback path.
0 = Disabled
1 = Enabled</td></tr>
<tr><td>0</td><td>CGM1_EN</td><td colspan="6">DAI1/Device Clock Gen Module Enable
CGM1_EN enables the device clock generation, and needs to be set for DAC playback or ADC record.
0 = Disabled
1 = Enabled</td></tr>
</table>

Table 12. Common NI1/NI2 Values

PCLK (MHz)	LRCLK (kHz)											
	DHF1/2 = 0									DHF1/2 = 1		
	8	11.025	12	16	22.05	24	32	44.1	48	64	88.2	96
10	13A9	1B18	1D7E	2752	3631	3AFB	4EA5	6C61	75F7	4EA5	6C61	75F7
11	11E0	18A2	1ACF	23BF	3144	359F	477E	6287	6B3E	477E	6287	6B3E
11.2896	116A	**1800**	1A1F	22D4	**3000**	343F	45A9	**6000**	687D	45A9	**6000**	687D
12	1062	1694	1893	20C5	2D29	3127	4189	5A51	624E	4189	5A51	624E
12.288	**1000**	160D	**1800**	**2000**	2C1A	**3000**	**4000**	5833	**6000**	**4000**	5833	**6000**
13	0F20	14D8	16AF	1E3F	29AF	2D5F	3C7F	535F	5ABE	3C7F	535F	5ABE
16	0C4A	10EF	126F	1893	21DE	24DD	3127	43BD	49BA	3127	43BD	49BA
16.9344	0B9C	**1000**	116A	1738	**2000**	22D4	2E71	**4000**	45A9	2E71	**4000**	45A9
18.432	0AAB	0EB3	**1000**	1555	1D66	**2000**	2AAB	3ACD	**4000**	2AAB	3ACD	**4000**
20	09D5	0D8C	0EBF	13A9	1B18	1D7E	2752	3631	3AFB	2752	3631	3AFB

Note: *Values in bold are exact integers that provide maximum full-scale performance.*

Sample Rate Converter

The sample rate conversion circuit allows for both sample rate conversion and mixing of asynchronous audio data from DAI1 (SDIN1) and DAI2 (SDIN2). The resulting audio can be output through DAI1 to either SDOUTS1 or SDOUTS2. The sample rate converter can be enabled on a per channel basis, allowing for one channel of DAI1 to output microphone data while the other channel is outputting sample rate converted data.

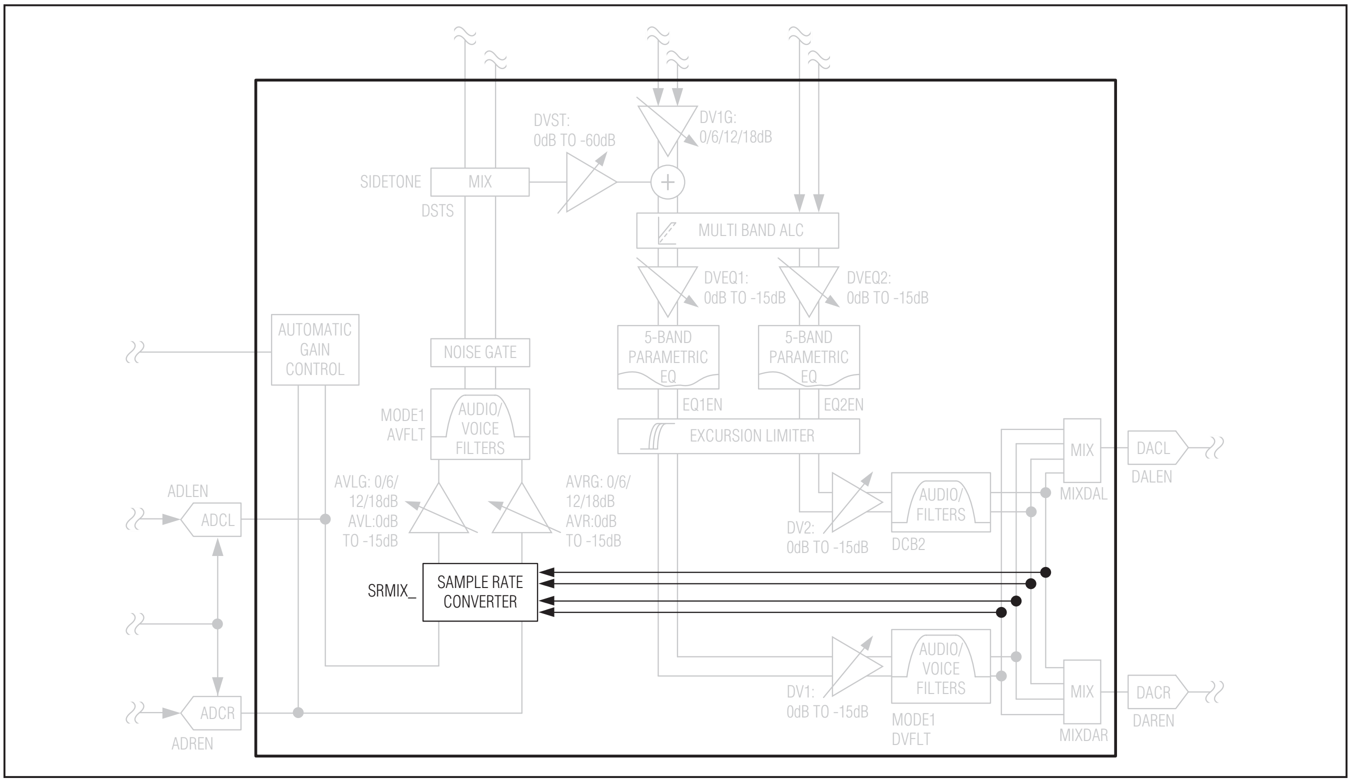


Figure 18. Sample Rate Converter

Table 13. Sample Rate Converter Register

REGISTER	BIT	NAME	DESCRIPTION
0x21	4	SRMIX_MODE	**Sample Rate Mix Mode.** Sets mixing configuration applied to the sample rate converted channel(s). 0 = (DAI1 + DAI2) 1 = (DAI1 + DAI2)/2
	3	SRMIX_ENL	**Sample Rate Mix Enable.** If enabled, mixes data on DAI1 and DAI2. If cleared, SCR data source is DAI2 only. 0 = SRC mix disable 1 = SRC mix enable
	2	SRMIX_ENR	
	1	SRC_ENL	**Sample Rate Converter Enable.** Select if the SRC is enabled on a per channel basis. 0 = Sample rate converter disable 1 = Sample rate converter enable
	0	SRC_ENR	

Passband Filtering

Each digital signal path in the IC includes options for defining the path bandwidth (Figure 19). The playback and record paths connected to DAI1 support both voice and music filtering while the playback path connected to DAI2 supports music filtering only.

The voice IIR filters provide greater than 70dB stopband attenuation at frequencies above $f_S/2$ to reduce aliasing. Three selectable highpass filters eliminate unwanted low-frequency signals.

Use music mode when processing high-fidelity audio content. The music FIR filters reduce power consumption and are linear phase to maintain stereo imaging. An optional DC-blocking filter is available to eliminate unwanted DC offset.

In music mode, a second set of FIR filters are available to support sample rates greater than 50kHz. The filters can be independently selected for DAI1 and DAI2 and support both the playback and record audio paths.

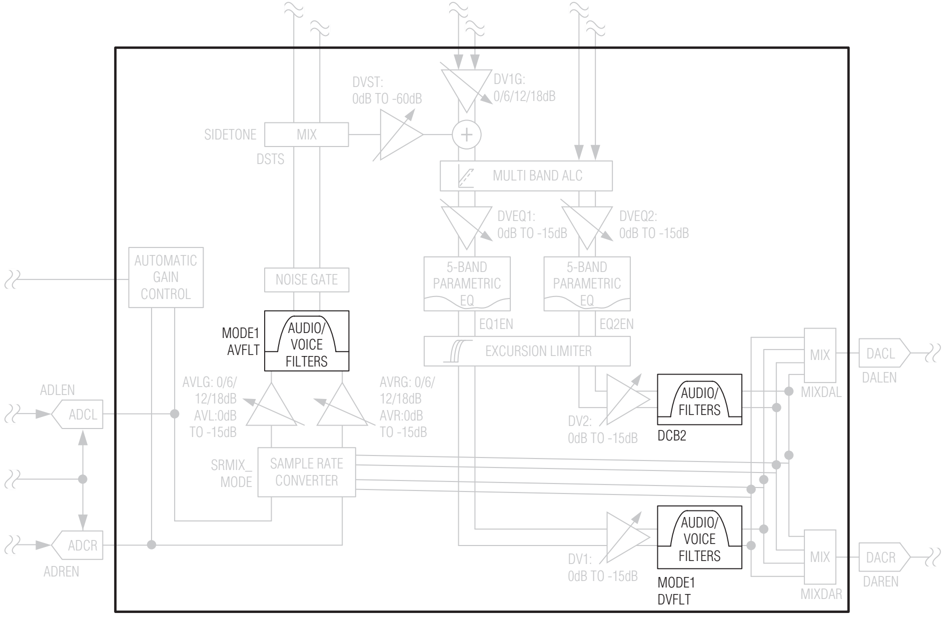
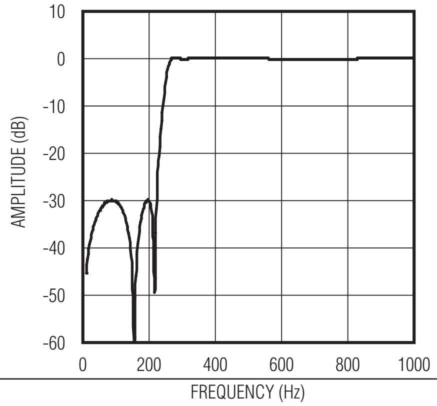
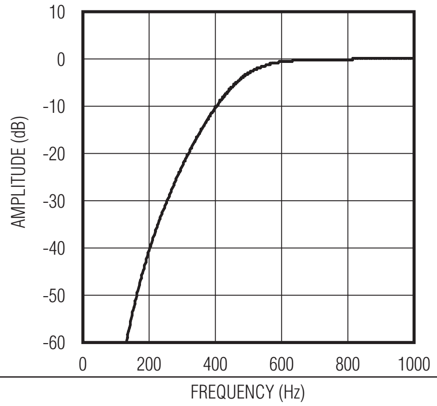
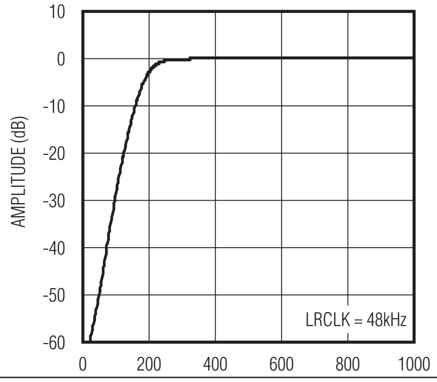


Figure 19. Digital Passband Filtering Block Diagram

Table 14. Passband Filtering Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="2">DESCRIPTION</th></tr>
<tr><td rowspan="10">0x18</td><td>7</td><td>MODE1</td><td colspan="2">DAI1 Passband Filtering Mode
0 = Voice filters
1 = Music filters (recommended for f_S > 24kHz)</td></tr>
<tr><td>6</td><td rowspan="4">AVFLT1</td><td colspan="2">DAI1 ADC Highpass Filter Mode</td></tr>
<tr><td>5</td><td>MODE1</td><td>AVFLT1</td></tr>
<tr><td rowspan="2">4</td><td>0</td><td>See Table 15.</td></tr>
<tr><td>1</td><td>Select a nonzero value to enable the DC- blocking filter.</td></tr>
<tr><td>3</td><td>DHF1</td><td colspan="2">DAI1 High Sample Rate Mode
Selects the sample rate range.
0 = 8kHz ≤ LRCLK ≤ 48kHz
1 = 48kHz ≤ LRCLK ≤ 96kHz</td></tr>
<tr><td>2</td><td rowspan="4">DVFLT1</td><td colspan="2">DAI1 DAC Highpass Filter Mode</td></tr>
<tr><td rowspan="2">1</td><td>MODE1</td><td>DVFLT1</td></tr>
<tr><td>0</td><td>See Table 15.</td></tr>
<tr><td>0</td><td>1</td><td>Select a nonzero value to enable the DC-blocking filter.</td></tr>
<tr><td rowspan="2">0x20</td><td>3</td><td>DHF2</td><td colspan="2">DAI2 High Sample Rate Mode
Selects the sample rate range.
0 = 8kHz ≤ LRCLK ≤ 48kHz
1 = 48kHz < LRCLK ≤ 96kHz</td></tr>
<tr><td>0</td><td>DCB2</td><td colspan="2">DAI2 DC Blocking Filter
Enables a DC-blocking filter on the DAI2 playback audio path.
0 = Disabled
1 = Enabled</td></tr>
</table>

Table 15. Voice Highpass Filters

AVFTL/DVFLT VALUE	INTENDED SAMPLE RATE	FILTER RESPONSE
000	N/A	Disabled
001/011	16kHz/8kHz	
010/100	16kHz/8kHz	
101	8kHz to 48kHz	
110/111	N/A	Reserved

Playback Path Signal Processing

The IC playback signal path includes automatic level control (ALC) and a 5-band parametric equalizer (EQ) (Figure 20). The DAI1 and DAI2 playback paths include separate ALCs controlled by a single set of registers. Two completely separate parametric EQs are included for the DAI1 and DAI2 playback paths.

Automatic Level Control

The automatic level control (ALC) circuit ensures maximum signal amplitude without producing audible clipping. This is accomplished by a variable gain stage that works on a sample by sample basis to increase the gain up to 12dB. A look-ahead circuit determines if the next sample exceeds full scale and reduces the gain so that the sample is exactly full scale.

A programmable low signal threshold determines the minimum signal amplitude that is amplified. Select a threshold that prevents the amplification of background noise. When the signal level drops below the low signal threshold, the ALC reduces the gain to 0dB until the signal increases above the threshold. Figure 21 shows an example of ALC input vs. output curves.

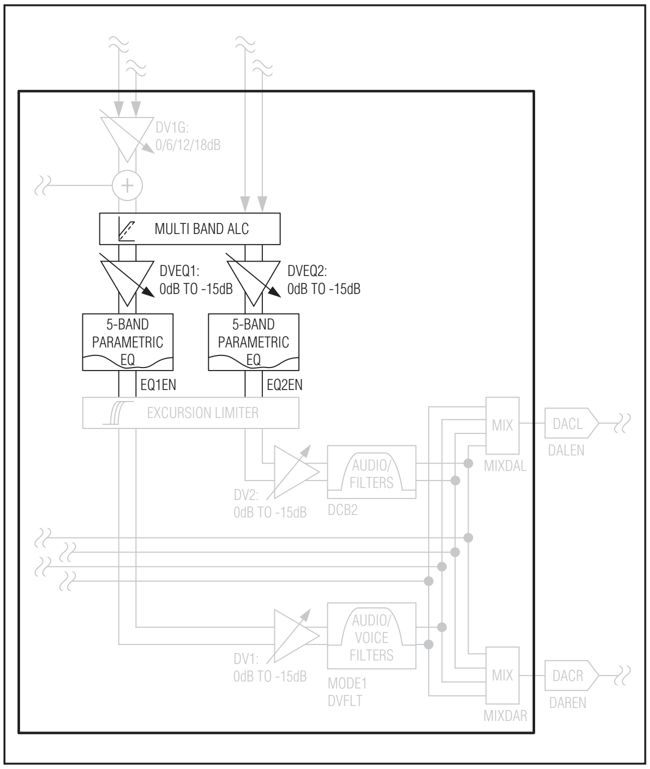


Figure 20. Playback Path Signal Processing Block Diagram

The ALC can optionally be configured in multiband mode. In this mode, the input signal is filtered into two bands with a 5kHz center frequency. Each band is routed through independent ALCs and then summed together. In multiband mode, both bands use the same parameters.

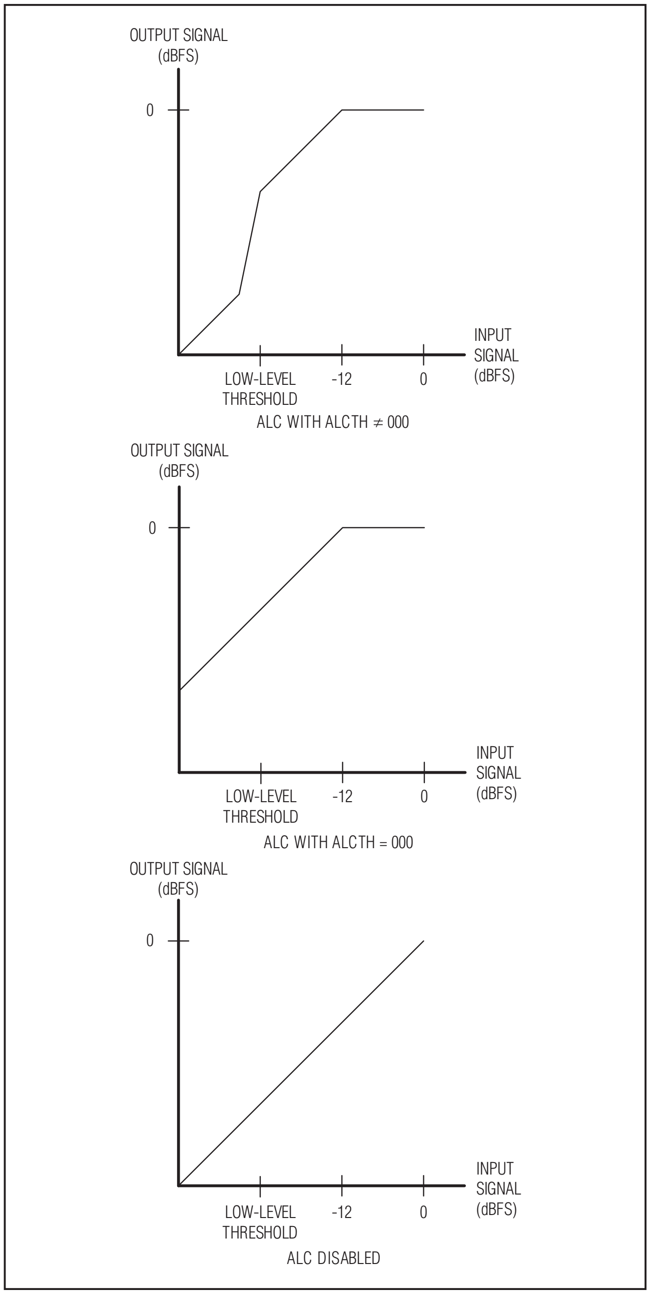


Figure 21. ALC Input vs. Output Examples

Table 16. Automatic Level Control Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="2">DESCRIPTION</th></tr>
<tr><td rowspan="15">0x43</td><td>7</td><td>ALCEN</td><td colspan="2">ALC Enable
Enables ALC on both the DAI1 and DAI2 playback paths.
0 = Disabled
1 = Enabled</td></tr>
<tr><td rowspan="2">6</td><td rowspan="10">ALCRLS</td><td colspan="2">ALC and Excursion Limiter Release Time
Sets the release time for both the ALC and Excursion Limiter. See the <i>Excursion Limiter</i> section for Excursion Limiter release times. ALC release time is defined as the time required to adjust the gain from 12dB to 0dB.</td></tr>
<tr><td>VALUE</td><td>ALC RELEASE TIME (s)</td></tr>
<tr><td rowspan="4">5</td><td>000</td><td>8</td></tr>
<tr><td>001</td><td>4</td></tr>
<tr><td>010</td><td>2</td></tr>
<tr><td>011</td><td>1</td></tr>
<tr><td rowspan="4">4</td><td>100</td><td>0.5</td></tr>
<tr><td>101</td><td>0.25</td></tr>
<tr><td>110</td><td>Reserved</td></tr>
<tr><td>111</td><td>Reserved</td></tr>
<tr><td>3</td><td>ALCMB</td><td colspan="2">Multiband Enable
Enables dual-band processing with a 5kHz center frequency. SR1 and SR2 must be configured properly to achieve the correct center frequency for each playback path.
0 = Single-band ALC
1 = Dual-band ALC</td></tr>
<tr><td>2</td><td rowspan="3">ALCTH</td><td colspan="2" rowspan="3">Low Signal Threshold
Selects the minimum signal level to be boosted by the ALC.
000 = -∞dB (low-signal threshold disabled)
001 = -12dB
010 = -18dB
011 = -24dB
100 = -30dB
101 = -36dB
110 = -42dB
111 = -48dB</td></tr>
<tr><td>1</td></tr>
<tr><td>0</td></tr>
</table>

Parametric Equalizer

The parametric EQ contains five independent biquad filters with programmable gain, center frequency, and bandwidth. Each biquad filter has a gain range of ±12dB and a center frequency range from 20Hz to 20kHz. Use a filter Q less than that shown in Figure 22 to achieve ideal frequency responses. Setting a higher Q results in non-ideal frequency response. The biquad filters are series connected, allowing a total gain of ±60dB.

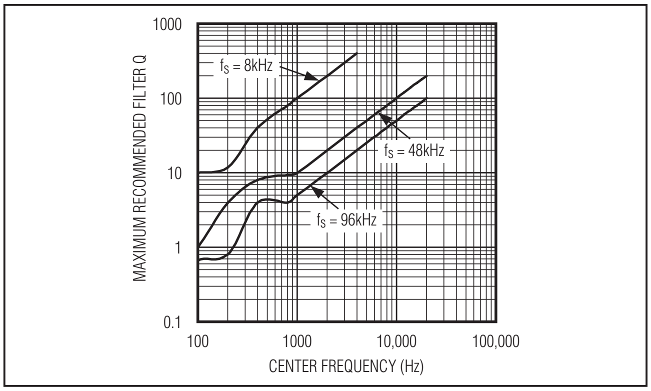


Figure 22. Maximum Recommended Filter Q vs. Frequency

The transfer function for the parametric EQ biquad coefficients is:

$$H(z) = \frac{(1/2[(1+k_2)+K(1-k_2)]+k_1(1+k_2)z^{(-1)}+1/2[(1+k_2)-K(1-k_2)]z^{(-2)})}{(1+k_1(1+k_2)z^{(-1)}+k_2z^{(-2)})}$$

The coefficients K, K1, K2, c1, and c2 are sample rate dependant and stored in registers 0x52 through 0xB5. Separate parametric EQ settings can be stored for the DAI1 and DAI2 playback paths. The MAX98089 EV kit software includes a graphic interface for generating the parametric EQ biquad coefficients.he parameters for the 5-band equalizer must be calculated by software, then programmed into the I2C registers. Hardware calculates the final parameters based on the I2C bits. Table 17 shows the parameter calculations.

Table 17. 5-Band Equalizer Parameters

	INPUT PARAMETER	INTERMEDIATE PARAMETER	OUTPUT PARAMETER
Software	Center Freq = cenf (Hz) Cutoff Freq = cutf (Hz) Gain = G (dB) Sampling Rate = fs (Hz)	$BW = \frac{\pi \times (\text{cutf - cenf})}{\text{fs}}$ $\Omega_0 = \frac{2\pi \times \text{cenf}}{\text{fs}}$ $y = \sqrt{K} \tan\left(\frac{BW}{2}\right)$	$K = 10^{\frac{G}{20dB}}$ $k_1 = \text{-}\cos(\Omega_0)$ $k_2 = \frac{1 - \frac{y}{\sqrt{K}}}{1 + \frac{y}{\sqrt{K}}}$ $c_1 = \sqrt{1 - k_1{}^2}$ $c_2 = \sqrt{1 - k_2{}^2}$
Hardware	K k1 k2 c1 c2	K1 = ½ [1+K] K2 = ½ [1-K]	K1 K2 k1 k2 c1 c2

Use the attenuator at the EQ's input to avoid clipping the signal. The attenuator can be programmed for fixed attenuation or dynamic attenuation based on signal level. If the dynamic EQ clip detection is enabled, the signal level from the EQ is fed back to the attenuator circuit to determine the amount of gain reduction necessary to avoid clipping.

The MAX98089 EV kit software includes a graphical interface for generating the EQ coefficients. The coefficients are sample rate dependent and stored in registers 0x52 through 0xB5.

Table 18. EQ Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="11">0x30/0x32</td><td>4</td><td>$\overline{\text{EQCLP1}}$/
$\overline{\text{EQCLP2}}$</td><td colspan="4">DAI1/DAI2 EQ Clip Detection
Automatically controls the EQ attenuator to prevent clipping in the EQ.
0 = Enabled
1 = Disabled</td></tr>
<tr><td>3</td><td rowspan="10">DVEQ1/DVEQ2</td><td colspan="4">DAI1/DAI2 EQ Attenuator
Provides attenuation to prevent clipping in the EQ when full-scale signals are boosted. DVEQ1/DVEQ2 operates only when EQ1EN/EQ2EN = 1 and $\overline{\text{EQCLP1}}$/$\overline{\text{EQCLP2}}$ = 1.</td></tr>
<tr><td rowspan="3">2</td><td>VALUE</td><td>GAIN (dB)</td><td>VALUE</td><td>GAIN (dB)</td></tr>
<tr><td>0x0</td><td>0</td><td>0x8</td><td>-8</td></tr>
<tr><td>0x1</td><td>-1</td><td>0x9</td><td>-9</td></tr>
<tr><td rowspan="3">1</td><td>0x2</td><td>-2</td><td>0xA</td><td>-10</td></tr>
<tr><td>0x3</td><td>-3</td><td>0xB</td><td>-11</td></tr>
<tr><td>0x4</td><td>-4</td><td>0xC</td><td>-12</td></tr>
<tr><td rowspan="3">0</td><td>0x5</td><td>-5</td><td>0xD</td><td>-13</td></tr>
<tr><td>0x6</td><td>-6</td><td>0xE</td><td>-14</td></tr>
<tr><td>0x7</td><td>-7</td><td>0xF</td><td>-15</td></tr>
<tr><td rowspan="5">0x49</td><td>7</td><td>$\overline{\text{VS2EN}}$</td><td colspan="4" rowspan="3">See the <i>Click-and-Pop Reduction</i> section.</td></tr>
<tr><td>6</td><td>$\overline{\text{VSEN}}$</td></tr>
<tr><td>5</td><td>$\overline{\text{ZDEN}}$</td></tr>
<tr><td>1</td><td>EQ2EN</td><td colspan="4">DAI2 EQ Enable
0 = Disabled
1 = Enabled</td></tr>
<tr><td>0</td><td>EQ1EN</td><td colspan="4">DAI1 EQ Enable
0 = Disabled
1 = Enabled</td></tr>
</table>

Playback Level Control

The IC includes separate digital level control for the DAI1 and DAI2 playback audio paths. The DAI1 signal path allows boost when MODE1 = 0 and attenuation in any mode. The DAI2 signal path allows attenuation only.

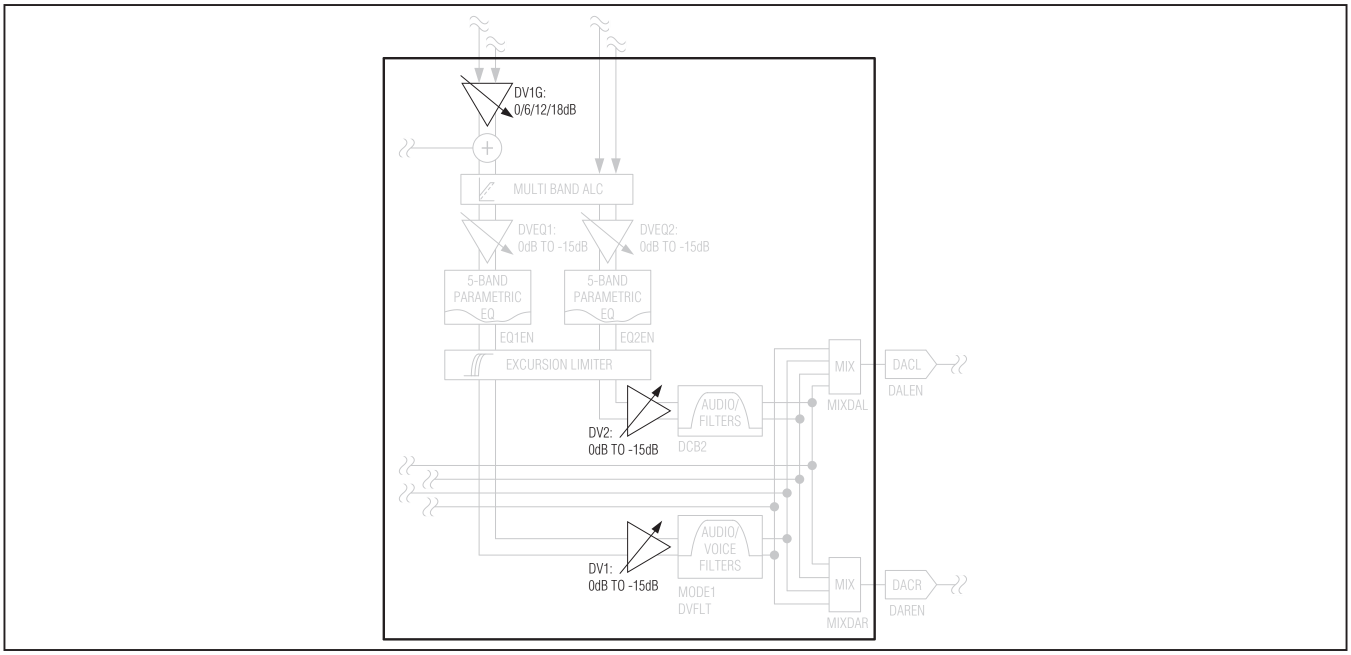


Figure 23. Playback Level Control Block Diagram

Table 19. DAC Playback Level Control Register

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="13">0x2F/0x31</td><td>7</td><td>DV1M/DV2M</td><td colspan="4">DAI1/DAI2 Mute
0 = Disabled
1 = Enabled</td></tr>
<tr><td>5</td><td rowspan="2">DV1G</td><td colspan="4" rowspan="2">DAI1 Voice Mode Gain
DV1G only applies when MODE1 = 0.
00 = 0dB
01 = 6dB
10 = 12dB
11 = 18dB</td></tr>
<tr><td>4</td></tr>
<tr><td rowspan="3">3</td><td rowspan="10">DV1/DV2</td><td colspan="4">DAI1/DAI2 Attenuation</td></tr>
<tr><td>VALUE</td><td>GAIN (dB)</td><td>VALUE</td><td>GAIN (dB)</td></tr>
<tr><td>0x0</td><td>0</td><td>0x8</td><td>-8</td></tr>
<tr><td rowspan="2">2</td><td>0x1</td><td>-1</td><td>0x9</td><td>-9</td></tr>
<tr><td>0x2</td><td>-2</td><td>0xA</td><td>-10</td></tr>
<tr><td rowspan="3">1</td><td>0x3</td><td>-3</td><td>0xB</td><td>-11</td></tr>
<tr><td>0x4</td><td>-4</td><td>0xC</td><td>-12</td></tr>
<tr><td>0x5</td><td>-5</td><td>0xD</td><td>-13</td></tr>
<tr><td rowspan="2">0</td><td>0x6</td><td>-6</td><td>0xE</td><td>-14</td></tr>
<tr><td>0x7</td><td>-7</td><td>0xF</td><td>-15</td></tr>
</table>

DAC Input Mixers

The IC's stereo DAC accepts input from two digital audio paths. The DAC mixer routes any audio path to the left and right DACs (Figure 24).

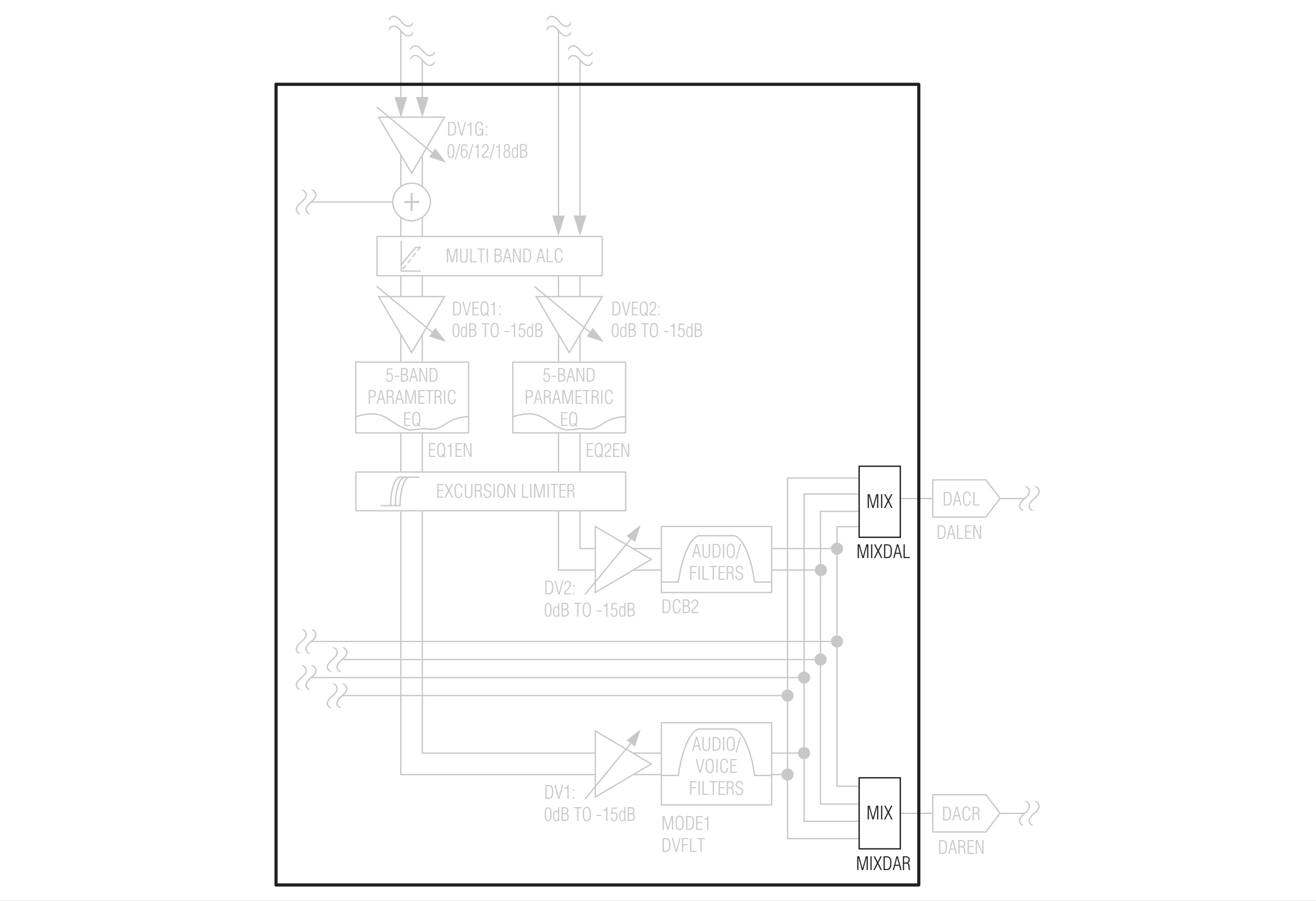


Figure 24. DAC Input Mixer Block Diagram

Table 20. DAC Input Mixer Register

REGISTER	BIT	NAME	DESCRIPTION
0x22	7	MIXDAL	**Left DAC Input Mixer** 1xxx = DAI1 left channel x1xx = DAI1 right channel xx1x = DAI2 left channel xxx1 = DAI2 right channel
	6		
	5		
	4		
	3	MIXDAR	**Right DAC Input Mixer** 1xxx = DAI1 left channel x1xx = DAI1 right channel xx1x = DAI2 left channel xxx1 = DAI2 right channel
	2		
	1		
	0		

Receiver Amplifier

The IC includes a single differential receiver amplifier. The receiver amplifier is designed to drive a 32Ω earpiece speaker. In cases where a single transducer is used for the loudspeaker and receiver, use the SPKBYP switch to route the receiver amplifier output to the left speaker outputs. The receiver amplifier can also be configured as stereo single-ended line outputs using the I²C interface.

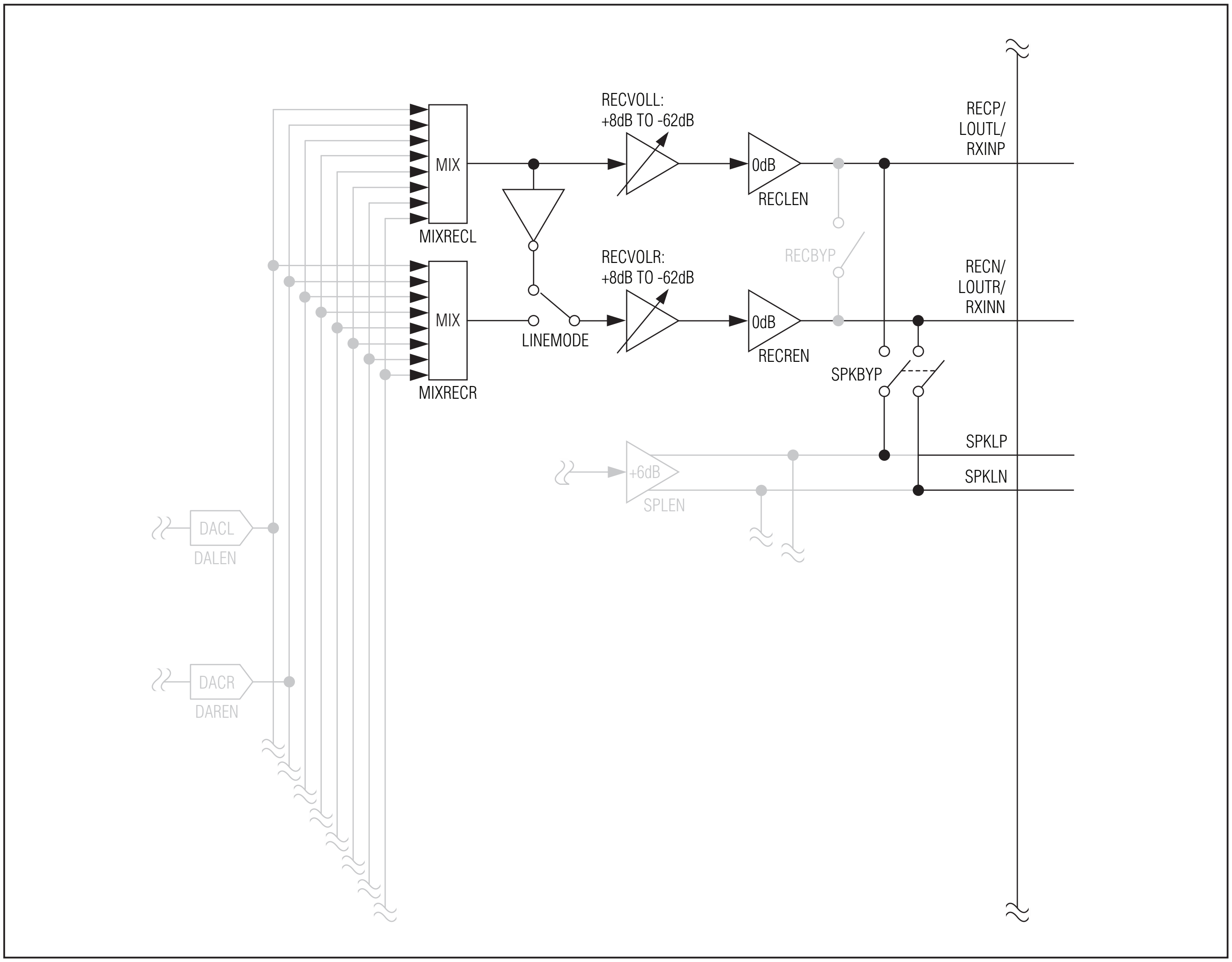


Figure 25. Receiver Amplifier Block Diagram

Receiver Output Mixer

The IC's receiver amplifier accepts input from the stereo DAC, the line inputs (single-ended or differential), and the MIC inputs. Configure the mixer to mix any combination of the available sources. When more than one signal is selected, the mixed signal can be configured to attenuate 6dB, 9dB, or 12dB.

Table 21. Receiver Output Mixer Register

REGISTER	BIT	NAME	DESCRIPTION
0x28	7	MIXRECL	**Left Receiver Output Mixer** 1xxxxxxx = Right DAC x1xxxxxx = MIC2 xx1xxxxx = MIC1 xxx1xxxx = INB2 (INBDIFF = 0) or INB2-INB1 (INADIFF = 1) xxxx1xxx = INB1 xxxxx1xx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxxxx1x = INA1 xxxxxxx1 = Left DAC
	6		
	5		
	4		
	3		
	2		
	1		
	0		
0x29	7	MIXRECR	**Right Receiver Output Mixer** 1xxxxxxx = Left DAC x1xxxxxx = MIC2 xx1xxxxx = MIC1 xxx1xxxx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1) xxxx1xxx = INA1 xxxxx1xx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxxxx1x = INA1 xxxxxxx1 = Right DAC
	6		
	5		
	4		
	3		
	2		
	1		
	0		
0x2A	7	LINE_MODE	**Receiver Output Mode**. Configures receive path output mode between BTL and stereo line output. 0 = BTL 1 = Stereo line output
	3	MIXRECR_GAIN	**Right Receiver Mixer Gain Select** 00 = 0dB 01 = -6dB 10 = -9dB 11 = -12dB
	2		
	1	MIXRECL_GAIN	**Left Receiver Mixer Gain Select** 00 = 0dB 01 = -6dB 10 = -9dB 11 = -12dB
	0		
	0		

Receiver Output Volume

Table 22. Receiver Output Level Register

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="19">0x3B/0x3C</td><td>7</td><td>RECLM/
RECRM</td><td colspan="4">**Receiver Output Mute**
0 = Disabled
1 = Enabled</td></tr>
<tr><td rowspan="2">4</td><td rowspan="18">RECVOLL/
RECVOLR</td><td colspan="4">**Receiver Output Volume Level**</td></tr>
<tr><td>**VALUE**</td><td>**VOLUME (dB)**</td><td>**VALUE**</td><td>**VOLUME (dB)**</td></tr>
<tr><td rowspan="4">3</td><td>0x00</td><td>-62</td><td>0x10</td><td>-10</td></tr>
<tr><td>0x01</td><td>-58</td><td>0x11</td><td>-8</td></tr>
<tr><td>0x02</td><td>-54</td><td>0x12</td><td>-6</td></tr>
<tr><td>0x03</td><td>-50</td><td>0x13</td><td>-4</td></tr>
<tr><td rowspan="4">2</td><td>0x04</td><td>-46</td><td>0x14</td><td>-2</td></tr>
<tr><td>0x05</td><td>-42</td><td>0x15</td><td>0</td></tr>
<tr><td>0x06</td><td>-38</td><td>0x16</td><td>+1</td></tr>
<tr><td>0x07</td><td>-35</td><td>0x17</td><td>+2</td></tr>
<tr><td rowspan="4">1</td><td>0x08</td><td>-32</td><td>0x18</td><td>+3</td></tr>
<tr><td>0x09</td><td>-29</td><td>0x19</td><td>+4</td></tr>
<tr><td>0x0A</td><td>-26</td><td>0x1A</td><td>+5</td></tr>
<tr><td>0x0B</td><td>-23</td><td>0x1B</td><td>+6</td></tr>
<tr><td rowspan="4">0</td><td>0x0C</td><td>-20</td><td>0x1C</td><td>+6.5</td></tr>
<tr><td>0x0D</td><td>-17</td><td>0x1D</td><td>+7</td></tr>
<tr><td>0x0E</td><td>-14</td><td>0x1E</td><td>+7.5</td></tr>
<tr><td>0x0F</td><td>-12</td><td>0x1F</td><td>+8</td></tr>
</table>

Speaker Amplifiers

The IC integrates a stereo filterless Class D amplifier that offers much higher efficiency than Class AB without the typical disadvantages.

The high efficiency of a Class D amplifier is due to the switching operation of the output stage transistors. In a Class D amplifier, the output transistors act as current steering switches and consume negligible additional power. Any power loss associated with the Class D output stage is mostly due to the I^2R loss of the MOSFET on-resistance, and quiescent current overhead.

The theoretical best efficiency of a linear amplifier is 78%, however, that efficiency is only exhibited at peak output power. Under normal operating levels (typical music reproduction levels), efficiency falls below 30%, whereas the IC's Class D amplifier still exhibits 80% efficiency under the same conditions.

Traditional Class D amplifiers require the use of external LC filters or shielding to meet EN55022B and FCC electromagnetic-interference (EMI) regulation standards. Maxim's patented active emissions limiting edge-rate control circuitry reduces EMI emissions, allowing operation without any output filtering in typical applications.

The device is protected from short-circuit damage by a thermal-based shutdown circuit. When a short-circuit condition is present, the temperature of the device rises above the set thermal limit and the output is disabled within 1µs. The speaker output remains disabled for 50µs before the device attempts to re-enable the speaker output. When the short-circuit condition is corrected, the speaker output auto-recovers and normal operation is restored.

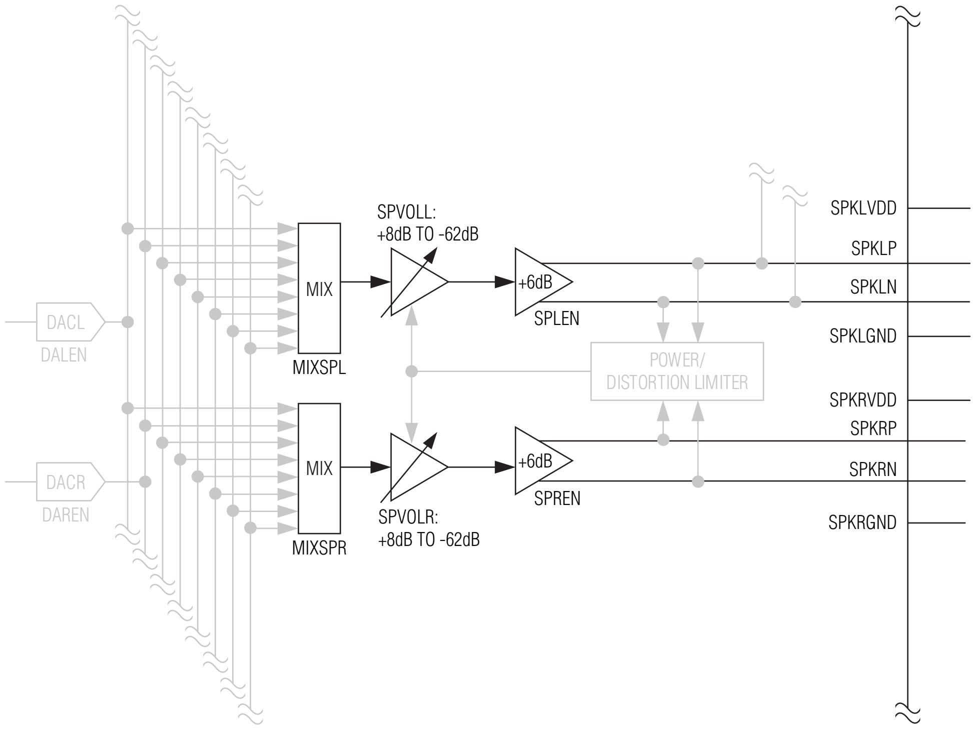


Figure 26. Speaker Amplifier Path Block Diagram

Speaker Output Mixers

The IC’s speaker amplifiers accept input from the stereo DAC, the line inputs (single-ended ore differential), and the MIC inputs. Configure the mixer to mix any combination of the available sources. When more than one signal is selected, the mixer can be configured to attenuate the signal by 6dB, 9dB or 12dB.

Table 23. Speaker Output Mixer Register

REGISTER	BIT	NAME	DESCRIPTION
0x2B	7	MIXSPL	**Left Speaker Output Mixer** 1xxxxxxx = Right DAC x1xxxxxx = MIC2 xx1xxxxx = MIC1 xxx1xxxx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1) xxxx1xxx = INB1 xxxxx1xx = INA2 (INBDIFF = 0) or INA2-INA1 (INADIFF = 1) xxxxxx1x = INA1 xxxxxxx1 = Left DAC
	6		
	5		
	4		
	3		
	2		
	1		
	0		
0x2C	7	MIXSPR	**Right Speaker Output Mixer** 1xxxxxxx = Left DAC x1xxxxxx = MIC2 xx1xxxxx = MIC1 xxx1xxxx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1) xxxx1xxx = INB1 xxxxx1xx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxxxx1x = INA1 xxxxxxx1 = Right DAC
	6		
	5		
	4		
	3		
	2		
	1		
	0		
0x2D	3	MIXSPR_GAIN	**Right Speaker Mixer Gain Select** 00 = 0dB 01 = -6dB 10 = -9dB 11 = -12dB
	2		
	1	MIXSPL_GAIN	**Left Speaker Mixer Gain Select** 00 = 0dB 01 = -6dB 10 = -9dB 11 = -12dB
	0		

Speaker Output Volume

Table 24. Speaker Output Level Register

REGISTER	BIT	NAME	DESCRIPTION			
0x3D/0x3E	7	SPLM/SPRM	**Left/Right Speaker Output Mute** 0 = Disabled 1 = Enabled			
	4	SPVOLL/SPVOLR	**Left/Right Speaker Output Volume Level**			
			VALUE	**VOLUME (dB)**	**VALUE**	**VOLUME (dB)**
			0x00	-62	0x10	-10
			0x01	-58	0x11	-8
	3		0x02	-54	0x12	-6
			0x03	-50	0x13	-4
			0x04	-46	0x14	-2
			0x05	-42	0x15	0
			0x06	-38	0x16	+1
			0x07	-35	0x17	+2
	2		0x08	-32	0x18	+3
			0x09	-29	0x19	+4
			0x0A	-26	0x1A	+5
			0x0B	-23	0x1B	+6
	1		0x0C	-20	0x1C	+6.5
			0x0D	-17	0x1D	+7
			0x0E	-14	0x1E	+7.5
			0x0F	-12	0x1F	+8

Speaker Amplifier Signal Processing

The IC includes signal processing to improve the sound quality of the speaker output and protect transducers from damage. An excursion limiter dynamically adjusts the highpass corner frequency, while a power limiter and distortion limiter prevent the amplifier from outputting too much distortion or power. The excursion limiter is located in the DSP while the distortion limiter and power limiter control the analog volume control (Figure 28). All three limiters analyze the speaker amplifier’s output signal to determine when to take action.

Excursion Limiter

The excursion limiter is a dynamic highpass filter that monitors the speaker outputs and increases the highpass corner frequency when the speaker amplifier’s output exceeds a predefined threshold. The filter smoothly transitions between the high and low corner frequency to prevent unwanted artifacts. The filter can operate in four different modes:

- **Fixed-Frequency Preset Mode.** The highpass corner frequency is fixed at the upper corner frequency and does not change with signal level.
- **Fixed-Frequency Programmable Mode.** The highpass corner frequency is fixed to that specified by the programmable biquad filter.
- **Preset Dynamic Mode.** The highpass filter automatically slides between a preset upper and lower corner frequency based on output signal level.
- **User-Programmable Dynamic Mode.** The highpass filter slides between a user-programmed biquad filter on the low side to a predefined corner frequency on the high side.

The transfer function for the user-programmable biquad is:

$$H(z) = \frac{b_0 + b_1 z^{-1} + b_2 z^{-2}}{1 + a_1 z^{-1} + a_2 z^{-2}}$$

The coefficients b_0, b_1, b_2, a_1, and a_2 are sample rate dependent and stored in registers 0xB4 through 0xC7. Store b_0, b_1, and b_2 as positive numbers. Store a_1 and a_2 as negated two's complement numbers. Separate filters can be stored for the DAI1 and DAI2 playback paths.

The MAX98089 EV kit software includes a graphic interface for generating the user-programmable biquad coefficients.

Note: Only change the excursion limiter settings when the signal path is disabled to prevent undesired artifacts.

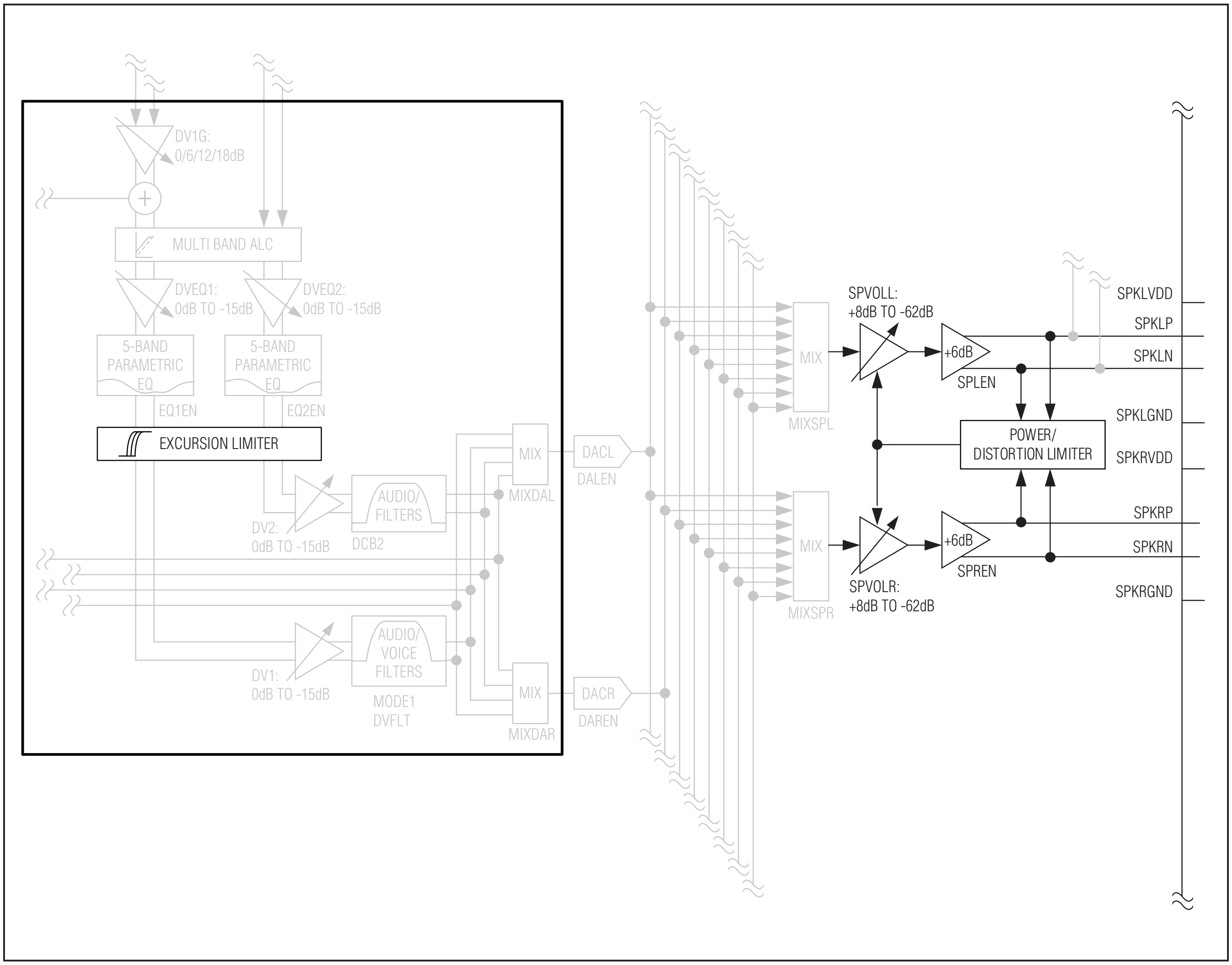


Figure 27. Speaker Amplifier Signal Processing Block Diagram

Table 25. Excursion Limiter Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="5">DESCRIPTION</th></tr>
<tr><td rowspan="15">0x41</td><td>6</td><td rowspan="7">DHPUCF</td><td colspan="5">Excursion Limiter Corner Frequency
The excursion limiter has limited sliding range and minimum corner frequencies. Listed below are all the valid filter combinations.</td></tr>
<tr><td rowspan="2">5</td><td>LOWER CORNER FREQUENCY</td><td>UPPER CORNER FREQUENCY</td><td>MINIMUM BIQUAD CORNER FREQUENCY</td><td>DHPUCF</td><td>DHPLCF</td></tr>
<tr><td colspan="2">Excursion limiter disabled</td><td>—</td><td>000</td><td>00</td></tr>
<tr><td rowspan="4">4</td><td colspan="2">400Hz</td><td>—</td><td>001</td><td>00</td></tr>
<tr><td colspan="2">600Hz</td><td>—</td><td>010</td><td>00</td></tr>
<tr><td colspan="2">800Hz</td><td>—</td><td>011</td><td>00</td></tr>
<tr><td colspan="2">1kHz</td><td>—</td><td>100</td><td>00</td></tr>
<tr><td rowspan="4">1</td><td rowspan="8">DHPLCF</td><td colspan="2">Programmable using biquad</td><td>100Hz</td><td>000</td><td>11</td></tr>
<tr><td>200Hz</td><td>400Hz</td><td>—</td><td>001</td><td>01</td></tr>
<tr><td>400Hz</td><td>600Hz</td><td>—</td><td>010</td><td>10</td></tr>
<tr><td>400Hz</td><td>800Hz</td><td>—</td><td>011</td><td>10</td></tr>
<tr><td rowspan="4">0</td><td>Programmable using biquad</td><td>400Hz</td><td>200Hz</td><td>001</td><td>11</td></tr>
<tr><td>Programmable using biquad</td><td>600Hz</td><td>300Hz</td><td>010</td><td>11</td></tr>
<tr><td>Programmable using biquad</td><td>800Hz</td><td>400Hz</td><td>011</td><td>11</td></tr>
<tr><td>Programmable using biquad</td><td>1kHz</td><td>500Hz</td><td>100</td><td>11</td></tr>
<tr><td rowspan="10">0x43</td><td rowspan="2">6</td><td rowspan="10">ALCRLS</td><td colspan="5">ALC and Excursion Limiter Release Time
Sets the release time for both the ALC and Excursion Limiter. See the <i>Automatic Level Control</i> section for ALC release times. Excursion limiter release time is defined as the time required to slide from the high corner frequency to the low corner frequency.</td></tr>
<tr><td colspan="2">VALUE</td><td colspan="3">EXCURSION LIMITER RELEASE TIME (s)</td></tr>
<tr><td rowspan="4">5</td><td colspan="2">000</td><td colspan="3">4</td></tr>
<tr><td colspan="2">001</td><td colspan="3">2</td></tr>
<tr><td colspan="2">010</td><td colspan="3">1</td></tr>
<tr><td colspan="2">011</td><td colspan="3">0.5</td></tr>
<tr><td rowspan="4">4</td><td colspan="2">100</td><td colspan="3">0.25</td></tr>
<tr><td colspan="2">101</td><td colspan="3">0.25</td></tr>
<tr><td colspan="2">110</td><td colspan="3">Reserved</td></tr>
<tr><td colspan="2">111</td><td colspan="3">Reserved</td></tr>
<tr><td rowspan="4">0x42</td><td>3</td><td rowspan="4">DHPTH</td><td colspan="5" rowspan="4">Excursion Limiter Threshold
Measured at the Class D speaker amplifier outputs. Signals above the threshold use the upper corner frequency. Signals below the threshold use the lower corner frequency. V_{BAT} must correctly reflect the voltage of SPKLVDD to achieve accurate thresholds.
000 = 0.34V_P
001 = 0.71V_P
010 = 1.30V_P
011 = 1.77V_P
100 = 2.33V_P
101 = 3.25V_P
110 = 4.25V_P
111 = 4.95V_P</td></tr>
<tr><td>2</td></tr>
<tr><td>1</td></tr>
<tr><td>0</td></tr>
</table>

Power Limiter

The IC's power limiter tracks the continuous power delivered to the loudspeaker and briefly mutes the speaker amplifier output if the speaker is at risk of sustaining permanent damage.

Loudspeakers are typically damaged when the voice coil overheats due to extended operation above the rated power. During normal operation, heat generated in the voice coil is transferred to the speaker's magnet, which transfers heat to the surrounding air. For the voice coil to overheat, both the voice coil and the magnet must overheat. The result is that a loudspeaker can operate above its rated power for a significant time before it heats sufficiently to cause damage.

The IC's power limiter includes user-programmable time constants and power thresholds to match a wide range of loudspeakers. Program the power limiter's threshold to match the loudspeaker's rated power handling. This can be determined through measurement or the loudspeaker's specification. Program time constant 1 to match the voice coil's thermal time constant. Program time constant 2 to match the magnet's thermal time constant. The time constants can be determined by plotting the voice coil's resistance vs. time as power is applied to the speaker.

Table 26. Power Limiter Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="20">0x44</td><td>7</td><td rowspan="10">PWRTH</td><td colspan="4">Power Limiter Threshold
If the continuous output power from the speaker amplifiers exceeds this threshold, the output is briefly muted to protect the speaker. The threshold is measured in watts assuming an 8Ω load. VBAT must correctly reflect the voltage of SPKLVDD/ SPKRVDD to achieve accurate thresholds.</td></tr>
<tr><td rowspan="2">6</td><td>VALUE</td><td>THRESHOLD (W)</td><td>VALUE</td><td>THRESHOLD (W)</td></tr>
<tr><td>0x0</td><td>Power limiter disabled</td><td>0x8</td><td>0.27</td></tr>
<tr><td rowspan="4">5</td><td>0x1</td><td>0.05</td><td>0x9</td><td>0.35</td></tr>
<tr><td>0x2</td><td>0.06</td><td>0xA</td><td>0.48</td></tr>
<tr><td>0x3</td><td>0.09</td><td>0xB</td><td>0.72</td></tr>
<tr><td>0x4</td><td>0.11</td><td>0xC</td><td>1.00</td></tr>
<tr><td rowspan="3">4</td><td>0x5</td><td>0.13</td><td>0xD</td><td>1.43</td></tr>
<tr><td>0x6</td><td>0.18</td><td>0xE</td><td>1.57</td></tr>
<tr><td>0x7</td><td>0.22</td><td>0xF</td><td>1.80</td></tr>
<tr><td>2</td><td rowspan="10">PWRK</td><td colspan="4">Power Limiter Weighting Factor
Determines the balance between time constant 1 and 2 to match the dominance of each time constant in the loudspeaker.</td></tr>
<tr><td rowspan="5">1</td><td>VALUE</td><td colspan="2">T1 (%)</td><td>T2 (%)</td></tr>
<tr><td>000</td><td colspan="2">50</td><td>50</td></tr>
<tr><td>001</td><td colspan="2">62.5</td><td>37.5</td></tr>
<tr><td>010</td><td colspan="2">75</td><td>25</td></tr>
<tr><td>011</td><td colspan="2">87.5</td><td>12.5</td></tr>
<tr><td rowspan="4">0</td><td>100</td><td colspan="2">100</td><td>0</td></tr>
<tr><td>101</td><td colspan="2">12.5</td><td>87.5</td></tr>
<tr><td>110</td><td colspan="2">25</td><td>75</td></tr>
<tr><td>111</td><td colspan="2">37.5</td><td>62.5</td></tr>
</table>

Table 26. Power Limiter Registers (continued)

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="20">0x45</td><td>7</td><td rowspan="10">PWRT2</td><td colspan="4">Power Limiter Time Constant 2
Select a value that matches the thermal time constant of the loudspeaker’s magnet.</td></tr>
<tr><td rowspan="3">6</td><td>VALUE</td><td>TIME CONSTANT (min)</td><td>VALUE</td><td>TIME CONSTANT (min)</td></tr>
<tr><td>0x0</td><td>Disabled</td><td>0x8</td><td>3.75</td></tr>
<tr><td>0x1</td><td>0.50</td><td>0x9</td><td>5.00</td></tr>
<tr><td rowspan="2">5</td><td>0x2</td><td>0.67</td><td>0xA</td><td>6.66</td></tr>
<tr><td>0x3</td><td>0.89</td><td>0xB</td><td>8.88</td></tr>
<tr><td rowspan="4">4</td><td>0x4</td><td>1.19</td><td>0xC</td><td>Reserved</td></tr>
<tr><td>0x5</td><td>1.58</td><td>0xD</td><td>Reserved</td></tr>
<tr><td>0x6</td><td>2.11</td><td>0xE</td><td>Reserved</td></tr>
<tr><td>0x7</td><td>2.81</td><td>0xF</td><td>Reserved</td></tr>
<tr><td>3</td><td rowspan="10">PWRT1</td><td colspan="4">Power Limiter Time Constant 1
Select a value that matches the thermal time constant of the loudspeaker’s voice coil.</td></tr>
<tr><td rowspan="3">2</td><td>VALUE</td><td>TIME CONSTANT (s)</td><td>VALUE</td><td>TIME CONSTANT (s)</td></tr>
<tr><td>0x0</td><td>Disabled</td><td>0x8</td><td>3.75</td></tr>
<tr><td>0x1</td><td>0.50</td><td>0x9</td><td>5.00</td></tr>
<tr><td rowspan="3">1</td><td>0x2</td><td>0.67</td><td>0xA</td><td>6.66</td></tr>
<tr><td>0x3</td><td>0.89</td><td>0xB</td><td>8.88</td></tr>
<tr><td>0x4</td><td>1.19</td><td>0xC</td><td>Reserved</td></tr>
<tr><td rowspan="3">0</td><td>0x5</td><td>1.58</td><td>0xD</td><td>Reserved</td></tr>
<tr><td>0x6</td><td>2.11</td><td>0xE</td><td>Reserved</td></tr>
<tr><td>0x7</td><td>2.81</td><td>0xF</td><td>Reserved</td></tr>
</table>

Distortion Limiter

The IC’s distortion limiter ensures that the speaker amplifier’s output does not exceed the programmed THD+N limit. The distortion limiter analyzes the Class D output duty cycle to determine the percentage of the waveform that is clipped. If the distortion exceeds the programmed threshold, the output gain is reduced.

Table 27. Distortion Limiter Registers

<table>
<tr><th>REGISTER</th><th>BIT</th><th>NAME</th><th colspan="4">DESCRIPTION</th></tr>
<tr><td rowspan="14">0x46</td><td>7</td><td rowspan="13">THDCLP</td><td colspan="4">Distortion Limit
Measured in % THD+N.</td></tr>
<tr><td rowspan="2">6</td><td>VALUE</td><td>THD+N LIMIT (%)</td><td>VALUE</td><td>THD+N LIMIT (%)</td></tr>
<tr><td>0x0</td><td>Limiter disabled</td><td>0x8</td><td>12</td></tr>
<tr><td rowspan="3">5</td><td>0x1</td><td>< 1</td><td>0x9</td><td>14</td></tr>
<tr><td>0x2</td><td>1</td><td>0xA</td><td>16</td></tr>
<tr><td>0x3</td><td>2</td><td>0xB</td><td>18</td></tr>
<tr><td rowspan="4">4</td><td>0x4</td><td>4</td><td>0xC</td><td>20</td></tr>
<tr><td>0x5</td><td>6</td><td>0xD</td><td>21</td></tr>
<tr><td>0x6</td><td>8</td><td>0xE</td><td>22</td></tr>
<tr><td>0x7</td><td>10</td><td>0xF</td><td>24</td></tr>
<tr><td>0</td><td>THDT1</td><td colspan="4">Distortion Limiter Release Time Constant
Duration of time required for the speaker amplifier’s output gain to adjust back to the nominal level after a large signal has passed.
0 = 1.4s
1 = 2.8s</td></tr>
</table>

Headphone

DirectDrive Headphone Amplifier

Traditional single-supply headphone amplifiers have outputs biased at a nominal DC voltage (typically half the supply). Large coupling capacitors are needed to block this DC bias from the headphone. Without these capacitors, a significant amount of DC current flows to the headphone, resulting in unnecessary power dissipation and possible damage to both headphone and headphone amplifier.

Maxim’s second-generation DirectDrive architecture uses a charge pump to create an internal negative supply voltage. This allows the headphone outputs of the ICs to be biased at GND while operating from a single supply (Figure 1). Without a DC component, there is no need for the large DC-blocking capacitors. Instead of two large (220μF typ) capacitors, the IC’s charge pump requires 3 small ceramic capacitors, conserving board space, reducing cost, and improving the frequency response of the headphone amplifier.

Charge Pump

The dual-mode charge pump generates both the positive and negative power supply for the headphone amplifier. To maximize efficiency, both the charge pump’s switching frequency and output voltage change based on signal level.

When the input signal level is less than 10% of PVDD, the switching frequency is reduced to a low rate. This minimizes switching losses in the charge pump. When the input signal exceeds 10% of PVDD, the switching frequency increases to support the load current.

For input signals below 25% of PVDD, the charge pump generates ±(PVDD/2) to minimize the voltage drop across the amplifier’s power stage and thus improve efficiency. Input signals that exceed 25% of PVDD cause the charge pump to output ±PVDD. The higher output voltage allows for full output power from the headphone amplifier.

To prevent audible gliches when transitioning from the ±(PVDD/2) output mode to the ±PVDD output mode, the charge pump transitions very quickly. This quick change draws significant current from PVDD for the duration of the transition. The bypass capacitor on PVDD supplies the required current and prevents droop on PVDD.

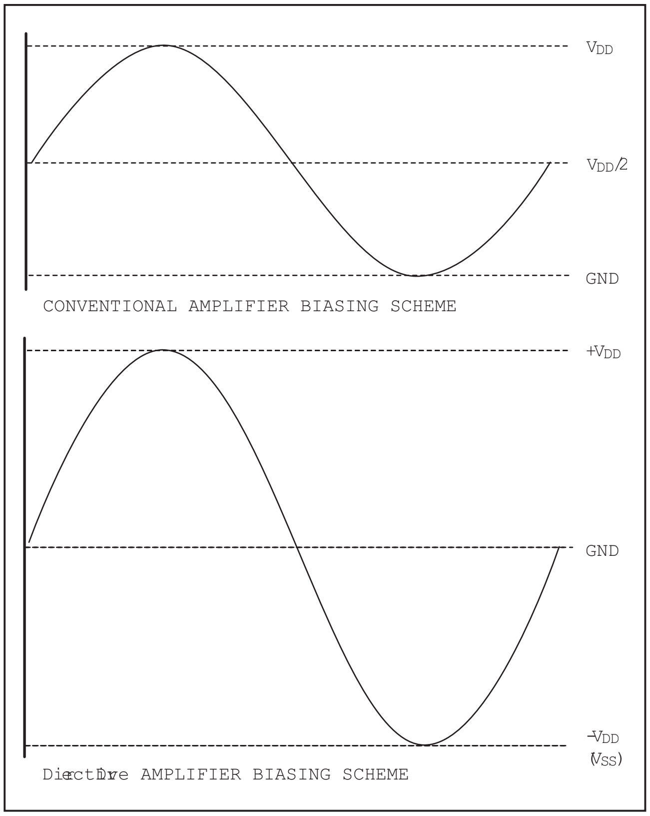


Figure 28. Traditional Amplifier Output vs. DirectDrive Output

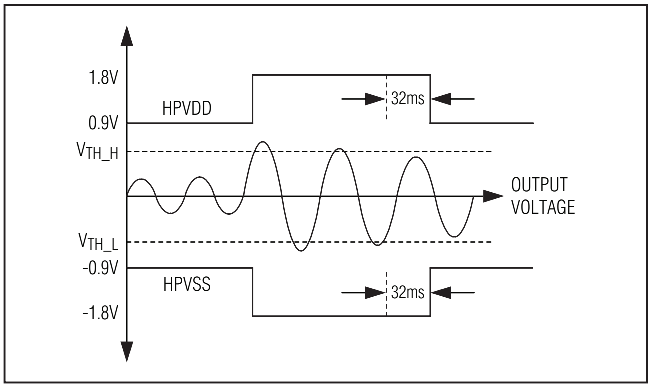


Figure 29. Class H Operation

Class H Operation

A Class H amplifier uses a Class AB output stage with power supplies that are modulated by the output signal. In the case of the ICs, two nominal power-supply differentials of 1.8V (+0.9V to -0.9V) and 3.6V (+1.8V to -1.8V) are available from the charge pump. Figure 29 shows the operation of the output-voltage-dependent power supply.

Headphone Ground Sense (HPSNS)

HPSNS senses the ground return for the headphone load. For optimal performance, connect HPSNS to the ground pole of the jack through an isolated trace, as shown in Figure 30. If HPSNS is not used, connect to the analog ground plane.

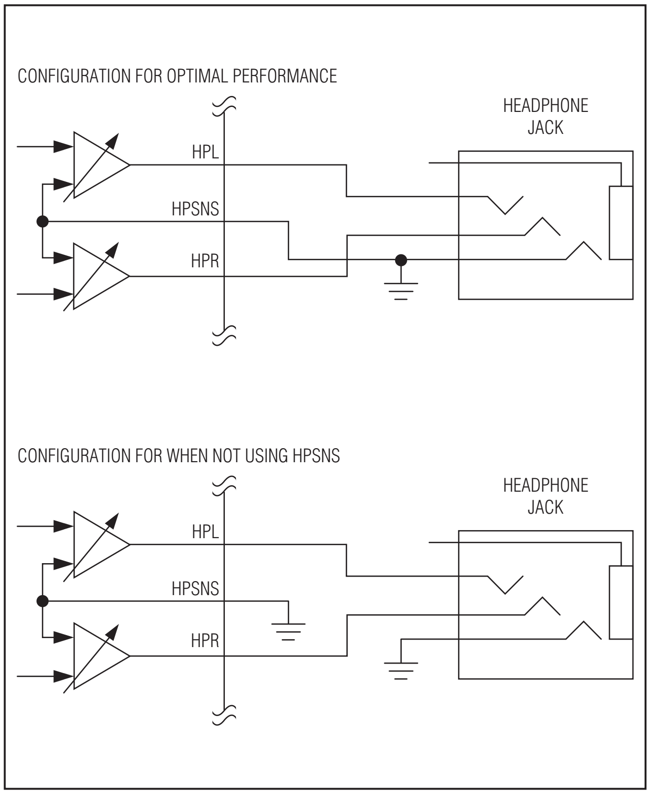


Figure 30. HPSNS Configurations

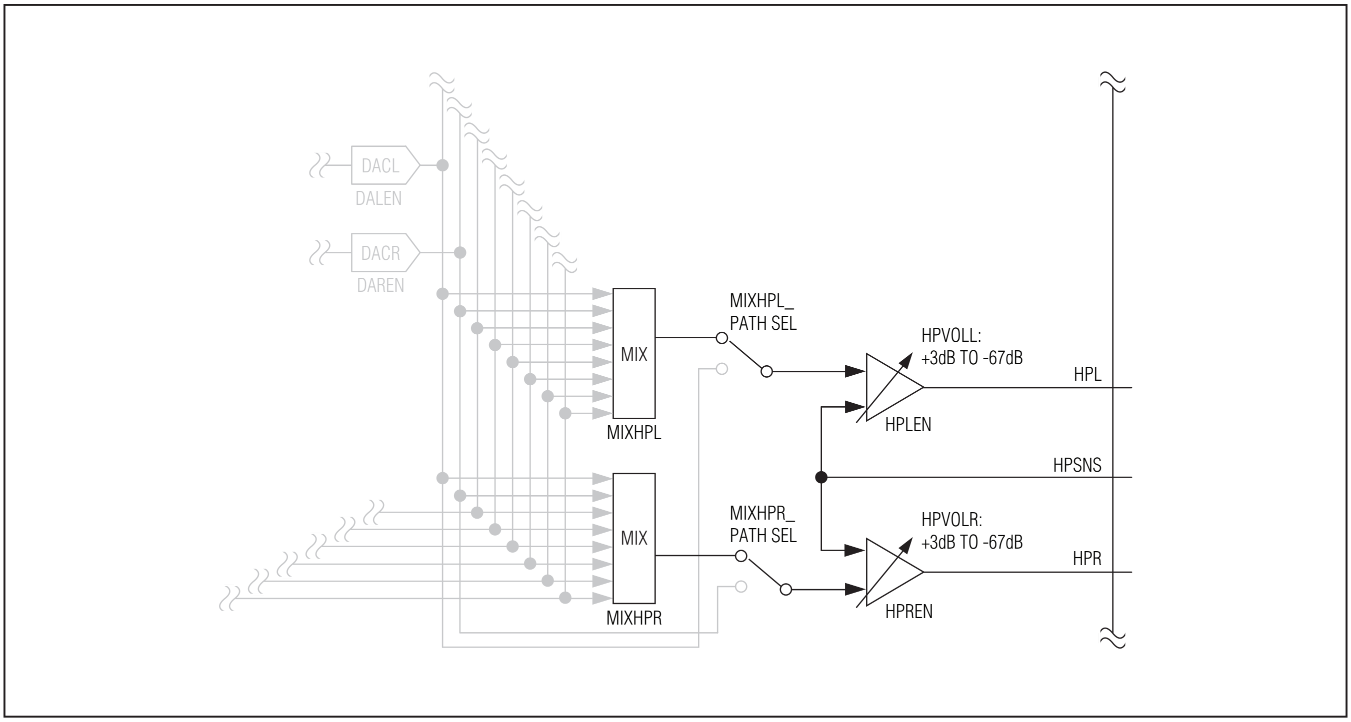


Figure 31. Headphone Amplifier Block Diagram

Headphone Output Mixers

The headphone amplifier mixer accepts input from the stereo DAC, the line inputs (single-ended or differential), and the MIC inputs. Configure the mixer to mix any combination of the available sources. When more than one signal is selected, the mixer can be configured to attenuate the signal by 6dB, 9dB, or 12dB. The stereo DAC can bypass the headphone mixers, and be connected directly to the headphone amplifiers to provide lower power consumption.

Table 28. Headphone Output Mixer Register

REGISTER	BIT	NAME	DESCRIPTION
0x25	7	MIXHPL	**Left Headphone Output Mixer** 1xxxxxxx = Right DAC x1xxxxxx = MIC2 xx1xxxxx = MIC1 xxx1xxxx = INB2 (INBDIFF = 0) or INB2-INB1 (INADIFF = 1) xxxx1xxx = INB1 xxxxx1xx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxxxx1x = INA1 xxxxxxx1 = Left DAC
	6		
	5		
	4		
	3		
	2		
	1		
	0		
0x26	7	MIXHPR	**Right Headphone Output Mixer** 1xxxxxxx = Left DAC x1xxxxxx = MIC2 xx1xxxxx = MIC1 xxx1xxxx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1) xxxx1xxx = INB1 xxxxx1xx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxxxx1x = INA1 xxxxxxx1 = Right DAC
	6		
	5		
	4		
	3		
	2		
	1		
	0		
0x27	5	MIXHPR_ PATH SEL	**Right Headphone Mixer Path Select** 0 = Directly connect to the right DAC (bypass right headphone output mixer) 1 = Right headphone output mixer
	4	MIXHPL_ PATH SEL	**Left Headphone Mixer Path Select** 0 = Directly connect to the left DAC (bypass left headphone output mixer) 1 = Left headphone output mixer
	3	MIXHPR _GAIN	**Right Headphone Mixer Gain Select** 00 = 0dB 01 = -6dB 10 = -9dB 11 = -12dB
	2		
	1	MIXHPL _GAIN	**Left Headphone Mixer Gain Select** 00 = 0dB 01 = -6dB 10 = -9dB 11 = -12dB
	0		

Headphone Output Volume

Table 29. Headphone Output Level Register

REGISTER	BIT	NAME	DESCRIPTION			
0x39/0x3A	7	HPLM/HPRM	**Headphone Output Mute** 0 = Disabled 1 = Enabled			
	4	HPVOLL/HPVOLR	**Left/Right Headphone Output Volume Level**			
			VALUE	**VOLUME (dB)**	**VALUE**	**VOLUME (dB)**
			0x00	-67	0x10	-15
			0x01	-63	0x11	-13
			0x02	-59	0x12	-11
	3		0x03	-55	0x13	-9
			0x04	-51	0x14	-7
			0x05	-47	0x15	-5
			0x06	-43	0x16	-4
	2		0x07	-40	0x17	-3
			0x08	-37	0x18	-2
			0x09	-34	0x19	-1
	1		0x0A	-31	0x1A	0
			0x0B	-28	0x1B	+1
			0x0C	-25	0x1C	+1.5
	0		0x0D	-22	0x1D	+2
			0x0E	-19	0x1E	+2.5
			0x0F	-17	0x1F	+3

Output Bypass Switches

The IC's includes two output bypass switches that solve common applications problems. When a single transducer is used for the loudspeaker and receiver, the need exists for two amplifiers to power the same transducer. Bypass switches connect the IC's receiver amplifier output to the speaker amplifier's output, allowing either amplifier to power the same transducer. In systems where an external receiver amplifier is used, route its output to the left speaker through RECP/RXINP and RECN/RXINN, bypassing the Class D amplifier. In systems where an external amplifier drives both the receiver and the IC's line input, one of the differential signals can be disconnected from the receiver when not needed by passing it through the analog switch that connects RECP/RXINP to RECN/RXINN.

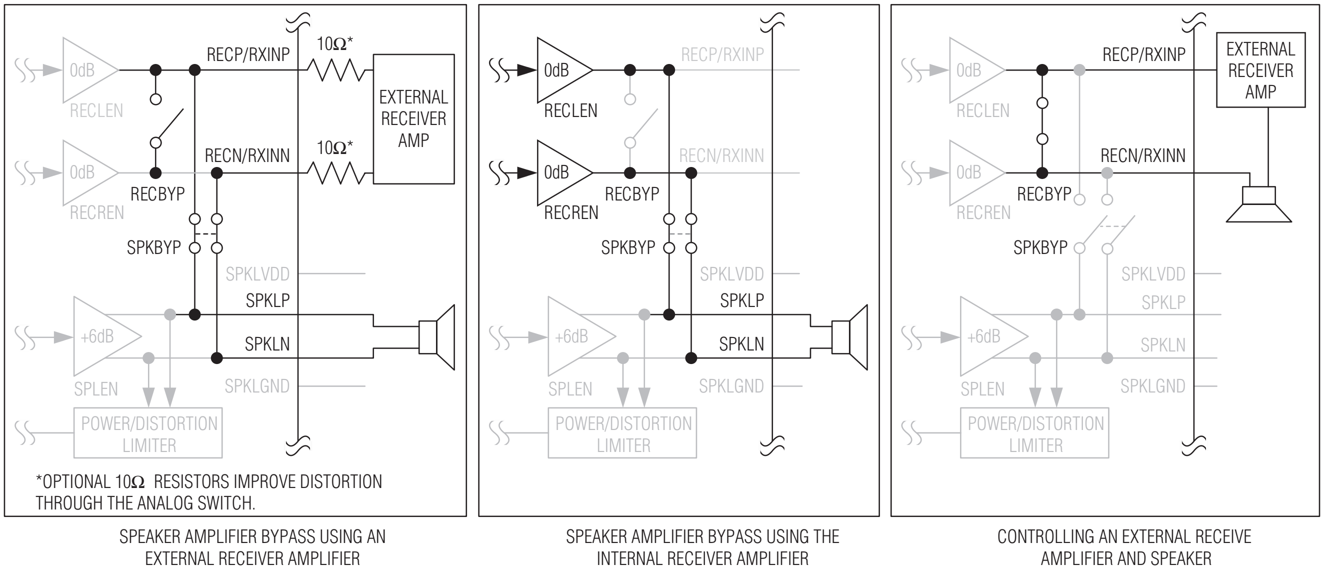


Figure 32. Output Bypass Switch Block Diagrams

Table 30. Output Bypass Switches Register

REGISTER	BIT	NAME	DESCRIPTION
0x4A	7	INABYP	See the *Microphone Inputs* section.
	4	MIC2BYP	
	1	RECBYP	**RXINP to RXINN Bypass Switch** Shorts RXINP to RXINN allowing a signal to pass through the ICs. Disable the receiver amplifier when RECBYP = 1. 0 = Disabled 1 = Enabled
	0	SPKBYP	**RXIN to SPKL Bypass Switch** Shorts RXINP/RXINN to SPKLP/SPKLN allowing either the internal or an external receiver amplifier to power the left speaker. Disable the left speaker amplifier when SPKBYP = 1. 0 = Disabled 1 = Enabled

Click-and-Pop Reduction

The IC includes extensive click-and-pop reduction circuitry. The circuitry minimizes clicks and pops at turn-on, turn-off, and during volume changes.

Zero-crossing detection is implemented on all analog PGAs and volume controls to prevent large glitches when volume changes are made. Instead of making a volume change immediately, the change is made when the audio signal crosses the midpoint. If no zero-crossing occurs within the timeout window, the change is forced.

Volume slewing breaks up large volume changes into the smallest available step size and the steps through each step between the initial and final volume setting. When enabled, volume slewing also occurs at device turn-on and turn-off. During turn-on the volume is set to mute before the output is enabled. Once the output is on, the volume ramps to the desired level. At turn-off the volume is ramped to mute before the outputs are disabled.

When there is no audio signal zero-crossing detection can prevent volume slewing from occurring. Enable enhanced volume slewing to prevent the volume controller from requesting another volume level until the previous one has been set. Each step in the volume ramp then occurs after a zero crossing has occurred in the audio signal or the timeout window has expired. During turn-off, enhance volume slewing is always disabled.

Table 31. Click-and-Pop Reduction Register

REGISTER	BIT	NAME	DESCRIPTION
0x47	7	$\overline{\text{VS2EN}}$	**Enhanced Volume Smoothing** During volume slewing, the controller waits for each step in the ramp to be applied before sending the next step. When zero-crossing detection is enabled this prevents large steps in the output volume when no zero crossings are detected. 0 = Enabled 1 = Disabled Applies to volume changes in HPVOLL, HPVOLR, RECVOL, SPVOLL, and SPVOLR.
	6	$\overline{\text{VSEN}}$	**Volume Adjustment Smoothing** Volume changes are smoothed by stepping through intermediate steps. Also ramps the volume from minimum to the programmed value at turn-on and back to minimum at turn-off. 0 = Enabled 1 = Disabled Applies to volume changes in HPVOLL, HPVOLR, RECVOL, SPVOLL, and SPVOLR.
	5	$\overline{\text{ZDEN}}$	**Zero-Crossing Detection** Holds volume changes until there is a zero crossing in the audio signal. This reduces click and pop during volume changes (zipper noise). If no zero crossing is detected within 100ms, the volume change is forced. 0 = Enabled 1 = Disabled Applies to volume changes in PGAM1, PGAM2, PGAOUTA, PGAOUTB, PGAOUTC, HPVOLL, HPVOLR, RECVOL, SPVOLL, and SPVOLR.
	1	EQ2EN	See the *5-Band Parametric EQ* section.
	0	EQ1EN	

Jack Detection

The IC features jack detection that can detect the insertion and removal of a jack as well as the load type. When a jack is detected, an interrupt on $\overline{\text{IRQ}}$ can be triggered (by setting IJDET) to alert the microcontroller of the event. Figure 33 shows the typical configuration for jack detection.

Jack Insertion

To detect a jack insertion, the IC must have a power supply. Set JDETEN to enable jack detection circuitry and apply a pullup current to JACKSNS. Set JDWK to minimize supply current. Jack insertion can be performed in shutdown or out of shutdown. Clear JDWK to differentiate between headsets with a microphone and headphones without a microphone. The voltage on JACKSNS is equal to SPKLVDD as long as no load is applied to JACKSNS and MICBIAS is disabled. Table 32 shows the change in JKSNS that occurs when a jack is inserted.

Accessory Button Detection

After jack insertion, the MAX98089 can detect button presses on accessories that include a microphone and a switch that shorts the microphone signal to ground. Set JDETEN to enable jack detection circuitry. Button presses can be detected both when MICBIAS is enabled and disabled. Table 33 shows the change in JKSNS that occurs when the accessory button is pressed.

Jack Removal

The IC detects jack removal by monitoring JACKSNS for transitions to the 11 state. Set JDETEN to enable jack detection circuitry. Set JDWK to minimize supply current if button detection is not required. Table 34 shows the change in JKSNS that occurs when a jack is removed. Jack removal can be done in shutdown or out of shutdown.

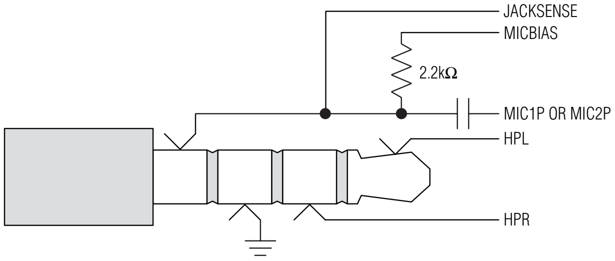


Figure 33. Typical Configuration for Jack Detection

Table 32. Change in JKSNS Upon Jack Insertion

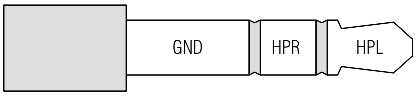
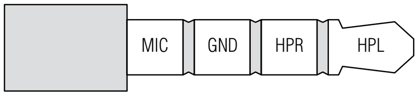
JACK TYPE	JDWK = 1	JDWK = 0
	JKSNS: 11 ➔ 00	JKSNS: 11 ➔ 00
	JKSNS: 11 ➔ 00	JKSNS: 11 ➔ 01

Table 33. Change in JKSNS Upon Button Press

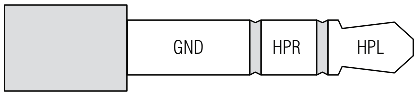
JACK TYPE	MICBIAS ENABLED OR DISABLED
	JKSNS: 01 ➔ 00

Table 34. Change in JKSNS Upon Jack Removal

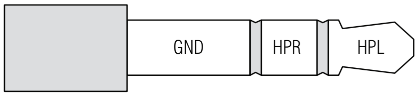
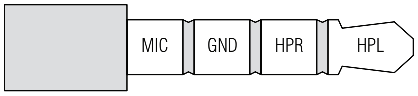
JACK TYPE	JDWK = 1 AND MICBIAS DISABLED	JDWK = 0 OR MICBIAS ENABLED
	JKSNS: 00 → 11	JKSNS: 00 → 11
	JKSNS: 00 → 11	JKSNS: 01 → 11

Table 35. Jack Detection Registers

REGISTER	BIT	NAME	DESCRIPTION		
0x02 (Read Only)	7	JKSNS	**JACKSNS State** Reports the status of JACKSNS when JDETEN = 1.		
			VALUE	**MODE**	**DESCRIPTION**
			00	MBEN = 1	$V_{JACKSNS}$ < 0.1V x $V_{MICBIAS}$
				MBEN = 0	$V_{JACKSNS}$ < 0.1V x $V_{SPKLVDD}$
			01	MBEN = 1	0.1V x $V_{MICBIAS}$ < $V_{JACKSNS}$ < 0.95V x $V_{MICBIAS}$
	6			MBEN = 0	0.1V x $V_{SPKLVDD}$ < $V_{JACKSNS}$ < 0.95V x $V_{SPKLVDD}$
			10	MBEN = 1	Reserved
				MBEN = 0	Reserved
			11	MBEN = 1	0.95V x $V_{MICBIAS}$ < $V_{JACKSNS}$
				MBEN = 0	0.95V x $V_{SPKLVDD}$ < $V_{JACKSNS}$
0x4B	7	JDETEN	**Jack Detection Enable** 0 = Disabled 1 = Enabled		
	1	JDEB	**Jack Detection Debounce** Configures the debounce time for setting JDET. 00 = 25ms 01 = 50ms 10 = 100ms 11 = 200ms		
	0				

Table 35. Jack Detection Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
0x4E	7	BGEN	See the *Power Management* section.
	6	SPREGEN	See the *Power Management* section.
	5	VCMEN	See the *Power Management* section.
	4	BIASEN	See the *Power Management* section.
	0	JDWK	**JACKSNS Pullup** When JDWK = 1, JACKSNS is slow to increase in voltage. Set JDWK = 0 before setting JDETEN = 1 to prevent false detection. Valid when MBIAS = 0. 0 = 2.4kΩ to SPKLVDD (allows microphone detection) 1 = 5µA to SPKLVDD (minimizes supply current)

Battery Measurement

The IC measures the voltage applied to SPKLVDD (typically the battery voltage) and reports the value in register 0x03. This value is also used by the speaker limiter circuitry to set accurate thresholds. When the battery measurement function is disabled, the battery voltage is user programmable.

Table 36. Battery Measurement Registers

REGISTER	BIT	NAME	DESCRIPTION
0x03	4	VBAT	**Battery Voltage** Read VBAT when VBATEN = 1 to determine $V_{SPKLVDD}$. Program VBAT when VBATEN = 0 to allow proper speaker amplifier signal processing. Calculate/program the battery voltage using the following formula: $V_{BATTERY}$ = 2.55V + [VBAT/10]
	3		
	2		
	1		
	0		
0x51	7	$\overline{\text{SHDN}}$	See the *Power Management* section.
	6	VBATEN	**Battery Measurement Enable.** Enables an internal ADC to measure $V_{SPKLVDD}$. 0 = Disabled (register 0x03 readable and writeable) 1 = Enabled (register 0x03 read only)
	3	PERFMODE	See the *Power Management* section.
	2	HPPLYBCK	See the *Power Management* section.
	1	PWRSV8K	See the *Power Management* section.
	0	PWRSV	See the *Power Management* section.

Device Status

The IC uses register 0x00 and $\overline{\text{IRQ}}$ to report the status of various device functions. The status register bits are set when their respective events occur, and cleared upon reading the register. Device status can be determined either by poling register 0x00 or configuring the $\overline{\text{IRQ}}$ to pull low when specific events occur. $\overline{\text{IRQ}}$ is an open-drain output that requires a pullup resistor for proper operation. Register 0x0F determines which bits in the status register trigger $\overline{\text{IRQ}}$ to pull low.

Table 37. Status and Interrupt Registers

REGISTER	BIT	NAME	DESCRIPTION
0x00 (Read Only)	7	CLD	**Full Scale** 0 = All digital signals are less than full scale. 1 = The DAC or ADC signal path has reached or exceeded full scale. This typically indicates clipping.
	6	SLD	**Volume Slew Complete** SLD reports that any of the programmable-gain arrays or volume controllers has completed slewing from a previous setting to a new programmed setting. If multiple gain arrays or volume controllers are changed at the same time, the SLD flag is set after the last volume slew completes. SLD also reports when the digital audio interface soft-start or soft-stop process has completed. MCLK is required for proper SLD operation. 0 = No volume slewing sequences have completed since the status register was last read. 1 = Volume slewing complete.
	5	ULK	**Digital Audio Interface Unlocked** 0 = Both digital audio interfaces are operating normally. 1 = Either digital audio interface is configured incorrectly or receiving invalid clocks.
	1	JDET	**Jack Configuration Change** JDET reports changes to any bit in the Jack Status register (0x02). Changes to the Jack Status bits are debounced before setting JDET. The debounce period is programmable using the JDEB bits. JDET is always set the first time JDETEN or $\overline{\text{SHDN}}$ is set the first time power is applied to the IC. Read the status register following such an event to clear JDET and allow for proper jack detection. 0 = No change in jack configuration. 1 = Jack configuration has changed.
0x0F	7	ICLD	**Full-Scale Interrupt Enable** 0 = Disabled 1 = Enabled
	6	ISLD	**Volume Slew Complete Interrupt Enable** 0 = Disabled 1 = Enabled
	5	IULK	**Digital Audio Interface Unlocked Interrupt Enable** 0 = Disabled 1 = Enabled
	1	IJDET	**Jack Configuration Change Interrupt Enable** 0 = Disabled 1 = Enabled

Device Revision

Table 38. Device Revision Register

REGISTER	BIT	NAME	DESCRIPTION
0xFF (Read Only)	7	REV	**Device Revision Code** REV is always set to 0x40.
	6		
	5		
	4		
	3		
	2		
	1		
	0		

I²C Serial Interface

The IC features an I²C/SMBus™-compatible, 2-wire serial interface comprising a serial-data line (SDA) and a serial-clock line (SCL). SDA and SCL facilitate communication between the IC and the master at clock rates up to 400kHz. Figure 5 shows the 2-wire interface timing diagram. The master generates SCL and initiates data transfer on the bus. The master device writes data to the IC by transmitting the proper slave address followed by the register address and then the data word. Each transmit sequence is framed by a START (S) or REPEATED START (Sr) condition and a STOP (P) condition. Each word transmitted to the IC is 8 bits long and is followed by an acknowledge clock pulse. A master reading data from the IC transmits the proper slave address followed by a series of nine SCL pulses. The IC transmits data on SDA in sync with the master-generated SCL pulses. The master acknowledges receipt of each byte of data. Each read sequence is framed by a START or REPEATED START condition, a not acknowledge, and a STOP condition. SDA operates as both an input and an open-drain output. A pullup resistor, typically greater than 500Ω, is required on SDA. SCL operates only as an input. A pullup resistor, typically greater than 500Ω, is required on SCL if there are multiple masters on the bus, or if the single master has an open-drain SCL output. Series resistors in line with SDA and SCL are optional. Series resistors protect the digital inputs of the IC from high voltage spikes on the bus lines, and minimize crosstalk and undershoot of the bus signals.

Bit Transfer

One data bit is transferred during each SCL cycle. The data on SDA must remain stable during the high period of the SCL pulse. Changes in SDA while SCL is high are control signals (see the *START and STOP Conditions* section).

START and STOP Conditions

SDA and SCL idle high when the bus is not in use. A master initiates communication by issuing a START condition. A START condition is a high-to-low transition on SDA with SCL high. A STOP condition is a low-to-high transition on SDA while SCL is high (Figure 33). A START condition from the master signals the beginning of a transmission to the IC. The master terminates transmission, and frees the bus, by issuing a STOP condition. The bus remains active if a REPEATED START condition is generated instead of a STOP condition.

Early STOP Conditions

The IC recognizes a STOP condition at any point during data transmission except if the STOP condition occurs in the same high pulse as a START condition. For proper operation, do not send a STOP condition during the same SCL high pulse as the START condition.

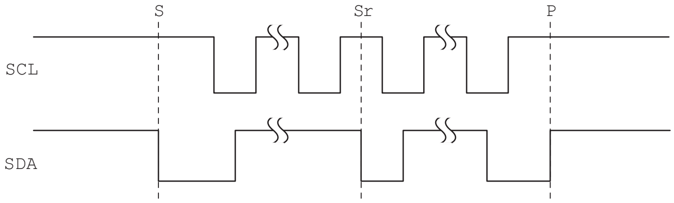


Figure 34. START, STOP, and REPEATED START Conditions

SMBus is a trademark of Intel Corp.

Slave Address

The slave address is defined as the seven most significant bits (MSBs) followed by the read/write bit. For the IC, the seven most significant bits are 0010000. Setting the read/write bit to 1 (slave address = 0x21) configures the IC for read mode. Setting the read/write bit to 0 (slave address = 0x20) configures the ICs for write mode. The address is the first byte of information sent to the IC after the START condition.

Acknowledge

The acknowledge bit (ACK) is a clocked 9th bit that the IC uses to handshake receipt each byte of data when in write mode (Figure 35). The IC pulls down SDA during the entire master-generated 9th clock pulse if the previous byte is successfully received. Monitoring ACK allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if a receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master retries communication. The master pulls down SDA during the 9th clock cycle to acknowledge receipt of data when the IC is in read mode. An acknowledge is sent by the master after each read byte to allow data transfer to continue. A not acknowledge is sent when the master reads the final byte of data from the IC, followed by a STOP condition.

Write Data Format

A write to the IC includes transmission of a START condition, the slave address with the R/$\overline{W}$ bit set to 0, one byte of data to configure the internal register address pointer, one or more bytes of data, and a STOP condition. Figure 36 illustrates the proper frame format for writing one byte of data to the IC. Figure 37 illustrates the frame format for writing n-bytes of data to the IC.

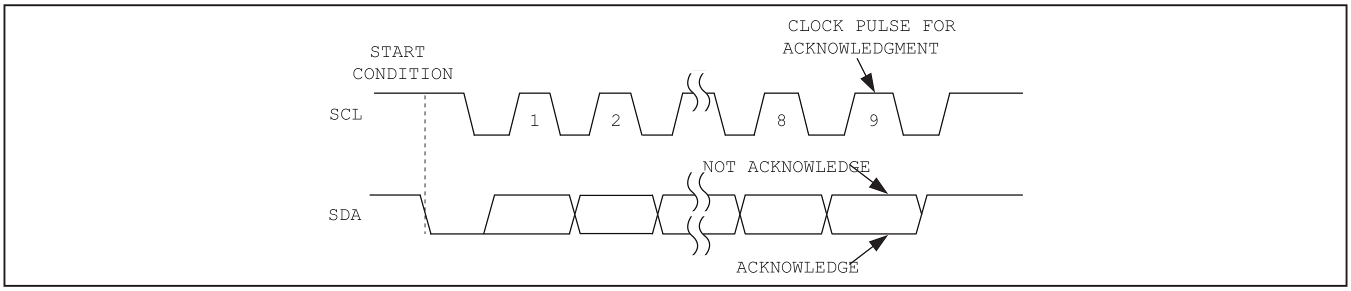


Figure 35. Acknowledge

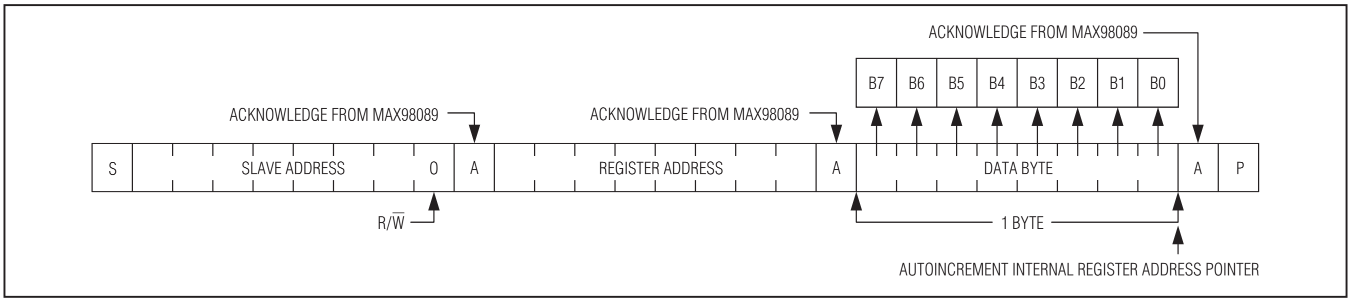


Figure 36. Writing One Byte of Data to the ICs

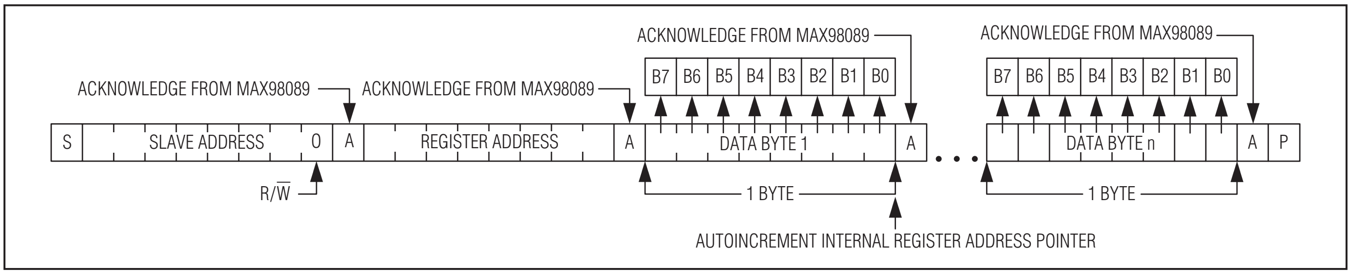


Figure 37. Writing n-Bytes of Data to the ICs

The slave address with the R/$\overline{W}$ bit set to 0 indicates that the master intends to write data to the ICs. The ICs acknowledge receipt of the address byte during the master-generated 9th SCL pulse.

The second byte transmitted from the master configures the IC's internal register address pointer. The pointer tells the IC where to write the next byte of data. An acknowledge pulse is sent by the ICs upon receipt of the address pointer data.

The third byte sent to the ICs contains the data that is written to the chosen register. An acknowledge pulse from the ICs signals receipt of the data byte. The address pointer autoincrements to the next register address after each received data byte. This autoincrement feature allows a master to write to sequential registers within one continuous frame. The master signals the end of transmission by issuing a STOP condition. Register addresses greater than 0xC7 are reserved. Do not write to these addresses.

Read Data Format

Send the slave address with the R/$\overline{W}$ bit set to 1 to initiate a read operation. The IC acknowledges receipt of its slave address by pulling SDA low during the 9th SCL clock pulse. A START command followed by a read command resets the address pointer to register 0x00.

The first byte transmitted from the ICs is the content of register 0x00. Transmitted data is valid on the rising edge of SCL. The address pointer autoincrements after each read data byte. This autoincrement feature allows all registers to be read sequentially within one continuous frame. A STOP condition can be issued after any number of read data bytes. If a STOP condition is issued followed by another read operation, the first data byte to be read is from register 0x00.

The address pointer can be preset to a specific register before a read command is issued. The master presets the address pointer by first sending the IC's slave address with the R/$\overline{W}$ bit set to 0 followed by the register address. A REPEATED START condition is then sent followed by the slave address with the R/$\overline{W}$ bit set to 1. The IC then transmits the contents of the specified register. The address pointer autoincrements after transmitting the first byte.

The master acknowledges receipt of each read byte during the acknowledge clock pulse. The master must acknowledge all correctly received bytes except the last byte. The final byte must be followed by a not acknowledge from the master and then a STOP condition. Figure 38 illustrates the frame format for reading one byte from the IC. Figure 39 illustrates the frame format for reading multiple bytes from the ICs.

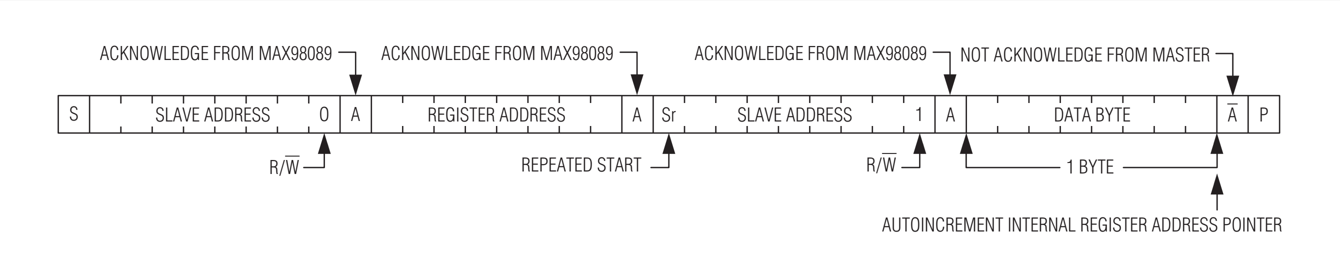


Figure 38. Reading One Byte of Data from the ICs

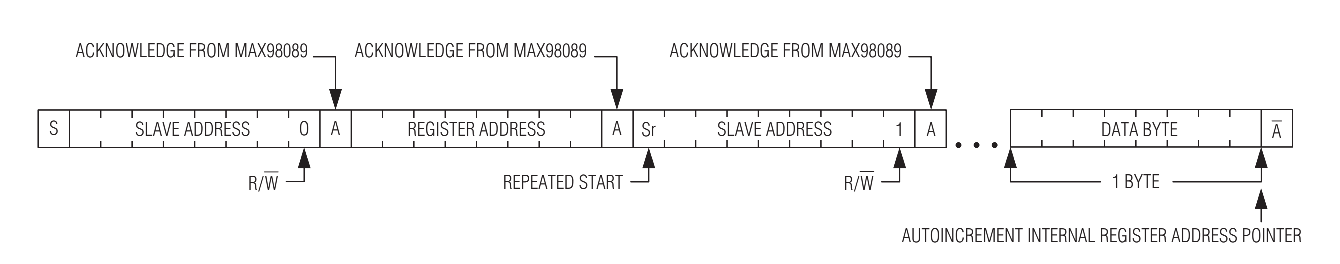


Figure 39. Reading n Bytes of Data from the ICs

Applications Information

Typical Operating Circuits

Figures 40 and 41 provide example operating circuits for the ICs. The external components shown are the minimum required for the ICs to operate. Additional components may be required by the application.

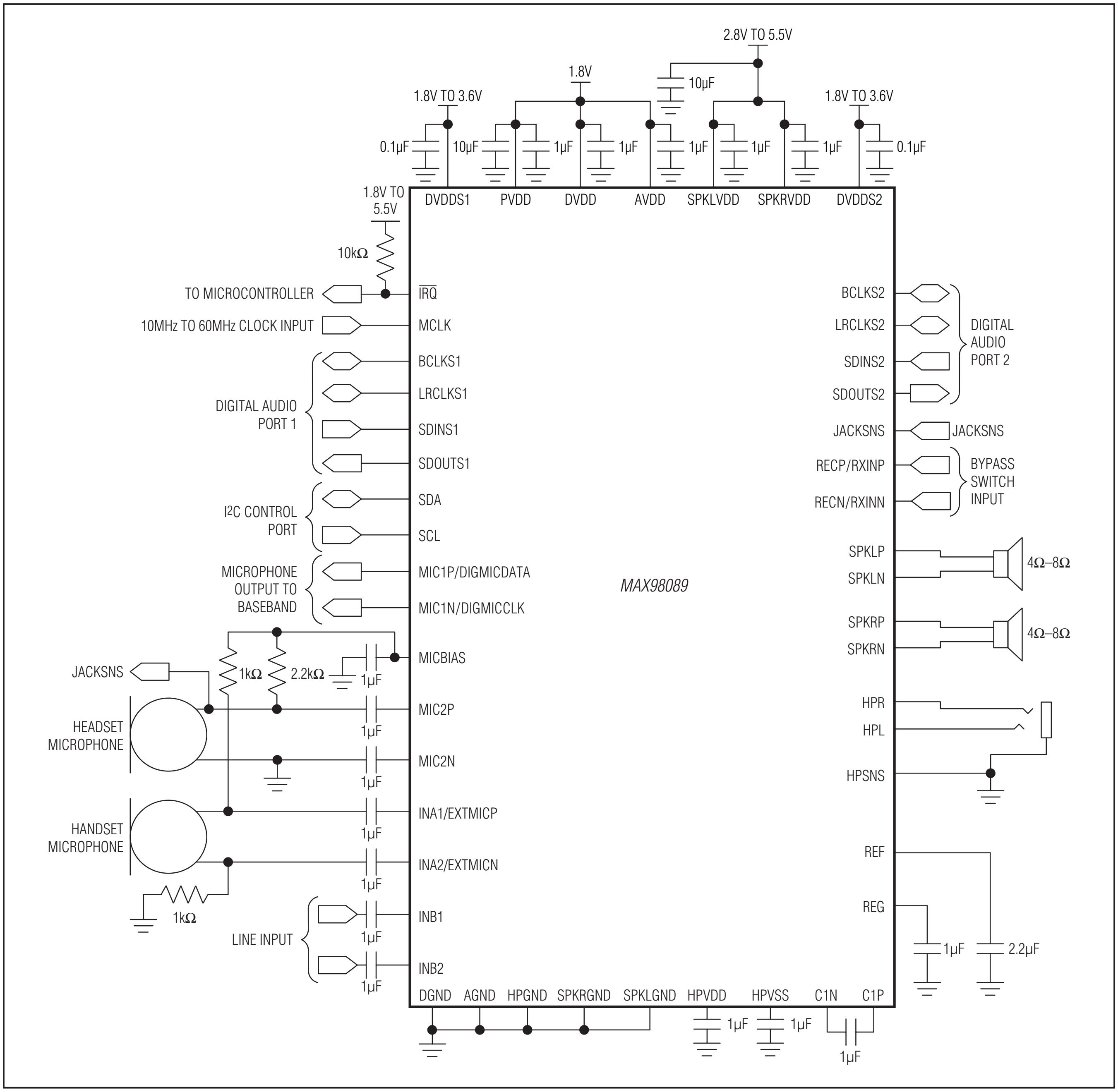


Figure 40. Typical Application Circuit Using Analog Microphone Inputs and the Bypass Switch

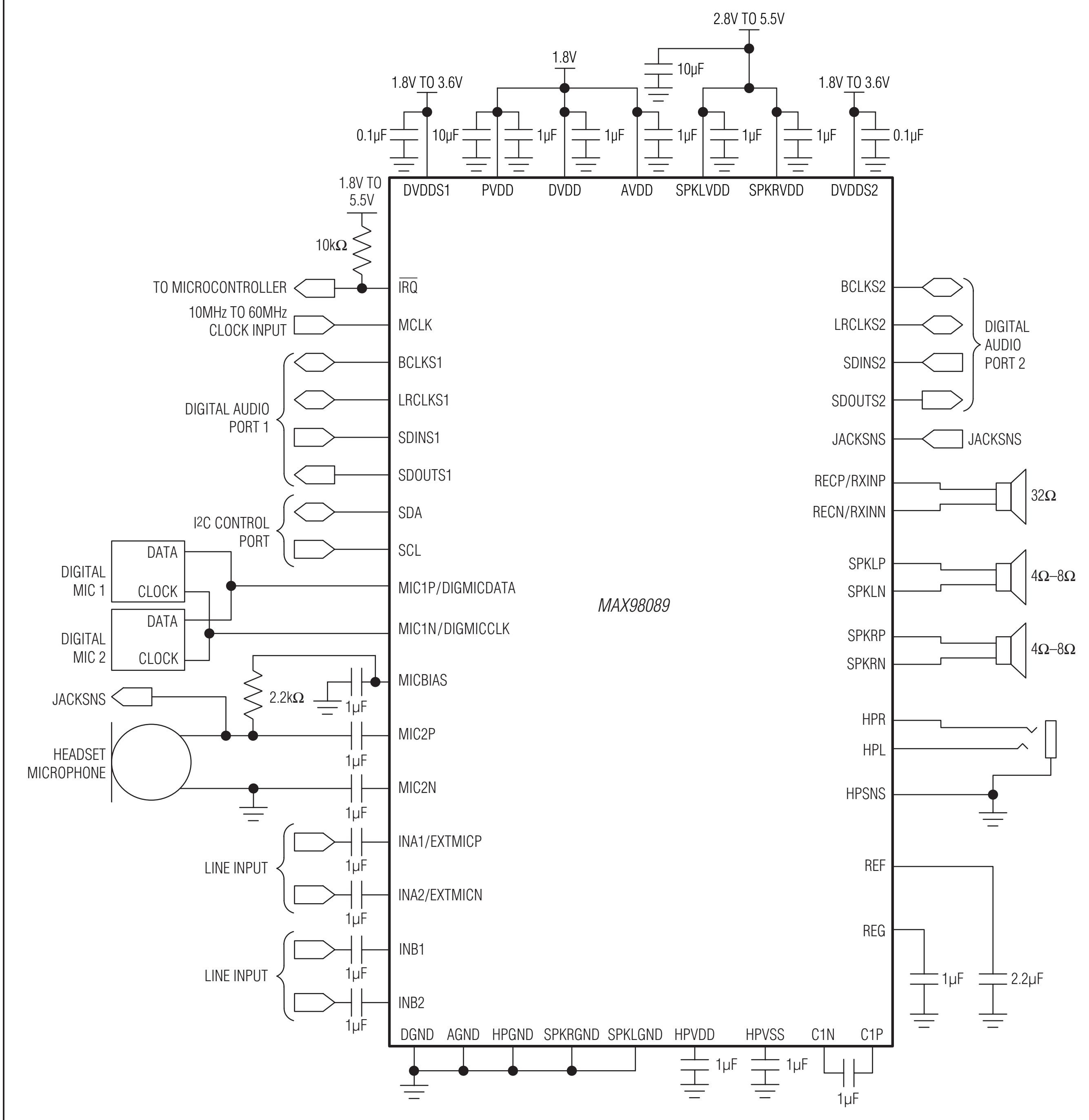


Figure 41. Typical Application Circuit Using the Digital Microphone Input and Receiver Amplifier

Filterless Class D Operation

Traditional Class D amplifiers require an output filter to recover the audio signal from the amplifier's output. The filters add cost, increase the solution size of the amplifier, and can decrease efficiency and THD+N performance. The traditional PWM scheme uses large differential output swings (2 x V_{DD} peak to peak) and causes large ripple currents. Any parasitic resistance in the filter components results in a loss of power, lowering the efficiency.

The IC does not require an output filter. The device relies on the inherent inductance of the speaker coil and the natural filtering of both the speaker and the human ear to recover the audio component of the square-wave output. Eliminating the output filter results in a smaller, less costly, more efficient solution.

Because the frequency of the IC's output is well beyond the bandwidth of most speakers, voice coil movement due to the square-wave frequency is very small. Although this movement is small, a speaker not designed to handle the additional power can be damaged. For optimum results, use a speaker with a series inductance > 10µH. Typical 8Ω speakers exhibit series inductances in the 20µH to 100µH range.

RF Susceptibility

GSM radios transmit using time-division multiple access (TDMA) with 217Hz intervals. The result is an RF signal with strong amplitude modulation at 217Hz and its harmonics that is easily demodulated by audio amplifiers. The IC is designed specifically to reject RF signals; however, PCB layout has a large impact on the susceptibility of the end product.

In RF applications, improvements to both layout and component selection decrease the IC's susceptibility to RF noise and prevent RF signals from being demodulated into audible noise. Trace lengths should be kept below 1/4 of the wavelength of the RF frequency of interest. Minimizing the trace lengths prevents them from functioning as antennas and coupling RF signals into the IC. The wavelength (ʎ) in meters is given by: $ʎ = c/f$ where $c = 3 \times 10^8$ m/s, and f = the RF frequency of interest.

Route audio signals on middle layers of the PCB to allow ground planes above and below to shield them from RF interference. Ideally, the top and bottom layers of the PCB should primarily be ground planes to create effective shielding.

Additional RF immunity can also be obtained by relying on the self-resonant frequency of capacitors as it exhibits a frequency response similar to a notch filter. Depending on the manufacturer, 10pF to 20pF capacitors typically exhibit self resonance at the RF frequencies of interest. These capacitors, when placed at the input pins, can effectively shunt the RF noise to ground. For these capacitors to be effective, they must have a low-impedance, low-inductance path to the ground plane. Avoid using microvias to connect to the ground plane whenever possible as these vias do not conduct well at RF frequencies.

Startup/Shutdown Sequencing

To ensure proper device initialization and minimal click-and-pop, program the IC's $\overline{\text{SHDN}}$ = 1 after configuring all registers. Table 39 lists an example startup sequence for the device. To shut down the IC, simply set $\overline{\text{SHDN}}$ = 0.

Table 39. Example Startup Sequence

SEQUENCE	DESCRIPTION	REGISTERS
1	Ensure $\overline{\text{SHDN}}$ = 0	0x51
2	Configure clocks	0x10 to 0x13, 0x19 to 0x1B
3	Configure digital audio interface	0x14 to 0x17, 0x1C to 0x1F
4	Configure digital signal processing	0x18, 0x20, 0x3F to 0x46
5	Load coefficients	0x52 to 0xC9
6	Configure mixers	0x22 to 0x2D
7	Configure gain and volume controls	0x2E to 0x3E
8	Configure miscellaneous functions	0x47 to 0x4B
9	Enable desired functions	0x4C, 0x50
10	Set $\overline{\text{SHDN}}$ = 1	0x51

Many configuration options in the ICs can be made while the devices are operating, however, some registers should only be adjusted when the corresponding audio path is disabled. Table 40 lists the registers that are sensitive during operation. Either disable the corresponding audio path or set $\overline{\text{SHDN}}$ = 0 while changing these registers.

Component Selection

Optional Ferrite Bead Filter

In applications where speaker leads exceed 20mm, additional EMI suppression can be achieved by using a filter constructed from a ferrite bead and a capacitor to ground (Figure 42). Use a ferrite bead with low DC resistance, high-frequency (> 600MHz) impedance between 100Ω and 600Ω, and rated for at least 1A. The capacitor value varies based on the ferrite bead chosen and the actual speaker lead length. Select a capacitor less than 1nF based on EMI performance.

Input Capacitor

An input capacitor, C_{IN}, in conjunction with the input impedance of the IC line inputs forms a highpass filter that removes the DC bias from an incoming analog signal. The AC coupling capacitor allows the amplifier to automatically bias the signal to an optimum DC level. Assuming zero-source impedance, the -3dB point of the highpass filter is given by:

$$f_{-3dB} = \frac{1}{2\pi R_{IN} C_{IN}}$$

Choose C_{IN} so that f_{-3dB} is well below the lowest frequency of interest. For best audio quality use capacitors whose dielectrics have low-voltage coefficients, such as tantalum or aluminum electrolytic. Capacitors with high-voltage coefficients, such as ceramics, may result in increased distortion at low frequencies.

Charge-Pump Capacitor Selection

Use capacitors with an ESR less than 100mΩ for optimum performance. Low-ESR ceramic capacitors minimize the output resistance of the charge pump. Most surface-mount ceramic capacitors satisfy the ESR requirement. For best performance over the extended temperature range, select capacitors with an X7R dielectric.

Table 40. Registers That Are Sensitive to Changes During Operation

REGISTER	DESCRIPTION
0x10 to 0x13, 0x19 to 0x1B	Clock Control Registers
0x14 to 0x17, 0x1C to 0x1F	Digital Audio Interface Configuration
0x18, 0x20	Digital Passband Filters
0x25 to 0x2D	Analog Mixers
0x52 to 0xC9	Digital Signal Processing Coefficients

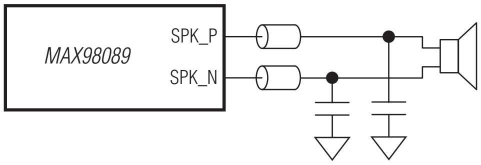


Figure 42. Optional Class D Ferrite Bead Filter

Charge-Pump Flying Capacitor

The value of the flying capacitor (connected between C1N and C1P) affects the output resistance of the charge pump. A value that is too small degrades the device's ability to provide sufficient current drive, which leads to a loss of output voltage. Increasing the value of the flying capacitor reduces the charge-pump output resistance to an extent. Above 1µF, the on-resistance of the internal switches and the ESR of external charge- pump capacitors dominate.

Charge-Pump Holding Capacitors

The holding capacitors (bypassing HPVSS to HPGND and HPVDD to HPGND) value and ESR directly affect the ripple at HPVSS and HPVDD. Increasing the capacitor's value reduces output ripple. Likewise, decreasing the ESR reduces both ripple and output resistance. Lower capacitance values can be used in systems with low maximum output power levels.

Unused Pins

Table 41 shows how to connect the IC's pins when circuit blocks are unused.

Table 41. Unused Pins

NAME	CONNECTION	NAME	CONNECTION
SPKRP	Unconnected	INB1	Unconnected
SPKRVDD	Always connect	INA2/MICEXTN	Unconnected
SPKLVDD	Always connect	LRCLKS2	Unconnected
SPKLP	Unconnected	MCLK	Always connect
RECN/RXINN	Unconnected	SDINS2	AGND
HPVDD	Unconnected	$\overline{\text{IRQ}}$	Unconnected
C1P	Unconnected	MIC1P/DIGMICDATA	Unconnected
HPGND	AGND	INA1/MICEXTP	Unconnected
SPKRN	Unconnected	DGND	Always connect
SPKRGND	Always connect	BCLKS2	Unconnected
SPKLGND	Always connect	SDA	Always connect
SPKLN	Unconnected	SCL	Always connect
RECP/RXINP	Unconnected	REG	Always connect
C1N	Unconnected	REF	Always connect
HPL	Unconnected	MIC1N/DIGMICCLK	Unconnected
HPVSS	Unconnected	MIC2P	Unconnected
SDINS1	AGND	SDOUTS2	Unconnected
LRCLKS1	Unconnected	DVDDS2	DVDD
HPSNS	AGND	DVDD	Always connect
INB2	Unconnected	AVDD	Always connect
HPR	Unconnected	PVDD	Always connect
DVDDS1	DVDD	AGND	Always connect
SDOUTS1	Unconnected	MICBIAS	Unconnected
BCLKS1	Unconnected	MIC2N	Unconnected
JACKSNS	Unconnected		

Recommended PCB Routing

The MAX98089EWY uses a 63-bump WLP package. Figure 43 provides an example of how to connect to all active bumps using 3 layers of the PCB. To ensure uninterrupted ground returns, use layer 2 as a connecting layer between layer 1 and layer 3 and flood the remaining area with ground.

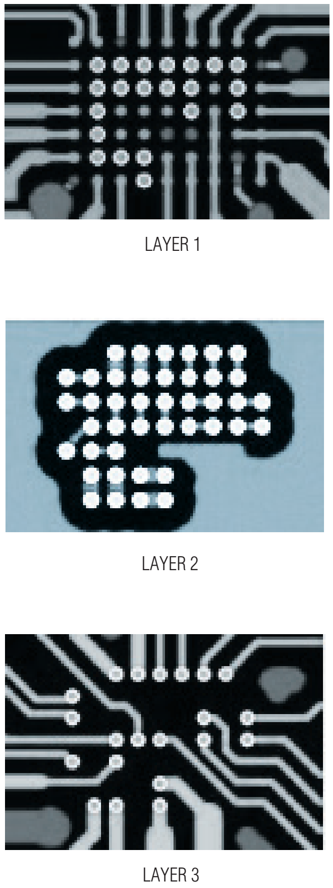


Figure 43. Suggested Routing for the MAX98089EWY

Supply Bypassing, Layout, and Grounding

Proper layout and grounding are essential for optimum performance. When designing a PCB for the ICs, partition the circuitry so that the analog sections of the IC are separated from the digital sections. This ensures that the analog audio traces are not routed near digital traces.

Use a large continuous ground plane on a dedicated layer of the PCB to minimize loop areas. Connect AGND, DGND, HPGND, SPKLGND, and SPKRGND directly to the ground plane using the shortest trace length possible. Proper grounding improves audio performance, minimizes crosstalk between channels, and prevents any digital noise from coupling into the analog audio signals.

Ground the bypass capacitors on MICBIAS, REG, and REF directly to the ground plane with minimum trace length. Also be sure to minimize the path length to AGND. Bypass AVDD directly to AGND.

Connect all digital I/O termination to the ground plane with minimum path length to DGND. Bypass DVDD, DVDDS1, and DVDDS2 directly to DGND.

Place the capacitor between C1P and C1N as close as possible to the ICs to minimize trace length from C1P to C1N. Inductance and resistance added between C1P and C1N reduce the output power of the headphone amplifier. Bypass HPVDD and HPVSS with a capacitor located close to HPVSS with a short trace length to HPGND. Close decoupling of HPVSS minimizes supply ripple and maximizes output power from the headphone amplifier.

HPSNS senses ground noise on the headphone jack and adds the same noise to the output audio signal, thereby making the output (headphone output minus ground) noise free. Connect HPSNS to the headphone jack shield to ensure accurate pickup of headphone ground noise.

Bypass SPKLVDD and SPKRVDD to SPKLGND and SPKRGND, respectively, with as little trace length as possible. Connect SPKLP, SPKLN, SPKRP, and SPKRN to the stereo speakers using the shortest traces possible. Reducing trace length minimizes radiated EMI. Route SPKLP/SPKLN and SPKRP/SPKRN as differential pairs on the PCB to minimize loop area, thereby the inductance of the circuit. If filter components are used on the speaker outputs, be sure to locate them as close as possible to the IC to ensure maximum effectiveness. Minimize the trace length from any ground-connected passive components to SPKLGND and SPKRGND to further minimize radiated EMI.

Route microphone signals from the microphone to the ICs as a differential pair, ensuring that the positive and negative signals follow the same path as closely as possible with equal trace length. When using single-ended microphones or other single-ended audio sources, ground the negative microphone input as close as possible to the audio source and then treat the positive and negative traces as differential pairs.

An evaluation kit (EV kit) is available to provide an example layout for the IC. The EV kit allows quick setup of the IC and includes easy-to-use software allowing all internal registers to be controlled.

WLP Applications Information

For the latest application details on WLP construction, dimensions, tape carrier information, PCB techniques, bump-pad layout, and recommended reflow temperature profile, as well as the latest information on reliability testing results, refer to the Application Note 1891: *Wafer-Level Packaging (WLP) and Its Applications*. Figure 44 shows the dimensions of the WLP balls used on the MAX98089EWY.

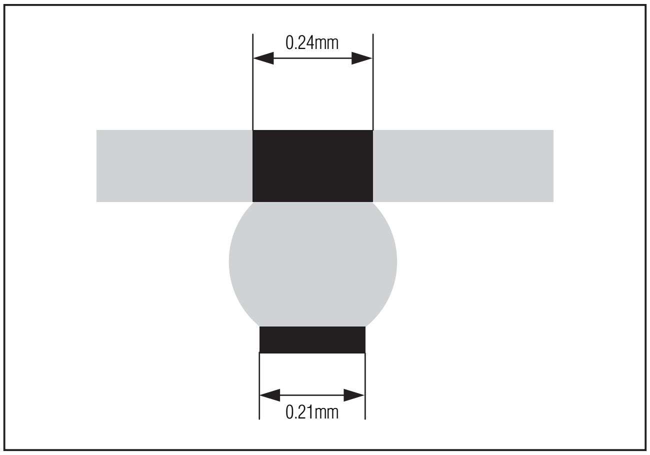


Figure 44. MAX98089EWY WLP Ball Dimensions

Ordering Information

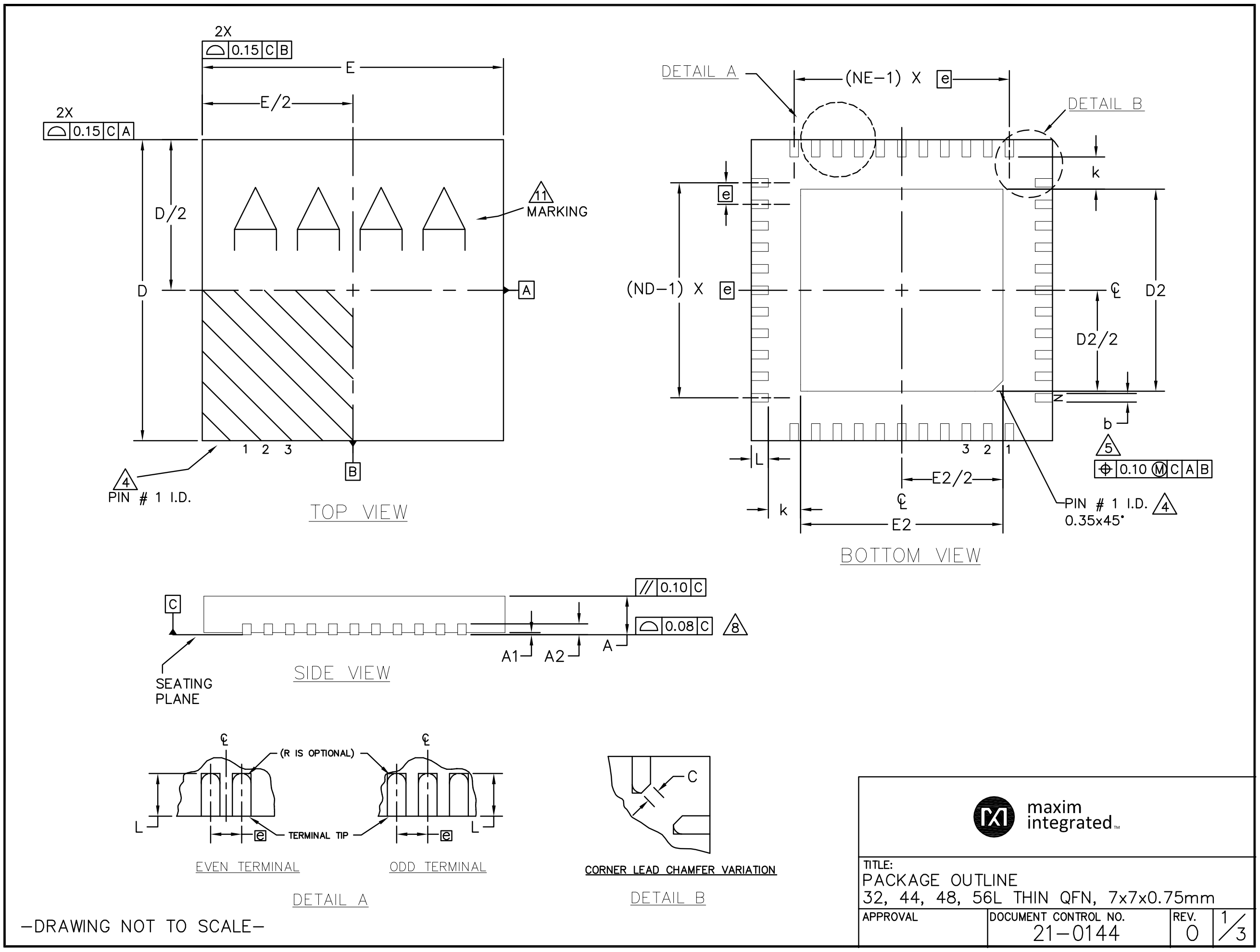
PART	TEMP RANGE	PIN-PACKAGE
MAX98089EWY+T	-40°C to +85°C	63 WLP
MAX98089ETN+T	-40°C to +85°C	56 TQFN-EP*

T = Tape and reel.
+Denotes lead(Pb)-free/RoHS-compliant package.
**EP = Exposed pad.*

Package Information

For the latest package outline information and land patterns (footprints), go to www.analog.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
56 TQFN	T5677+1	21-0144	90-0042
63 WLP	W633A3+1	21-0462	—



Package Information (continued)

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COMMON DIMENSIONS

PKG	32L 7x7			44L 7x7			48L 7x7			CUSTOM PKG. (T4877−1) 48L 7x7			56L 7x7		
SYMBOL	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80
A1	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05	0	–	0.05
A2	0.20 REF.			0.20 REF.			0.20 REF.			0.20 REF.			0.20 REF.		
b	0.25	0.30	0.35	0.20	0.25	0.30	0.20	0.25	0.30	0.20	0.25	0.30	0.15	0.20	0.25
D	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10
E	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10
e	0.65 BSC.			0.50 BSC.			0.50 BSC.			0.50 BSC.			0.40 BSC.		
k	0.25	–	–	0.25	–	–	0.25	–	–	0.25	–	–	0.25	–	–
L	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.45	0.55	0.65	0.30	0.40	0.50
N	32			44			48			44			56		
ND	8			11			12			10			14		
NE	8			11			12			12			14		

CORNER LEAD CHAMFER VARIATION

PKG. CODES	C
T4877−3	0.115 X 45°
T4877−4	0.115 X 45°
T4877−4C	0.115 X 45°
T4877−6	0.115 X 45°
T4877−7	0.115 X 45°
T4877−10	0.115 X 45°
T4877M−1	0.115 X 45°
T4877M−6	0.115 X 45°

EXPOSED PAD VARIATIONS

PKG. CODES	DEPOPULATED LEADS	D2			E2			JEDEC MO220 REV. C
		MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
T3277−2	–	4.55	4.70	4.85	4.55	4.70	4.85	–
T3277−3	–	4.55	4.70	4.85	4.55	4.70	4.85	–
T4477−2	–	4.55	4.70	4.85	4.55	4.70	4.85	WKKD−1
T4477−2C	–	4.55	4.70	4.85	4.55	4.70	4.85	WKKD−1
T4477−3	–	4.55	4.70	4.85	4.55	4.70	4.85	WKKD−1
T4877−3	–	4.95	5.10	5.25	4.95	5.10	5.25	–
T4877−4	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877−4C	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877−6	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877−7	–	4.95	5.10	5.25	4.95	5.10	5.25	–
T4877−10	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877M−1	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877M−6	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877MN−8	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877N−8	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T4877−9C	–	3.92	4.02	4.12	3.92	4.02	4.12	–
T5677−1	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T5677MN−1	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T5677−2	–	5.40	5.50	5.60	5.40	5.50	5.60	–
T5677−3	–	5.40	5.50	5.60	5.40	5.50	5.60	–

maxim
integrated™

TITLE:
PACKAGE OUTLINE
32, 44, 48, 56L THIN QFN, 7x7x0.75mm

APPROVAL

DOCUMENT CONTROL NO.
21−0144

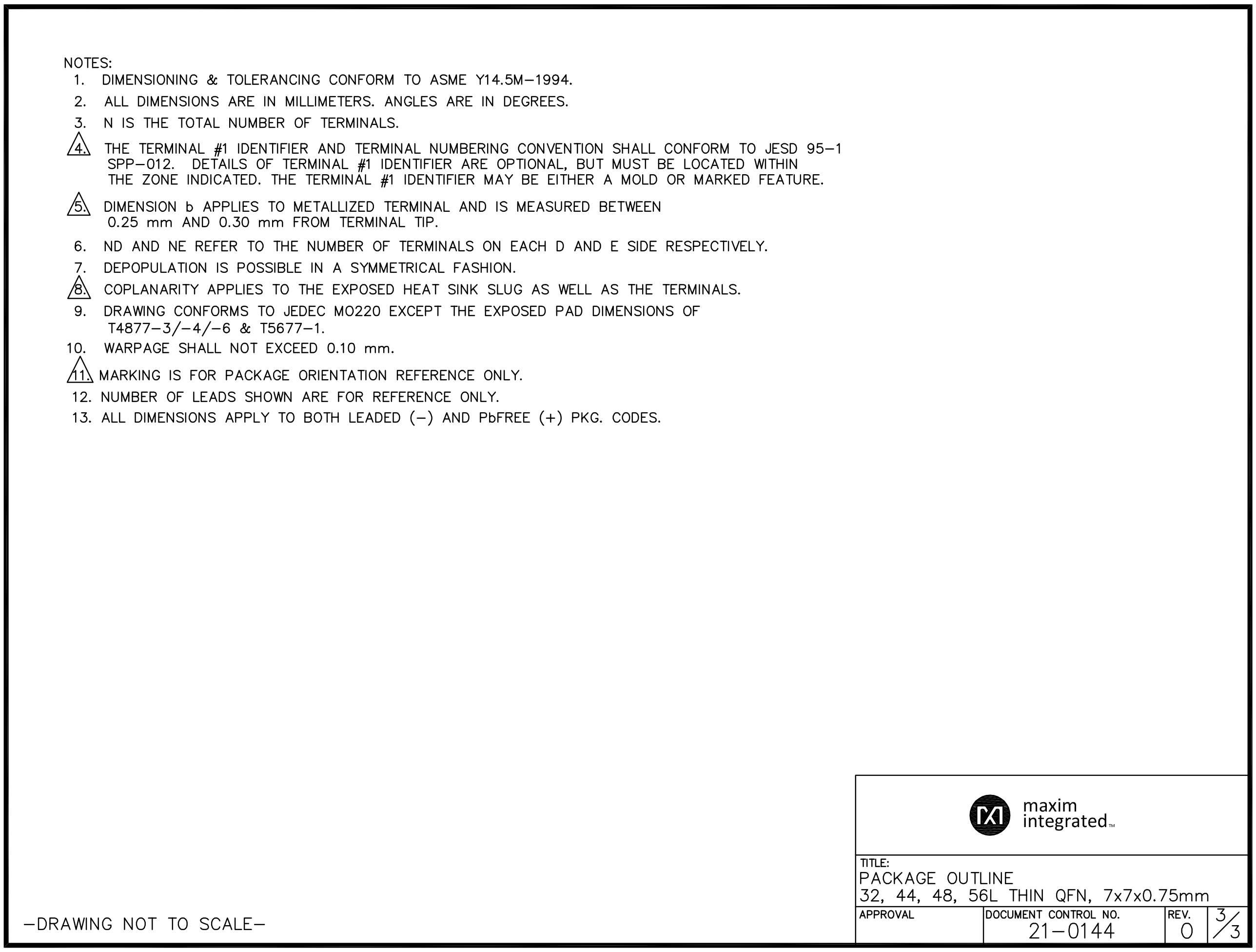
REV.
0

2/3

−DRAWING NOT TO SCALE−

Package Information (continued)

For the latest package outline information and land patterns (footprints), go to www.analog.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.



NOTES:

1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M−1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
3. N IS THE TOTAL NUMBER OF TERMINALS.

△4 THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95−1 SPP−012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.

△5 DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.

6. ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
7. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.

△8 COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.

9. DRAWING CONFORMS TO JEDEC MO220 EXCEPT THE EXPOSED PAD DIMENSIONS OF T4877−3/−4/−6 & T5677−1.
10. WARPAGE SHALL NOT EXCEED 0.10 mm.

△11 MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.

12. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
13. ALL DIMENSIONS APPLY TO BOTH LEADED (−) AND PbFREE (+) PKG. CODES.

−DRAWING NOT TO SCALE−

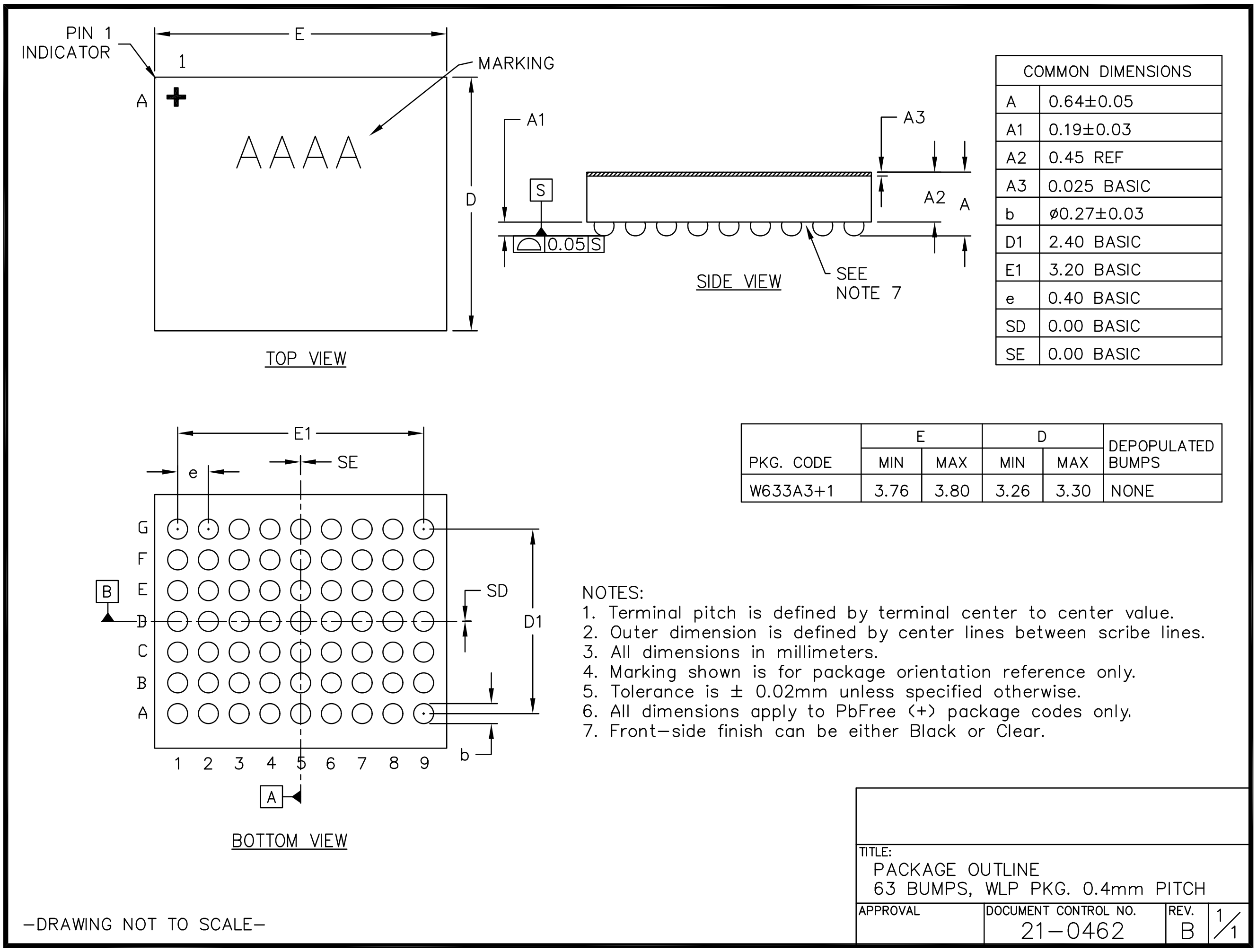
maxim
integrated™

TITLE:
PACKAGE OUTLINE
32, 44, 48, 56L THIN QFN, 7x7x0.75mm

APPROVAL
DOCUMENT CONTROL NO. 21−0144
REV. 0
3/3

Package Information (continued)

For the latest package outline information and land patterns (footprints), go to www.analog.com/packages. Note that a “+”, “#”, or “-” in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.



COMMON DIMENSIONS	
A	0.64±0.05
A1	0.19±0.03
A2	0.45 REF
A3	0.025 BASIC
b	ø0.27±0.03
D1	2.40 BASIC
E1	3.20 BASIC
e	0.40 BASIC
SD	0.00 BASIC
SE	0.00 BASIC

PKG. CODE	E		D		DEPOPULATED BUMPS
	MIN	MAX	MIN	MAX	
W633A3+1	3.76	3.80	3.26	3.30	NONE

NOTES:
1. Terminal pitch is defined by terminal center to center value.
2. Outer dimension is defined by center lines between scribe lines.
3. All dimensions in millimeters.
4. Marking shown is for package orientation reference only.
5. Tolerance is ± 0.02mm unless specified otherwise.
6. All dimensions apply to PbFree (+) package codes only.
7. Front-side finish can be either Black or Clear.

TITLE:
PACKAGE OUTLINE
63 BUMPS, WLP PKG. 0.4mm PITCH

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0462	B	1/1

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	6/11	Initial release	—
1	3/12	Added output offset voltage row to the DAC to Receiver Amplifier Path section in the *Electrical Characteristics* table, updated the sidetone functions	13, 14, 77, 78, 114
2	11/18	Updated *Parametric Equalizer* section, added new Table 17, and renumbered subsequent tables	94–97, 99, 100, 102, 103, 105–108, 111–119, 124–126
3	10/23	Updated *Charge Pump* section	108
4	6/24	Updated Table 1 and Table 10	61, 81
5	5/25	Updated *Speaker Amplifiers* section	101

ANALOG DEVICES